

Atmel Corporation

CMOS Flash Memory



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Thank you for your interest in Atmel's expanding family of nonvolatile Flash memory integrated circuits.

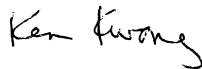
Atmel is the leading supplier of 5-volt-only and 3-volt-only read and write Flash PEROMs. The Flash memory family is specified over commercial as well as military temperature ranges and is available in through-hole and surface mount packages (such as PLCC and TSOP).

Atmel Corporation, founded in 1984, designs, develops, manufactures and markets, on a worldwide basis, a wide variety of complex integrated circuits based on proprietary process techniques. Included in the Company's product offerings are several families of nonvolatile programmable memories, programmable logic devices and application specific standard products.

Atmel will continue to expand this product family, offering new densities and lower voltage products.

If you require additional literature, please contact the literature department at (800) 292-8635. For further assistance, please contact your local sales representative listed on the back of this booklet.

Sincerely,



Ken Kwong
Director, Flash Memories



AMEL



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Features

- Fast Read Access Time - 90 ns
- Five-Volt-Only Reprogramming
- Page Program Operation
 - Single Cycle Reprogram (Erase and Program)
 - Internal Address and Data Latches for 64 Bytes
- Internal Program Control and Timer
- Hardware and Software Data Protection
- Fast Program Cycle Times
 - Page (64 Byte) Program Time - 10 ms
 - Chip Erase Time - 10 ms
- DATA Polling for End of Program Detection
- Low Power Dissipation
 - 80 mA Active Current
 - 300 μ A CMOS Standby Current
- High Reliability CMOS Technology
 - 1000 Erase/Program Cycles
 - 10-Year Data Retention
- Single 5 V \pm 10% Supply
- CMOS and TTL Compatible Inputs and Outputs
- Full Military, Commercial, and Industrial Temperature Ranges

**256K (32K x 8)
5-Volt Only
CMOS Flash
PEROM**

Description

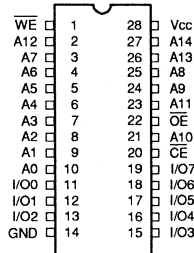
The AT29C256 is a five-volt-only in-system Flash Programmable and Erasable Read Only Memory (PEROM). Its 256K of memory is organized as 32,768 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 90 ns with power dissipation of just 440 mW. When the device is deselected, the CMOS standby current is less than 300 μ A.

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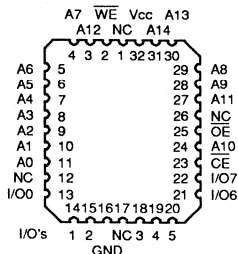
Pin Configurations

Pin Name	Function
A0 - A14	Addresses
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

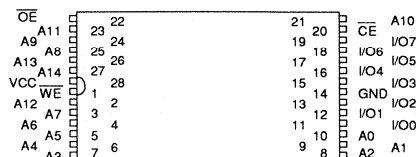
DIP Top View



PLCC and LCC Top View



TSOP Top View
Type 1



Note: PLCC package pins 1 and 17 are DON'T CONNECT.

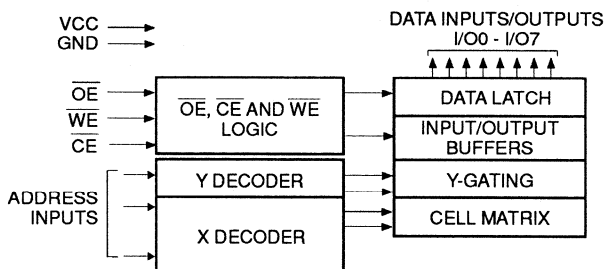


Description (Continued)

To allow for simple in-system reprogrammability, the AT29C256 does not require high input voltages for programming. Five-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from a static RAM. Reprogramming the AT29C256 is performed on a page basis; 64 bytes of data are loaded into the device and then simultaneously programmed. The contents of the entire device may be erased by using a six-byte software code (although erasure before programming is not needed).

During a reprogram cycle, the address locations and 64 bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the page and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected a new access for a read, program or chip erase can begin.

Block Diagram



Device Operation

READ: The AT29C256 is accessed like a static RAM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

BYTE LOAD: A byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$. Byte loads are used to enter the 64 bytes of a page to be programmed or the software codes for data protection and chip erasure.

PROGRAM: The device is reprogrammed on a page basis. If a byte of data within a page is to be changed, data for the entire page must be loaded into the device. Any byte that is not loaded during the programming of its page will be erased to read FFh. Once the bytes of a page are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) of the preceding byte. If a high to low transition is not detected within 150 μs of the last low to high transition, the load period will end and the internal programming period will start. A6 to A14 specify the page address. The page address must be valid during each high to low transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$). A0 to

A5 specify the byte address within the page. The bytes may be loaded in any order; sequential loading is not required.

SOFTWARE DATA PROTECTION: A software controlled data protection feature is available on the AT29C256. Once the software protection is enabled a software algorithm must be issued to the device before a program may be performed. The software protection feature may be enabled or disabled by the user; when shipped from Atmel, the software data protection feature is disabled. To enable the software data protection, a series of three program commands to specific addresses with specific data must be performed. After the software data protection is enabled the same three program commands must begin each program cycle in order for the programs to occur. All software program commands must obey the page program timing specifications. Once set, the software data protection feature remains active unless its disable command is issued. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

Once set, software data protection will remain active unless the disable command sequence is issued.

After setting SDP, any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc}, a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high.

continued on next page

Device Operation (Continued)

The address is latched on the falling edge of \overline{CE} or \overline{WE} , whichever occurs last. The data is latched by the first rising edge of \overline{CE} or \overline{WE} . The 64 bytes of data must be loaded into each sector by the same procedure as outlined in the program section under device operation.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29C256 in the following ways: (a) V_{CC} sense— if V_{CC} is below 3.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 5 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer and may be accessed by a hardware operation. For details, see Operating Modes or Product Identification.

\overline{DATA} POLLING: The AT29C256 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29C256 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground.....	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground.....	-0.6 V to $V_{CC} + 0.6$ V
Voltage on \overline{OE} with Respect to Ground.....	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. This parameter is characterized and is not 100% tested.



D.C. and A.C. Operating Range

		AT29C256-90	AT29C256-12	AT29C256-15	AT29C256-20	AT29C256-25
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
	Ind.		-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
	Mil.		-55°C - 125°C	-55°C - 125°C	-55°C - 125°C	-55°C - 125°C
Vcc Power Supply		5 V ± 10%	5 V ± 10%	5 V ± 10%	5 V ± 10%	5 V ± 10%

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	D _{OUT}
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	D _{IN}
5V Chip Erase	V _{IL}	V _{IH}	V _{IL}	Ai	
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Write Inhibit	X	X	V _{IH}		
Write Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
High Voltage Chip Erase	V _{IL}	V _H ⁽³⁾	V _{IL}	X	High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A14 = V _{IL} , A9 = V _H , A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A14 = V _{IL} , A9 = V _H , A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

- Notes: 1. X can be V_{IL} or V_{IH}.
 2. Refer to A.C. Programming Waveforms.
 3. V_H = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: DC
 5. See details under Software Product Identification Entry/Exit.

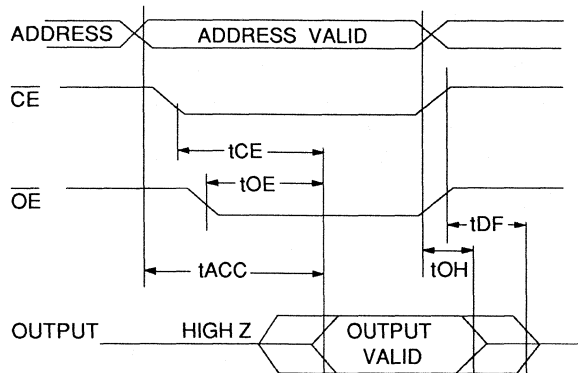
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		10	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		10	μA
I _{SB1}	V _{CC} Standby Current CMOS	\overline{CE} = V _{CC} -0.3 V to V _{CC}		300	μA
I _{SB2}	V _{CC} Standby Current TTL	\overline{CE} = 2.0 V to V _{CC}		3	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA		80	mA
V _{IL}	Input Low Voltage			0.8	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		.45	V
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	I _{OH} = -100 μA; V _{CC} = 4.5 V	4.2		V

A.C. Read Characteristics

Symbol	Parameter	AT29C256-90		AT29C256-12		AT29C256-15		AT29C256-20		AT29C256-25		Units
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{ACC}	Address to Output Delay	90		120		150		200		250		ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay	90		120		150		200		250		ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	40	0	50	0	70	0	80	0	100	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	25	0	30	0	40	0	50	0	60	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		0		0		0		ns

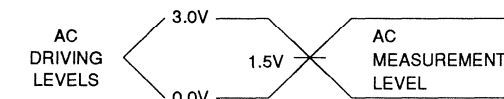
A.C. Read Waveforms



Notes:

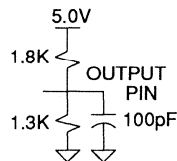
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5\text{pF}$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5 \text{ ns}$

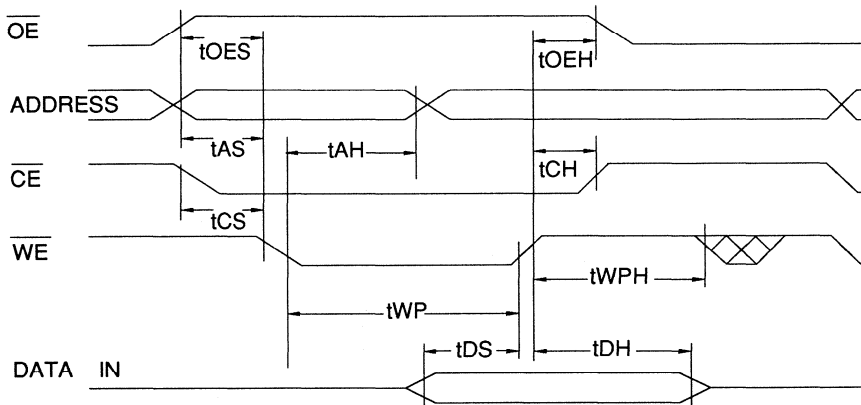
Output Test Load



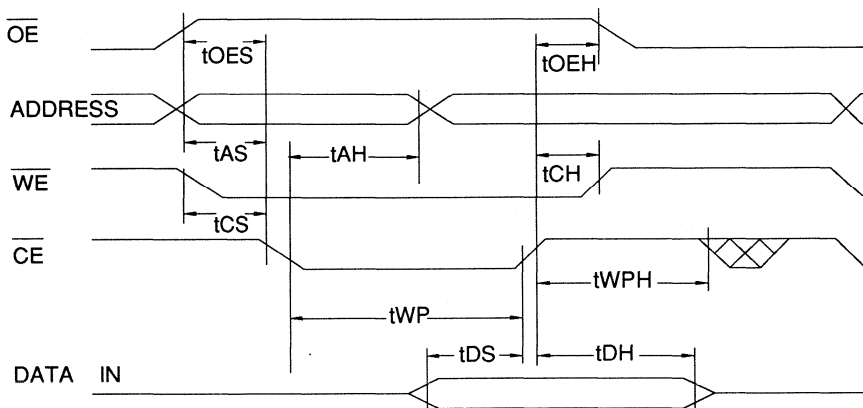
A.C. Byte Load Characteristics

Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	0		ns
t_{AH}	Address Hold Time	50		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	90		ns
t_{DS}	Data Set-up Time	50		ns
t_{DH}, t_{OEH}	Data, \overline{OE} Hold Time	0		ns
t_{WPH}	Write Pulse Width High	100		ns

A.C. Byte Load Waveforms- \overline{WE} Controlled



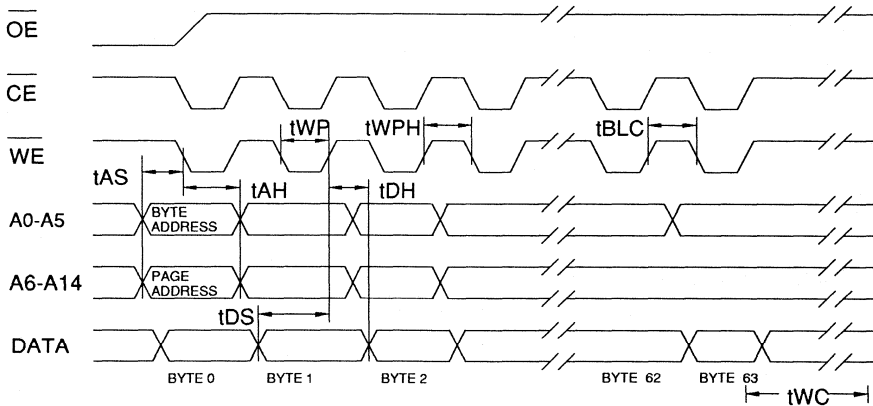
A.C. Byte Load Waveforms- \overline{CE} Controlled



Program Cycle Characteristics

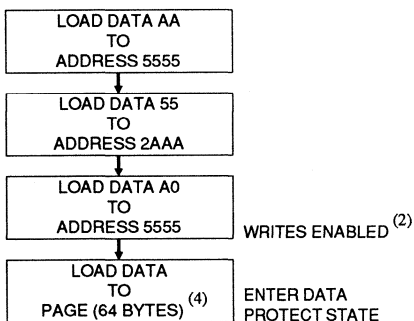
Symbol	Parameter	Min	Max	Units
t _{WC}	Write Cycle Time		10	ms
t _{AS}	Address Set-up Time	0		ns
t _{AH}	Address Hold Time	50		ns
t _{DS}	Data Set-up Time	50		ns
t _{DH}	Data Hold Time	0		ns
t _{WP}	Write Pulse Width	90		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	100		ns

Program Cycle Waveforms

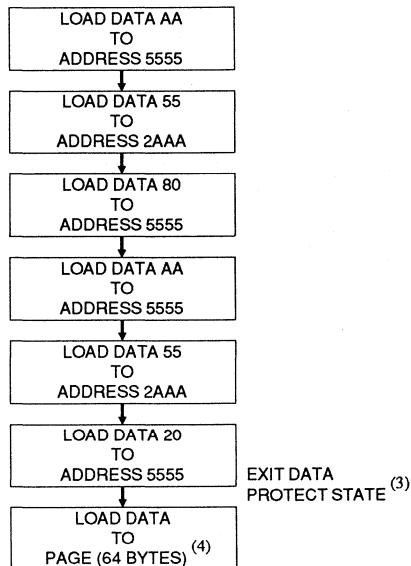


Notes: A6 through A14 must specify the page address during each high to low transition of \overline{WE} (or \overline{CE}). \overline{OE} must be high when \overline{WE} and \overline{CE} are both low. All bytes that are not loaded within the page being programmed will be erased to FF.

Software Data Protection Enable Algorithm ⁽¹⁾



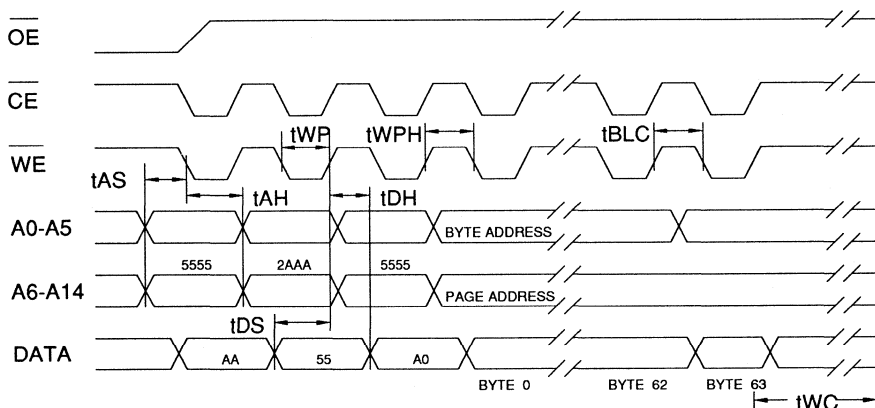
Software Data Protection Disable Algorithm ⁽¹⁾



Notes for software program code:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Data Protect state will be activated at end of program cycle.
3. Data Protect state will be deactivated at end of program period.
4. 64 bytes of data **must** be loaded.

Software Protected Program Cycle Waveform



Notes:

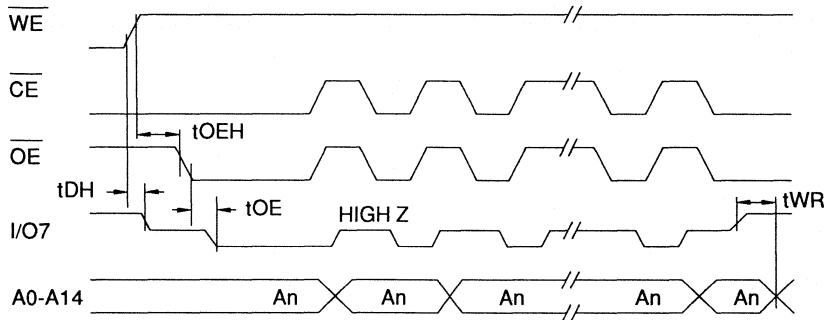
1. A6 through A14 must specify the page address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
2. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
3. All bytes that are not loaded within the page being programmed will be erased to FF.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	0			ns
t _{OEH}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

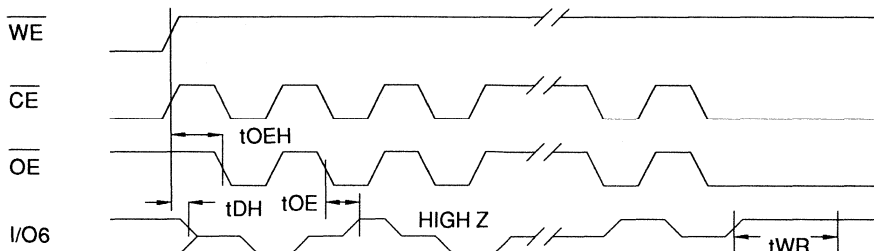


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	0			ns
t _{OEH}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

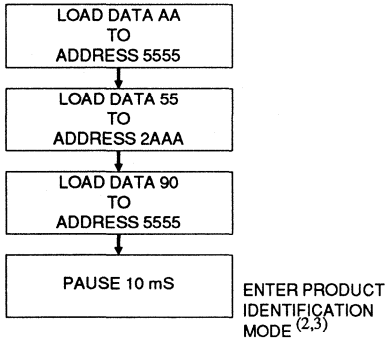
Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms

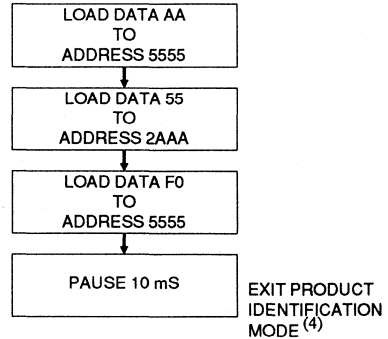


Notes:
1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
2. Beginning and ending state of I/O6 will vary.
3. Any address location may be used but the address should not vary.

Software Product Identification Entry ⁽¹⁾



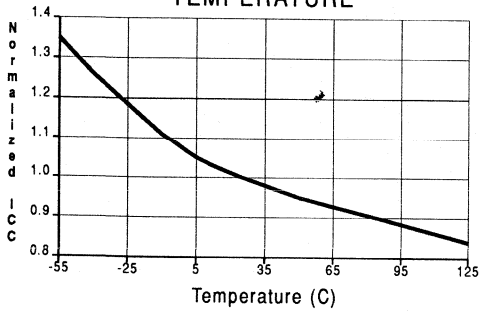
Software Product Identification Exit ⁽¹⁾



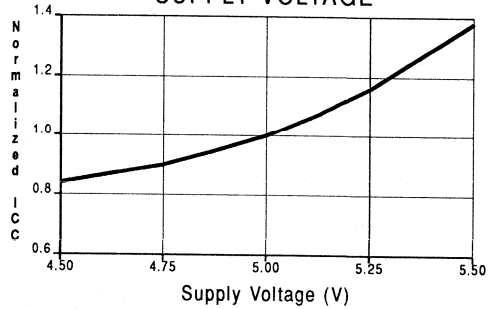
Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A14 = V_{IL} .
Manufacture Code is read for A0 = V_{IL} ;
Device Code is read for A0 = V_{IH} .
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: DC

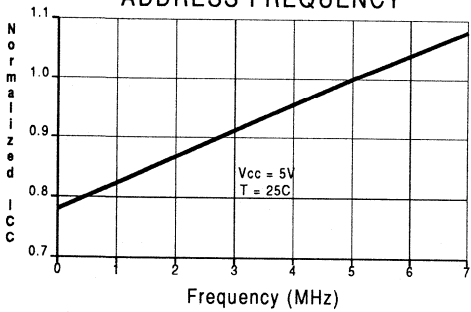
NORMALIZED SUPPLY CURRENT vs. TEMPERATURE



NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE



NORMALIZED SUPPLY CURRENT vs. ADDRESS FREQUENCY





Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range			
	Active	Standby						
90	80	0.3	AT29C256-90DC	28D6	Commercial (0° to 70°C)			
			AT29C256-90JC	32J				
			AT29C256-90PC	28P6				
90	50	0.3	AT29C256-90TC	28T	Commercial (0° to 70°C)			
120	80	0.3	AT29C256-12DC	28D6	Commercial (0° to 70°C)			
			AT29C256-12JC	32J				
			AT29C256-12LC	32L				
			AT29C256-12PC	28P6				
			AT29C256-12TC	28T	Industrial (-40° to 85°C)			
			AT29C256-12DI	28D6				
			AT29C256-12JI	32J				
			AT29C256-12LI	32L				
			AT29C256-12PI	28P6	Military (-55°C to 125°C)			
			AT29C256-12DM	28D6				
			AT29C256-12LM	32L				
			AT29C256-12DM/883	28D6				
AT29C256-12LM/883	32L	Military/883C Class B, Fully Compliant (-55°C to 125°C)						
150	80	0.3	AT29C256-15DC	28D6	Commercial (0° to 70°C)			
			AT29C256-15JC	32J				
			AT29C256-15LC	32L				
			AT29C256-15DI	28D6	Industrial (-40° to 85°C)			
			AT29C256-15JI	32J				
			AT29C256-15LI	32L				
			AT29C256-15PI	28P6				
			AT29C256-15TI	28T	Military (-55°C to 125°C)			
			AT29C256-15DM	28D6				
			AT29C256-15LM	32L				
			AT29C256-15DM/883	28D6				
			AT29C256-15LM/883	32L	Military/883C Class B, Fully Compliant (-55°C to 125°C)			
			200	80	0.3	AT29C256-20DC	28D6	Commercial (0° to 70°C)
						AT29C256-20JC	32J	
						AT29C256-20LC	32L	
						AT29C256-20PC	28P6	Industrial (-40° to 85°C)
AT29C256-20DI	28D6							
AT29C256-20JI	32J							
AT29C256-20LI	32L							
AT29C256-20PI	28P6	Military (-55°C to 125°C)						
AT29C256-20DM	28D6							
AT29C256-20LM	32L							
AT29C256-20DM/883	28D6							
AT29C256-20LM/883	32L	Military/883C Class B, Fully Compliant (-55°C to 125°C)						

Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
250	80	0.3	AT29C256-25DC	28D6	Commercial (0° to 70°C)
			AT29C256-25JC	32J	
			AT29C256-25LC	32L	
			AT29C256-25PC	28P6	
250	80	0.3	AT29C256-25DI	28D6	Industrial (-40° to 85°C)
			AT29C256-25JI	32J	
			AT29C256-25LI	32L	
			AT29C256-25PI	28P6	Military (-55°C to 125°C)
			AT29C256-25DM	28D6	
			AT29C256-25LM	32L	
250	80	0.3	AT29C256-25DM/883	28D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)
			AT29C256-25LM/883	32L	

Package Type	
28D6	28 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)
32L	32 Pad, Non-Windowed, Ceramic Leadless Chip Carrier (LCC)
28P6	28 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
28T	28 Lead, Thin Small Outline Package (TSOP)



Features

- **Fast Read Access Time - 90 ns**
- **Five-Volt-Only Reprogramming**
- **Page Program Operation**
 - **Single Cycle Reprogram (Erase and Program)**
 - **Internal Address and Data Latches for 64 Bytes**
- **Internal Program Control and Timer**
- **Hardware and Software Data Protection**
- **Fast Program Cycle Times**
 - **Page (64 Byte) Program Time - 10 ms**
 - **Chip Erase Time - 10 ms**
- **DATA Polling for End of Program Detection**
- **Low Power Dissipation**
 - **50 mA Active Current**
 - **300 μ A CMOS Standby Current**
- **High Reliability CMOS Technology**
 - **1000 Erase/Program Cycles**
 - **10 Year Data Retention**
- **Single 5 V \pm 10% Supply**
- **CMOS and TTL Compatible Inputs and Outputs**
- **Full Military, Commercial, and Industrial Temperature Ranges**
- **Pin-Compatible with 29C010 and 29C512 for Easy System Upgrades**

**256K (32K x 8)
5-Volt Only
CMOS Flash
PEROM**

Description

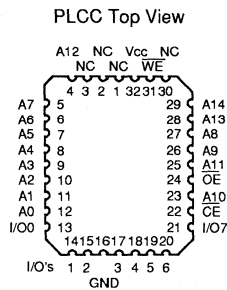
The AT29C257 is a five-volt-only in-system Flash Programmable and Erasable Read Only Memory (PEROM). Its 256K of memory is organized as 32,768 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 90 ns with power dissipation of just 275 mW. When the device is deselected, the CMOS standby current is less than 300 μ A.

To allow for simple in-system reprogrammability, the AT29C257 does not require high input voltages for programming. Five-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from a static RAM. Reprogramming the AT29C257 is performed on a page basis; 64 bytes of data are loaded into the device and then simultaneously programmed. The contents of the entire device may be erased by using a six-byte software code (although erasure before programming is not needed).

During a reprogram cycle, the address locations and 64 bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the page and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected a new access for a read, program or chip erase can begin.

Pin Configurations

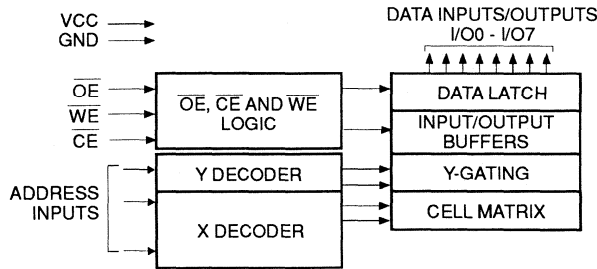
Pin Name	Function
A0 - A14	Addresses
$\overline{\text{CE}}$	Chip Enable
$\overline{\text{OE}}$	Output Enable
$\overline{\text{WE}}$	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect



- Notes:
1. PLCC package pin 30 is a DON'T CONNECT.
 2. To upgrade to the 1-Mbit 29C010, pin 3 is A15 and pin 2 is A16.



Block Diagram



Device Operation

READ: The AT29C257 is accessed like a static RAM. When \overline{CE} and \overline{OE} are low and \overline{WE} is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever \overline{CE} or \overline{OE} is high. This dual-line control gives designers flexibility in preventing bus contention.

BYTE LOAD: A byte load is performed by applying a low pulse on the \overline{WE} or \overline{CE} input with \overline{CE} or \overline{WE} low (respectively) and \overline{OE} high. The address is latched on the falling edge of \overline{CE} or \overline{WE} , whichever occurs last. The data is latched by the first rising edge of \overline{CE} or \overline{WE} . Byte loads are used to enter the 64 bytes of a page to be programmed or the software codes for data protection and chip erasure.

PROGRAM: The device is reprogrammed on a page basis. If a byte of data within a page is to be changed, data for the entire page must be loaded into the device. Any byte that is not loaded during the programming of its page will be erased to read FFh. Once the bytes of a page are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on \overline{WE} (or \overline{CE}) within 150 μ s of the low to high transition of \overline{WE} (or \overline{CE}) of the preceding byte. If a high to low transition is not detected within 150 μ s of the last low to high transition, the load period will end and the internal programming period will start. A6 to A14 specify the page address. The page address must be valid during each high to low transition of \overline{WE} (or \overline{CE}). A0 to A5 specify the byte address within the page. The bytes may be loaded in any order; sequential loading is not required.

SOFTWARE DATA PROTECTION: A software controlled data protection feature is available on the AT29C257. Once the software protection is enabled a software algorithm must be issued to the device before a program may be performed. The software protection feature may be enabled or disabled by the

user; when shipped from Atmel, the software data protection feature is disabled. To enable the software data protection, a series of three program commands to specific addresses with specific data must be performed. After the software data protection is enabled the same three program commands must begin each program cycle in order for the programs to occur. All software program commands must obey the page program timing specifications. Once set, the software data protection feature remains active unless its disable command is issued. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

Once set, software data protection will remain active unless the disable command sequence is issued.

After setting SDP, any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc}, a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the \overline{WE} or \overline{CE} input with \overline{CE} or \overline{WE} low (respectively) and \overline{OE} high. The address is latched on the falling edge of \overline{CE} or \overline{WE} , whichever occurs last. The data is latched by the first rising edge of \overline{CE} or \overline{WE} . The 64 bytes of data must be loaded into each sector by the same procedure as outlined in the program section under device operation.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29C257 in the following ways: (a) V_{CC} sense— if V_{CC} is below 3.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 5 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of

continued on next page

Device Operation (Continued)

less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer and may be accessed by a hardware or software operation. For details, see Operating Modes or Software Product Identification.

DATA POLLING: The AT29C257 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next

cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29C257 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to $V_{CC} + 0.6$ V
Voltage on \overline{OE} with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. This parameter is characterized and is not 100% tested.



D.C. and A.C. Operating Range

		AT29C257-90	AT29C257-12	AT29C257-15	AT29C257-20	AT29C257-25
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
	Ind.		-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
V _{CC} Power Supply		5 V ± 10%	5 V ± 10%	5 V ± 10%	5 V ± 10%	5 V ± 10%

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	DOUT
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	DIN
5V Chip Erase	V _{IL}	V _{IH}	V _{IL}	Ai	
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Write Inhibit	X	X	V _{IH}		
Write Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
High Voltage Chip Erase	V _{IL}	V _H ⁽³⁾	V _{IL}	X	High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A14 = V _{IL} , A9 = V _H , A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A14 = V _{IL} , A9 = V _H , A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_H = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: DC

5. See details under Software Product Identification Entry/Exit.

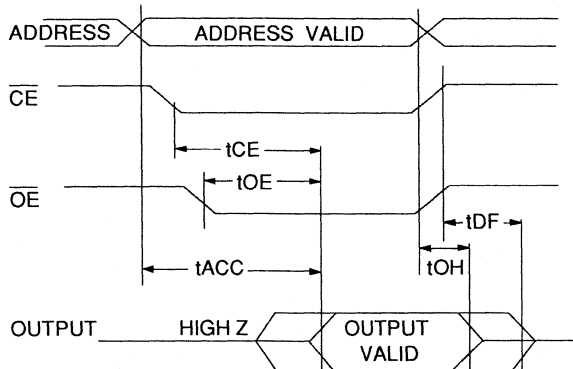
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		10	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		10	μA
I _{SB1}	V _{CC} Standby Current CMOS	\overline{CE} = V _{CC} -0.3V to V _{CC}		300	μA
I _{SB2}	V _{CC} Standby Current TTL	\overline{CE} = 2.0 V to V _{CC}		3	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA		50	mA
V _{IL}	Input Low Voltage			0.8	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		.45	V
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	I _{OH} = -100 μA; V _{CC} = 4.5V	4.2		V

A.C. Read Characteristics

Symbol	Parameter	AT29C257-90		AT29C257-12		AT29C257-15		AT29C257-20		AT29C257-25		Units
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t_{ACC}	Address to Output Delay	90		120		150		200		250		ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay	90		120		150		200		250		ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	40	0	50	0	70	0	80	0	100	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	25	0	30	0	40	0	50	0	60	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		0		0		0		ns

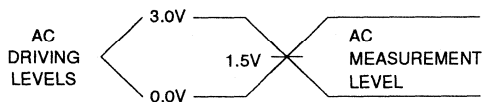
A.C. Read Waveforms



Notes:

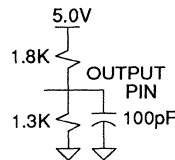
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5 \text{ pF}$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5 \text{ ns}$

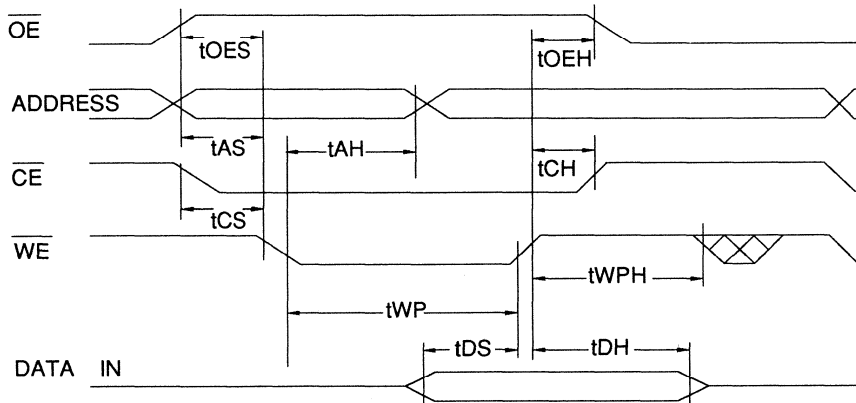
Output Test Load



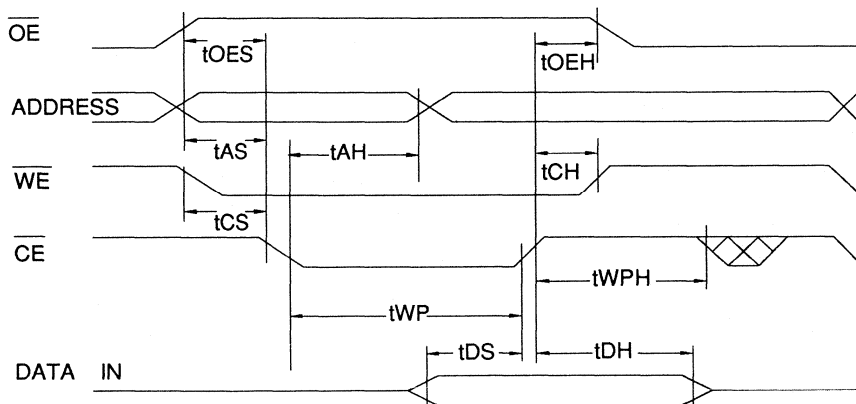
A.C. Byte Load Characteristics

Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	0		ns
t_{AH}	Address Hold Time	50		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	90		ns
t_{DS}	Data Set-up Time	50		ns
t_{DH}, t_{OEh}	Data, \overline{OE} Hold Time	0		ns
t_{WPH}	Write Pulse Width High	100		ns

A.C. Byte Load Waveforms- \overline{WE} Controlled



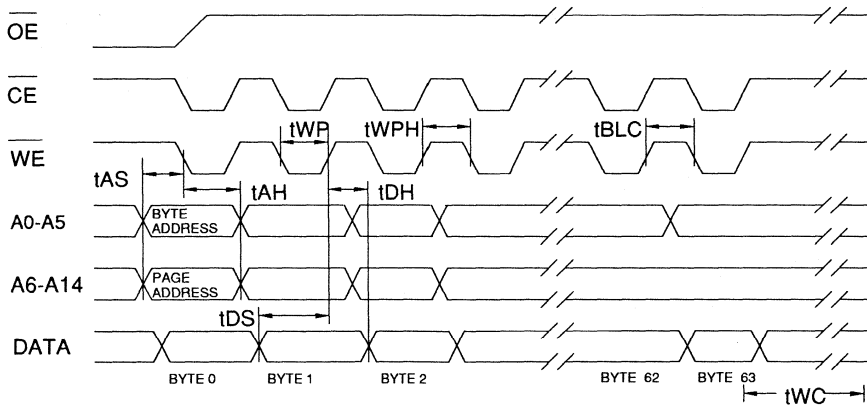
A.C. Byte Load Waveforms- \overline{CE} Controlled



Program Cycle Characteristics

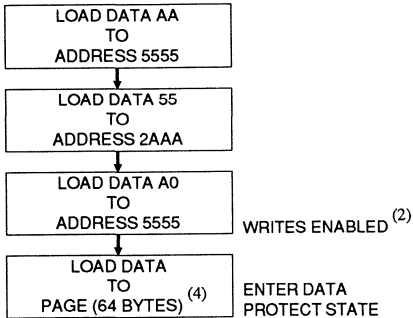
Symbol	Parameter	Min	Max	Units
t _{WC}	Write Cycle Time		10	ms
t _{AS}	Address Set-up Time	0		ns
t _{AH}	Address Hold Time	50		ns
t _{DS}	Data Set-up Time	50		ns
t _{DH}	Data Hold Time	0		ns
t _{WP}	Write Pulse Width	90		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	100		ns

Program Cycle Waveforms

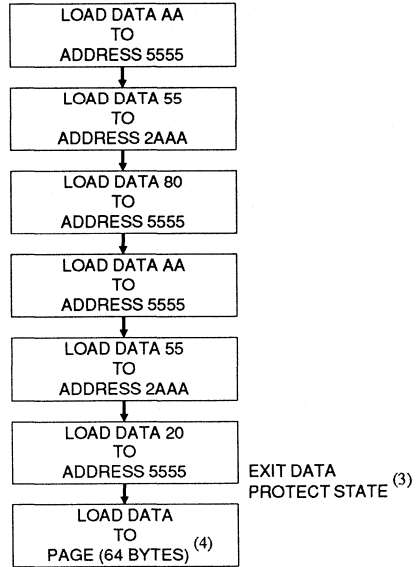


Notes: A6 through A14 must specify the page address during each high to low transition of \overline{WE} (or \overline{CE}).
 \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
 All bytes that are not loaded within the page being programmed will be erased to FF.

Software Data Protection Enable Algorithm ⁽¹⁾



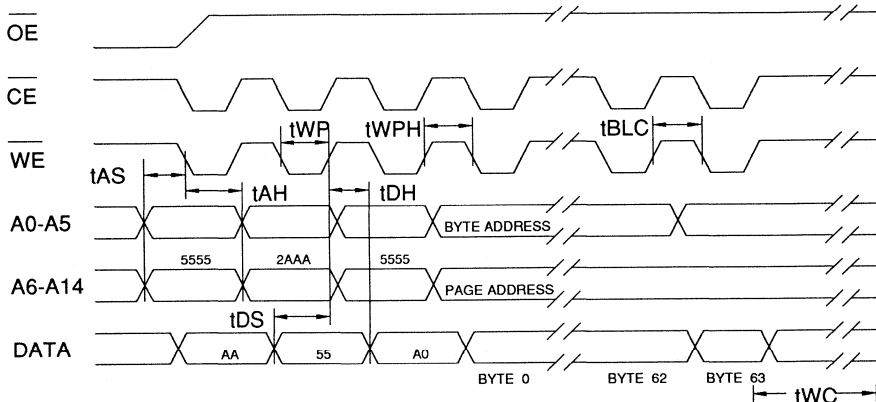
Software Data Protection Disable Algorithm ⁽¹⁾



Notes for software program code:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Data Protect state will be activated at end of program cycle.
3. Data Protect state will be deactivated at end of program period.
4. 64 bytes of data **must** be loaded.

Software Protected Program Cycle Waveform



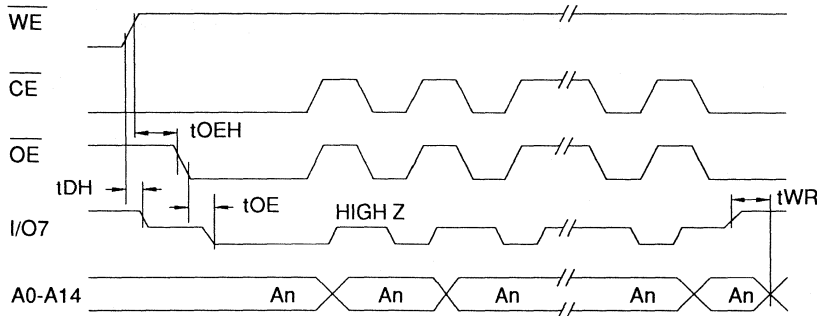
- Notes:
1. A6 through A14 must specify the page address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
 2. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
 3. All bytes that are not loaded within the page being programmed will be erased to FF.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	0			ns
t _{OEH}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

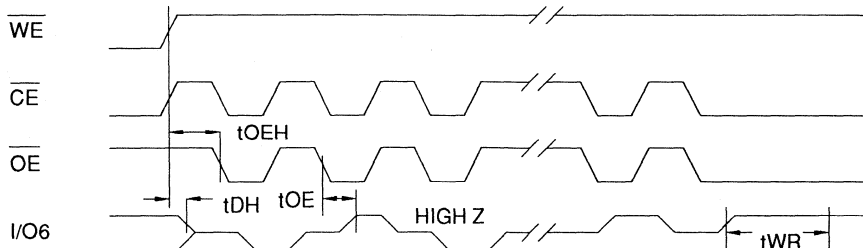


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	0			ns
t _{OEH}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

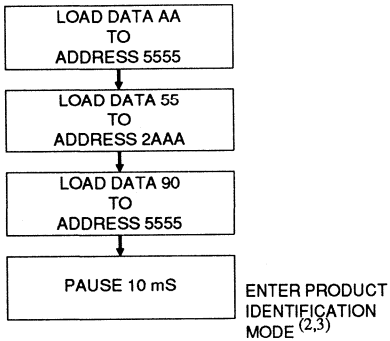
Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms

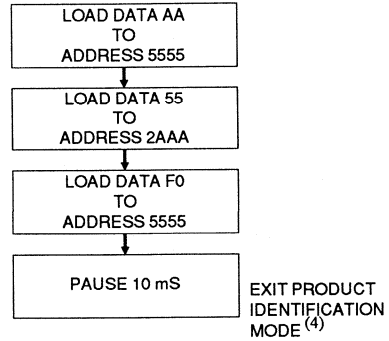


Notes:
 1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
 2. Beginning and ending state of I/O6 will vary.
 3. Any address location may be used but the address should not vary.

Software Product Identification Entry ⁽¹⁾



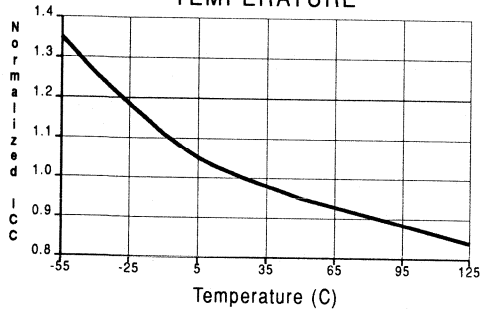
Software Product Identification Exit ⁽¹⁾



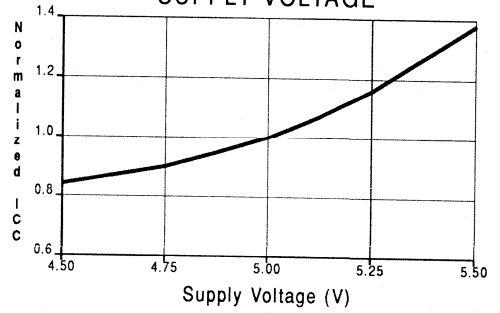
Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A14 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: DC

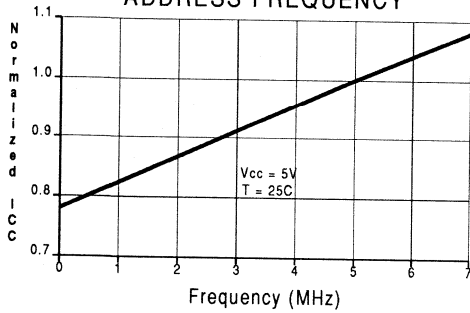
NORMALIZED SUPPLY CURRENT vs. TEMPERATURE



NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE



NORMALIZED SUPPLY CURRENT vs. ADDRESS FREQUENCY





Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
90	80	0.3	AT29C257-90JC	32J	Commercial (0° to 70°C)
120	80	0.3	AT29C257-12JC	32J	Commercial (0° to 70°C)
			AT29C257-12JI	32J	Industrial (-40° to 85°C)
150	80	0.3	AT29C257-15JC	32J	Commercial (0° to 70°C)
			AT29C257-15JI	32J	Industrial (-40° to 85°C)
200	80	0.3	AT29C257-20JC	32J	Commercial (0° to 70°C)
			AT29C257-20JI	32J	Industrial (-40° to 85°C)
250	80	0.3	AT29C257-25JC	32J	Commercial (0° to 70°C)
			AT29C257-25JI	32J	Industrial (-40° to 85°C)

Package Type

32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)
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Features

- Fast Read Access Time - 90 ns
- Five-Volt-Only Reprogramming
- Sector Program Operation
 - Single Cycle Reprogram (Erase and Program)
 - 512 Sectors (128 bytes/sector)
 - Internal Address and Data Latches for 128 Bytes
- Internal Program Control and Timer
- Hardware and Software Data Protection
- Fast Sector Program Cycle Time - 10 ms
- DATA Polling for End of Program Detection
- Low Power Dissipation
 - 50 mA Active Current
 - 100 μ A CMOS Standby Current
- High Reliability CMOS Technology
 - 1000 Program Cycles per Sector
 - 10-Year Data Retention
- Single 5 V \pm 10% Supply
- CMOS and TTL Compatible Inputs and Outputs
- Full Military, Commercial, and Industrial Temperature Ranges

**512K (64K x 8)
5-Volt Only
CMOS Flash
PEROM**

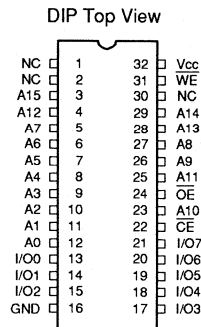
Description

The AT29C512 is a five-volt-only in-system Flash Programmable and Erasable Read Only Memory (PEROM). Its 512K of memory is organized as 65,536 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 90 ns with power dissipation of just 275 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than 100 μ A.

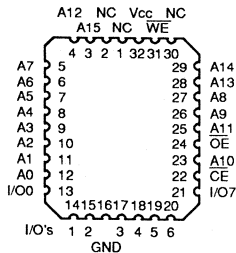
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Pin Configurations

Pin Name	Function
A0 - A15	Addresses
CE	Chip Enable
OE	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

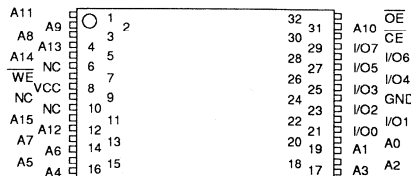


PLCC and LCC Top View



Note: PLCC package pin 30 is a DON'T CONNECT.

TSOP Top View
Type 1

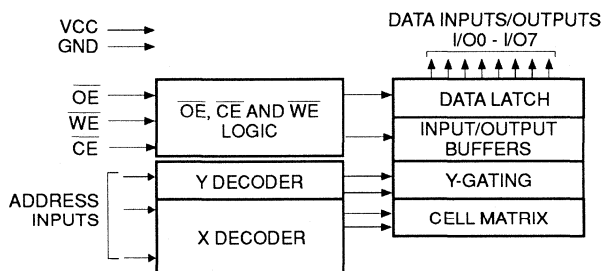


Description (Continued)

To allow for simple in-system reprogrammability, the AT29C512 does not require high input voltages for programming. Five-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT29C512 is performed on a sector basis; 128 bytes of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 128 bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29C512 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

BYTE LOAD: Byte loads are used to enter the 128 bytes of a sector to be programmed or the software codes for data protection. A byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

PROGRAM: The device is reprogrammed on a sector basis. If a byte of data within a sector is to be changed, data for the entire sector must be loaded into the device. Any byte that is not loaded during the programming of its sector will be erased to read FFh. Once the bytes of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) of the preceding byte. If a high to low transition is not detected within 150 μs of the last low to high transition, the load period will end and the internal programming period will start. A7 to A15 specify the sector address. The sector address must be valid during each high to low transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$). A0 to A6 specify the byte address within the sector. The

bytes may be loaded in any order; sequential loading is not required.

SOFTWARE DATA PROTECTION: A software controlled data protection feature is available on the AT29C512. Once the software protection is enabled a software algorithm must be issued to the device before a program may be performed. The software protection feature may be enabled or disabled by the user; when shipped from Atmel, the software data protection feature is disabled. To enable the software data protection, a series of three program commands to specific addresses with specific data must be performed. After the software data protection is enabled the same three program commands must begin each program cycle in order for the programs to occur. All software program commands must obey the sector program timing specifications. Once set, the software data protection feature remains active unless its disable command is issued. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

Once set, software data protection will remain active unless the disable command sequence is issued.

After setting SDP, any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc}, a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high.

continued on next page

Device Operation (Continued)

The address is latched on the falling edge of \overline{CE} or \overline{WE} , whichever occurs last. The data is latched by the first rising edge of \overline{CE} or \overline{WE} . The 128 bytes of data must be loaded into each sector by the same procedure as outlined in the program section under device operation.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29C512 in the following ways: (a) V_{CC} sense— if V_{CC} is below 3.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 5 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identification mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common

board design for 256K to 4-megabit densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

\overline{DATA} POLLING: The AT29C512 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29C512 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to $V_{CC} + 0.6$ V
Voltage on \overline{OE} with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.

This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Notes: 1. This parameter is characterized and is not 100% tested.



D.C. and A.C. Operating Range

		AT29C512-90	AT29C512-12	AT29C512-15	AT29C512-20
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
	Mil.		-55°C - 125°C	-55°C - 125°C	-55°C - 125°C
V _{CC} Power Supply		5 V ± 10%	5 V ± 10%	5 V ± 10%	5 V ± 10%

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	D _{OUT}
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	D _{IN}
5V Chip Erase	V _{IL}	V _{IH}	V _{IL}	Ai	
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A15 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A15 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_H = 12.0 V ± 0.5 V

4. Manufacturer Code: 1F, Device Code: 5D

5. See details under Software Product Identification Entry/Exit.

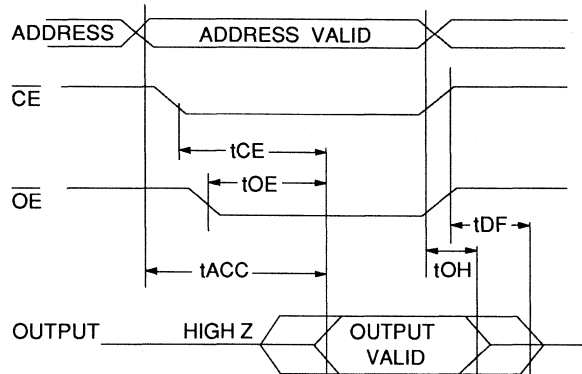
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		10	μA
I _{LO}	Output Leakage Current	V _{IO} = 0 V to V _{CC}		10	μA
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{CE} = V_{CC} - 0.3 \text{ V to } V_{CC}$	Com.	100	μA
			Ind., Mil.	300	μA
I _{SB2}	V _{CC} Standby Current TTL	$\overline{CE} = 2.0 \text{ V to } V_{CC}$		3	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA		50	mA
V _{IL}	Input Low Voltage			0.8	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		.45	V
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	I _{OH} = -100 μA; V _{CC} = 4.5 V	4.2		V

A.C. Read Characteristics

Symbol	Parameter	AT29C512-90		AT29C512-12		AT29C512-15		AT29C512-20		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		90		120		150		200	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		90		120		150		200	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	40	0	50	0	70	0	80	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	25	0	30	0	40	0	50	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		0		0		ns

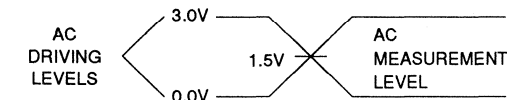
A.C. Read Waveforms



Notes:

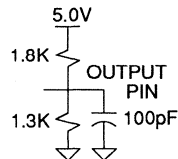
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5 \text{ pF}$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5 \text{ ns}$

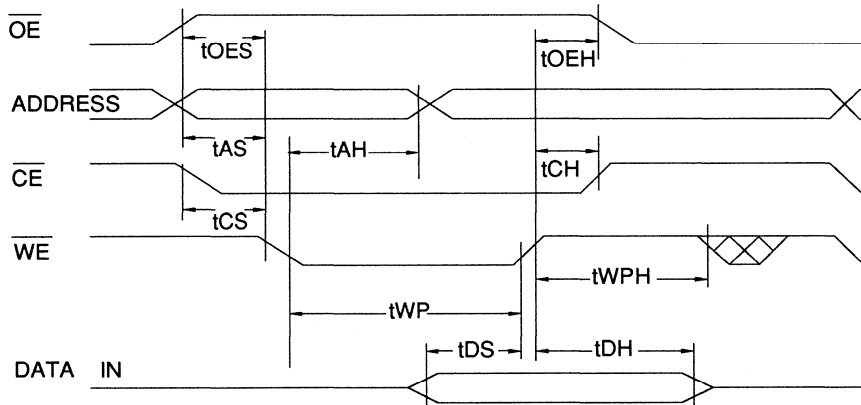
Output Test Load



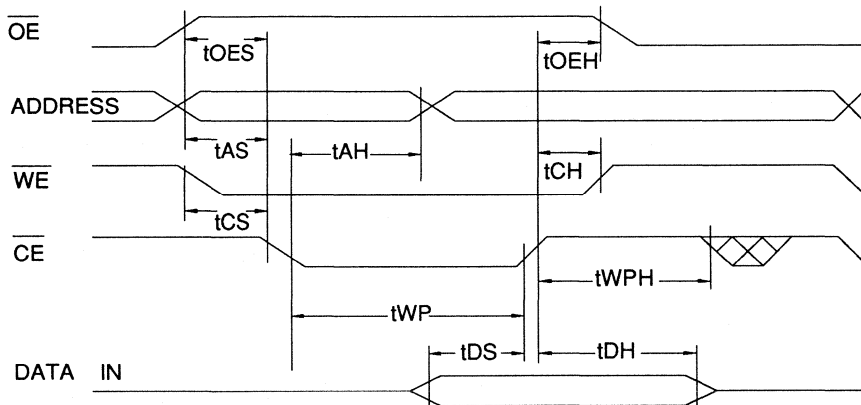
A.C. Byte Load Characteristics

Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	0		ns
t_{AH}	Address Hold Time	50		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	90		ns
t_{DS}	Data Set-up Time	50		ns
t_{DH}, t_{OEH}	Data, \overline{OE} Hold Time	0		ns
t_{WPH}	Write Pulse Width High	100		ns

A.C. Byte Load Waveforms- \overline{WE} Controlled



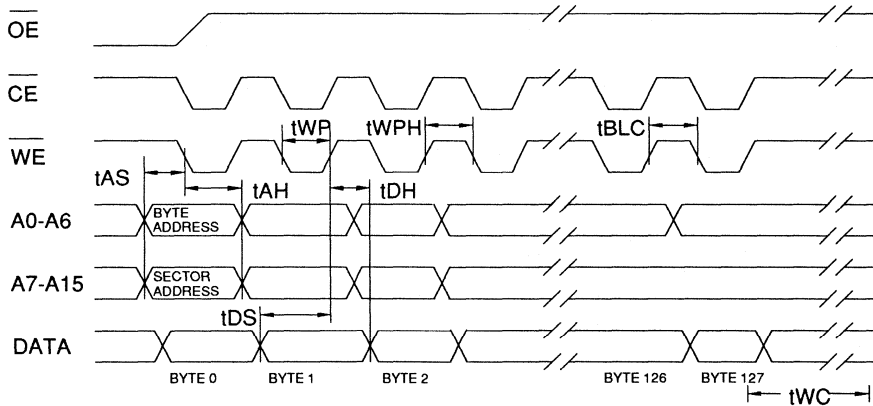
A.C. Byte Load Waveforms- \overline{CE} Controlled



Program Cycle Characteristics

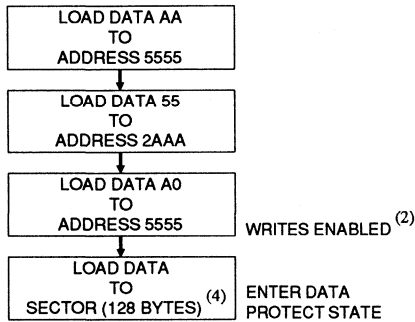
Symbol	Parameter	Min	Max	Units
t _{wc}	Write Cycle Time		10	ms
t _{AS}	Address Set-up Time	0		ns
t _{AH}	Address Hold Time	50		ns
t _{DS}	Data Set-up Time	50		ns
t _{DH}	Data Hold Time	0		ns
t _{WP}	Write Pulse Width	90		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	100		ns

Program Cycle Waveforms

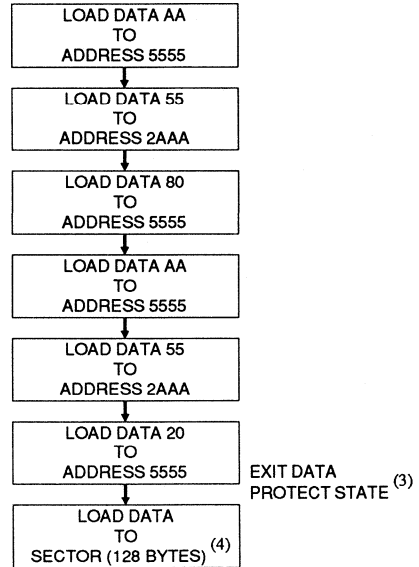


Notes: A7 through A15 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}).
 \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
 All bytes that are not loaded within the sector being programmed will be erased to FF.

Software Data Protection Enable Algorithm ⁽¹⁾



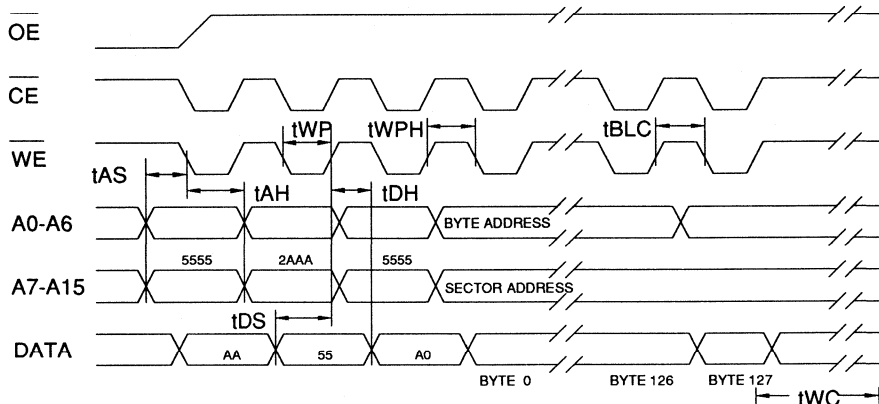
Software Data Protection Disable Algorithm ⁽¹⁾



Notes for software program code:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Data Protect state will be activated at end of program cycle.
3. Data Protect state will be deactivated at end of program period.
4. 128 bytes of data **MUST BE** loaded.

Software Protected Program Cycle Waveform



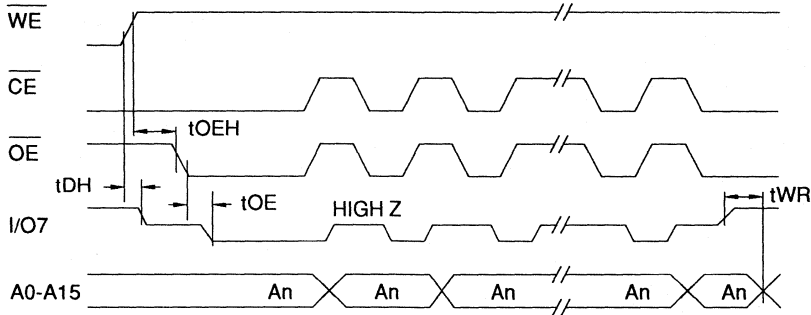
- Notes:
- A7 through A15 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
 - \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
 - All bytes that are not loaded within the sector being programmed will be erased to FF.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE_H}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾			100	ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

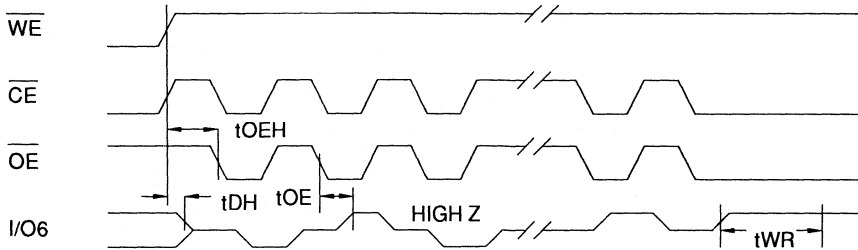


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE_H}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

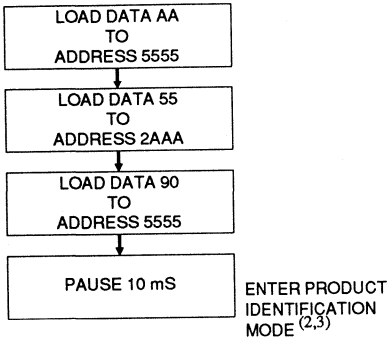
Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms

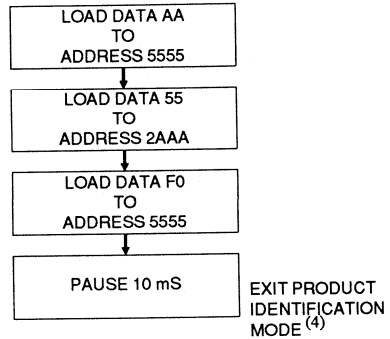


Notes:
 1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
 2. Beginning and ending state of I/O6 will vary.
 3. Any address location may be used but the address should not vary.

Software Product Identification Entry ⁽¹⁾



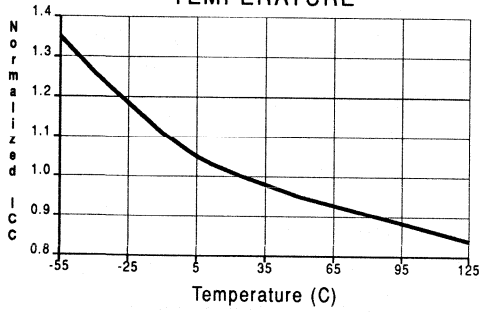
Software Product Identification Exit ⁽¹⁾



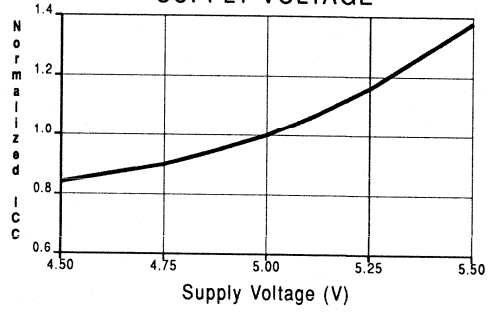
Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A15 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: 5D

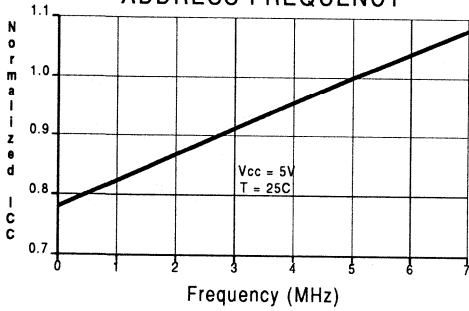
NORMALIZED SUPPLY CURRENT vs. TEMPERATURE



NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE



NORMALIZED SUPPLY CURRENT vs. ADDRESS FREQUENCY





Ordering Information

tACC (ns)	ICC (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
90	50	0.1	AT29C512-90DC AT29C512-90JC AT29C512-90PC	32D6 32J 32P6	Commercial (0° to 70°C)
90	50	0.3	AT29C512-90DI AT29C512-90JI AT29C512-90PI	32D6 32J 32P6	Industrial (-40° to 85°C)
120	50	0.1	AT29C512-12DC AT29C512-12JC AT29C512-12PC AT29C512-12TC	32D6 32J 32P6 32T	Commercial (0° to 70°C)
120	50	0.3	AT29C512-12DI AT29C512-12JI AT29C512-12PI	32D6 32J 32P6	Industrial (-40° to 85°C)
			AT29C512-12DM	32D6	Military (-55°C to 125°C)
			AT29C512-12DM/883	32D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)
150	50	0.1	AT29C512-15DC AT29C512-15JC AT29C512-15PC AT29C512-15TC	32D6 32J 32P6 32T	Commercial (0° to 70°C)
150	50	0.3	AT29C512-15DI AT29C512-15JI AT29C512-15PI	32D6 32J 32P6	Industrial (-40° to 85°C)
			AT29C512-15DM	32D6	Military (-55°C to 125°C)
			AT29C512-15DM/883	32D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)
200	50	0.1	AT29C512-20DC AT29C512-20JC AT29C512-20PC	32D6 32J 32P6	Commercial (0° to 70°C)
200	50	0.3	AT29C512-20DI AT29C512-20JI AT29C512-20PI	32D6 32J 32P6	Industrial (-40° to 85°C)
			AT29C512-20DM	32D6	Military (-55°C to 125°C)
			AT29C512-20DM/883	32D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)

Ordering Information

Package Type	
32D6	32 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)
32P6	32 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
32T	32 Lead, Thin Small Outline Package (TSOP)



Features

- **Fast Read Access Time - 90 ns**
- **Five-Volt-Only Reprogramming**
- **Sector Program Operation**
 - Single Cycle Reprogram (Erase and Program)
 - 1024 Sectors (128 bytes/sector)
 - Internal Address and Data Latches for 128 Bytes
- **Internal Program Control and Timer**
- **Hardware and Software Data Protection**
- **Fast Sector Program Cycle Time - 10 ms**
- **DATA Polling for End of Program Detection**
- **Low Power Dissipation**
 - 50 mA Active Current
 - 100 μ A CMOS Standby Current
- **High Reliability CMOS Technology**
 - 1000 Program Cycles per Sector
 - 10-Year Data Retention
- **Single 5 V \pm 10% Supply**
- **CMOS and TTL Compatible Inputs and Outputs**
- **Full Military, Commercial, and Industrial Temperature Ranges**

**1 Megabit
(128K x 8)
5-Volt Only
CMOS Flash
PEROM**

Description

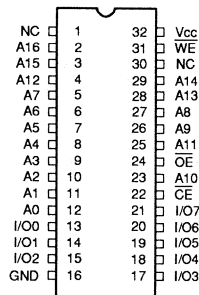
The AT29C010 is a five-volt-only in-system Flash Programmable and Erasable Read Only Memory (PEROM). Its one megabit of memory is organized as 131,072 words by 8 bits. Manufactured with Amel's advanced nonvolatile CMOS technology, the device offers access times to 90 ns with power dissipation of just 275 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than 100 μ A.

continued on next page

Pin Configurations

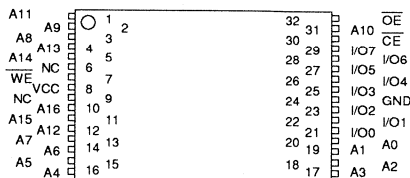
Pin Name	Function
A0 - A16	Addresses
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

DIP Top View

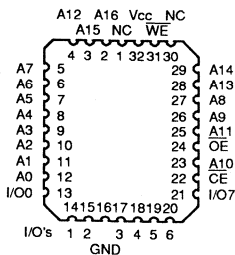


TSOP Top View

Type 1



PLCC and LCC Top View



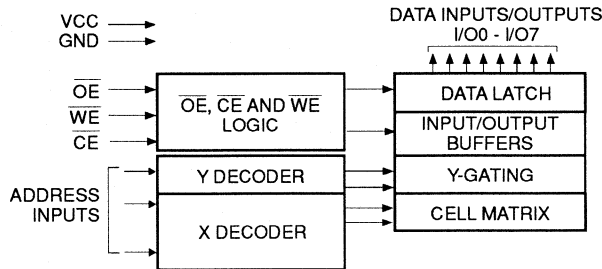
Note: PLCC package pin 30 is a DON'T CONNECT.

Description (Continued)

To allow for simple in-system reprogrammability, the AT29C010 does not require high input voltages for programming. Five-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT29C010 is performed on a sector basis; 128 bytes of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 128 bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by DATA polling of I/O7. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29C010 is accessed like an EPROM. When \overline{CE} and \overline{OE} are low and \overline{WE} is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever \overline{CE} or \overline{OE} is high. This dual-line control gives designers flexibility in preventing bus contention.

BYTE LOAD: Byte loads are used to enter the 128 bytes of a sector to be programmed or the software codes for data protection. A byte load is performed by applying a low pulse on the \overline{WE} or \overline{CE} input with \overline{CE} or \overline{WE} low (respectively) and \overline{OE} high. The address is latched on the falling edge of \overline{CE} or \overline{WE} , whichever occurs last. The data is latched by the first rising edge of \overline{CE} or \overline{WE} .

PROGRAM: The device is reprogrammed on a sector basis. If a byte of data within a sector is to be changed, data for the entire sector must be loaded into the device. Any byte that is not loaded during the programming of its sector will be erased to read FFh. Once the bytes of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on \overline{WE} (or \overline{CE}) within 150 μ s of the low to high transition of \overline{WE} (or \overline{CE}) of the preceding byte. If a high to low transition is not detected within 150 μ s of the last low to high transition, the load period will end and the internal programming period will start. A7 to A16 specify the sector address. The sector address must be valid during each high to low transition of \overline{WE} (or \overline{CE}). A0 to A6 specify the byte address within the sector. The bytes may be loaded in any order; sequential loading is not required.

SOFTWARE DATA PROTECTION: A software controlled data protection feature is available on the AT29C010. Once the software protection is enabled a software algorithm must be issued to the device before a program may be performed. The software protection feature may be enabled or disabled by the user; when shipped from Atmel, the software data protection feature is disabled. To enable the software data protection, a series of three program commands to specific addresses with specific data must be performed. After the software data protection is enabled the same three program commands must begin each program cycle in order for the programs to occur. All software program commands must obey the sector program timing specifications. Once set, the software data protection feature remains active unless its disable command is issued. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

Once set, software data protection will remain active unless the disable command sequence is issued.

After setting SDP, any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc}, a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the \overline{WE} or \overline{CE} input with \overline{CE} or \overline{WE} low (respectively) and \overline{OE} high. The address is latched on the falling edge of \overline{CE} or \overline{WE} , whichever occurs last. The data is latched by the first rising edge of \overline{CE} or \overline{WE} . The 128 bytes of data must be loaded into each sector by

continued on next page

Device Operation (Continued)

the same procedure as outlined in the program section under device operation.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29C010 in the following ways: (a) V_{CC} sense— if V_{CC} is below 3.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 5 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identification mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for 256K to 4-megabit densities and, with each

density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

\overline{DATA} POLLING: The AT29C010 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29C010 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to V_{CC} +0.6 V
Voltage on \overline{OE} with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. This parameter is characterized and is not 100% tested.



D.C. and A.C. Operating Range

		AT29C010-90	AT29C010-12	AT29C010-15	AT29C010-20
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
	Mil.		-55°C - 125°C	-55°C - 125°C	-55°C - 125°C
Vcc Power Supply		5 V ± 10%	5 V ± 10%	5 V ± 10%	5 V ± 10%

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	D _{OUT}
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	D _{IN}
5V Chip Erase	V _{IL}	V _{IH}	V _{IL}	Ai	
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A16 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A16 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_{IH} = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: D5

5. See details under Software Product Identification Entry/Exit.

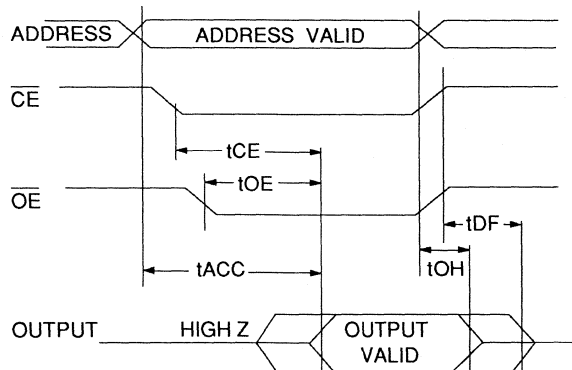
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		10	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		10	μA
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{CE} = V_{CC} - 0.3V$ to V _{CC}	Com.	100	μA
			Ind., Mil.	300	μA
I _{SB2}	V _{CC} Standby Current TTL	$\overline{CE} = 2.0 V$ to V _{CC}		3	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA		50	mA
V _{IL}	Input Low Voltage			0.8	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		.45	V
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	I _{OH} = -100 μA; V _{CC} = 4.5 V	4.2		V

A.C. Read Characteristics

Symbol	Parameter	AT29C010-90		AT29C010-12		AT29C010-15		AT29C010-20		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		90		120		150		200	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		90		120		150		200	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	40	0	50	0	70	0	80	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	25	0	30	0	40	0	50	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		0		0		ns

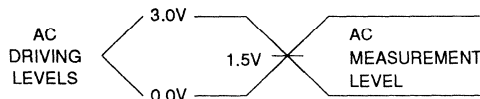
A.C. Read Waveforms



Notes:

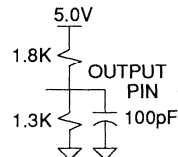
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5pF$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5 \text{ ns}$

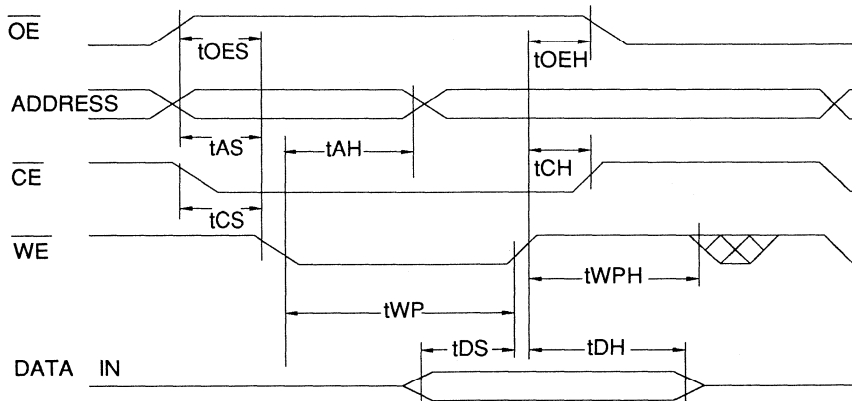
Output Test Load



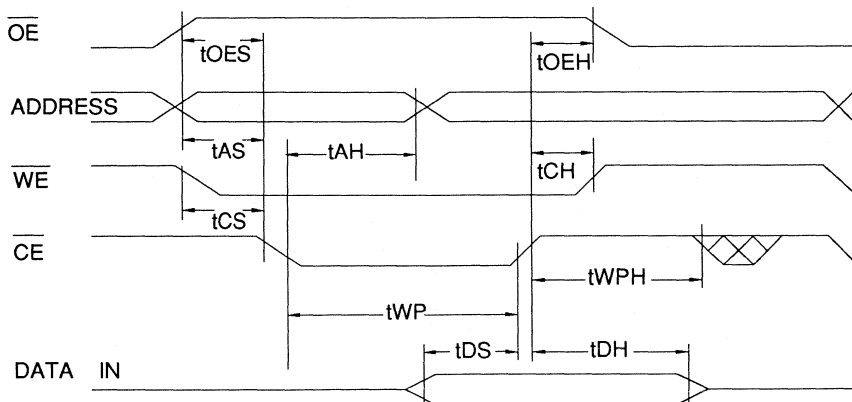
A.C. Byte Load Characteristics

Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	0		ns
t_{AH}	Address Hold Time	50		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	90		ns
t_{DS}	Data Set-up Time	50		ns
t_{DH}, t_{OEH}	Data, \overline{OE} Hold Time	0		ns
t_{WPH}	Write Pulse Width High	100		ns

A.C. Byte Load Waveforms- \overline{WE} Controlled



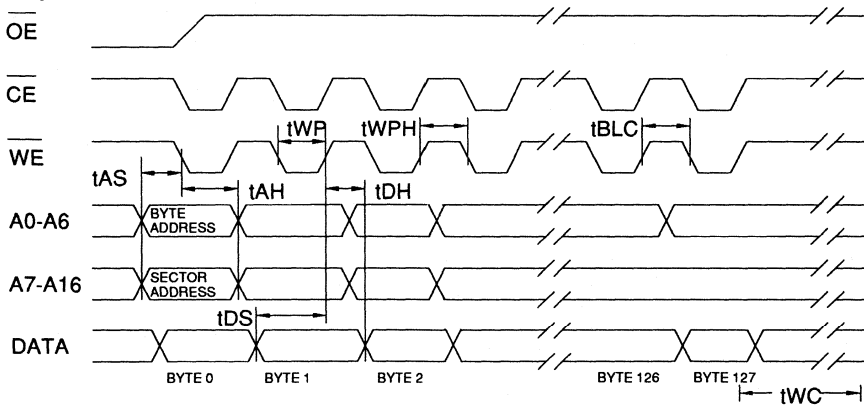
A.C. Byte Load Waveforms- \overline{CE} Controlled



Program Cycle Characteristics

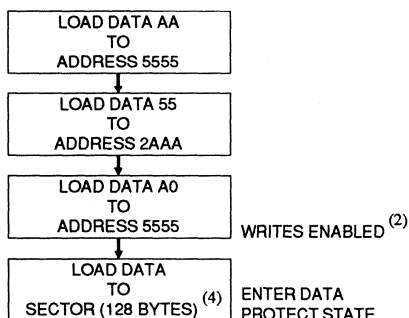
Symbol	Parameter	Min	Max	Units
t _{WC}	Write Cycle Time		10	ms
t _{AS}	Address Set-up Time	0		ns
t _{AH}	Address Hold Time	50		ns
t _{DS}	Data Set-up Time	50		ns
t _{DH}	Data Hold Time	0		ns
t _{WP}	Write Pulse Width	90		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	100		ns

Program Cycle Waveforms

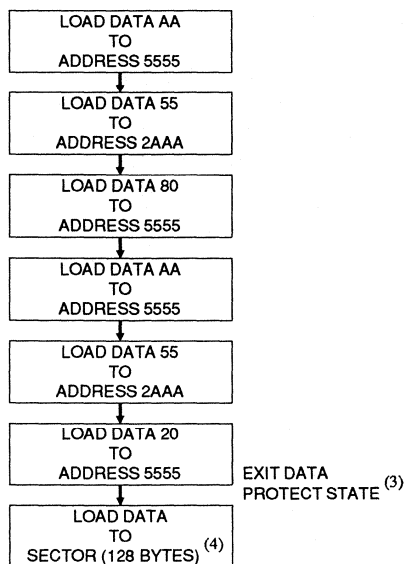


Notes: A7 through A16 must specify the sector address during each high to low transition of WE (or CE).
 OE must be high when WE and CE are both low.
 All bytes that are not loaded within the sector being programmed will be erased to FF.

Software Data Protection Enable Algorithm ⁽¹⁾



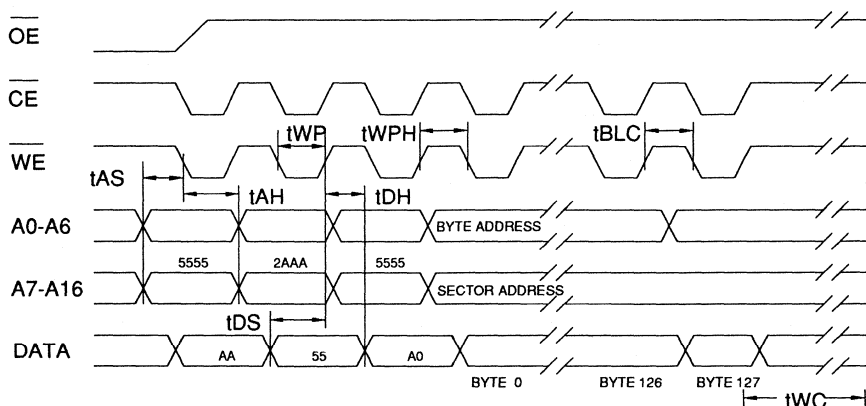
Software Data Protection Disable Algorithm ⁽¹⁾



Notes for software program code:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Data Protect state will be activated at end of program cycle.
3. Data Protect state will be deactivated at end of program period.
4. 128 bytes of data **MUST BE** loaded.

Software Protected Program Cycle Waveform



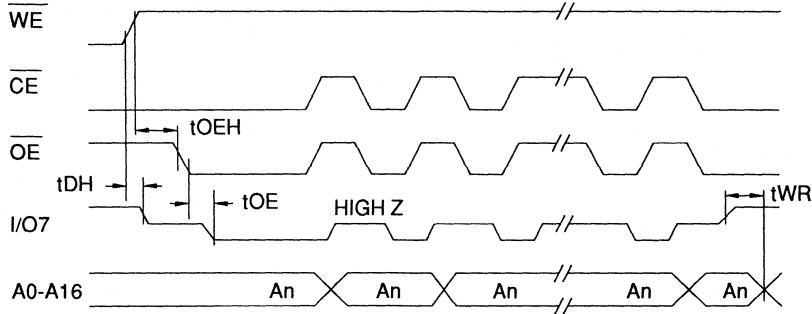
1. A7 through A16 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
2. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
3. All bytes that are not loaded within the sector being programmed will be erased to FF.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE_H}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

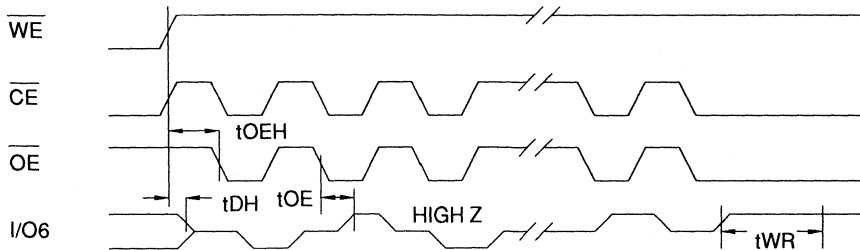


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE_H}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

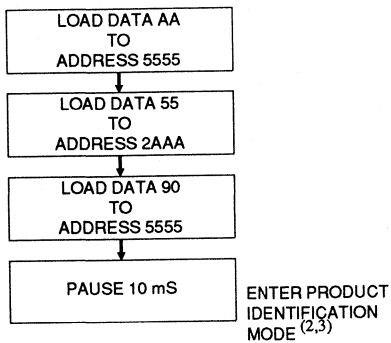
Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms

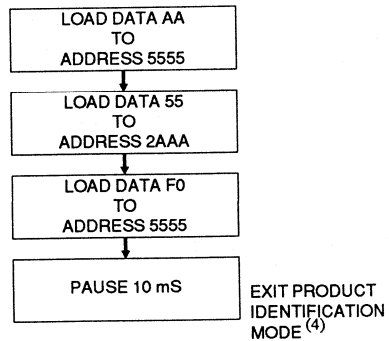


Notes:
 1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
 2. Beginning and ending state of I/O6 will vary.
 3. Any address location may be used but the address should not vary.

Software Product Identification Entry ⁽¹⁾



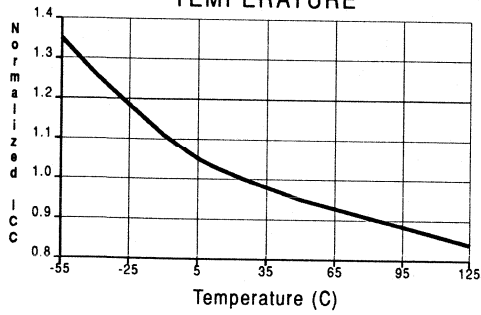
Software Product Identification Exit ⁽¹⁾



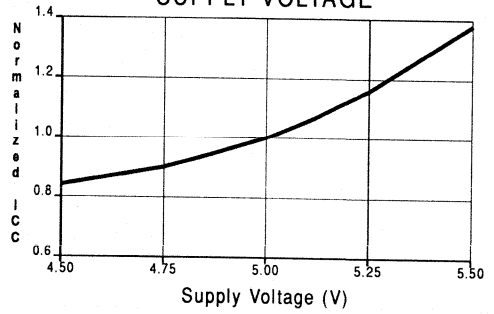
Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A16 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{III}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: D5

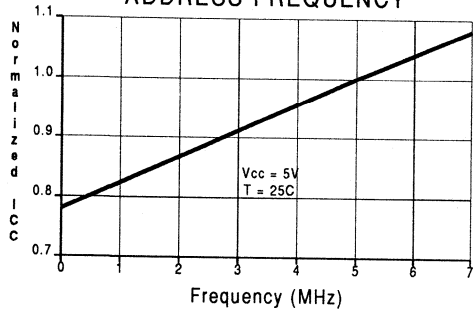
NORMALIZED SUPPLY CURRENT vs. TEMPERATURE



NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE



NORMALIZED SUPPLY CURRENT vs. ADDRESS FREQUENCY





Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
90	50	0.1	AT29C010-90DC	32D6	Commercial (0° to 70°C)
			AT29C010-90JC	32J	
			AT29C010-90LC	32L	
			AT29C010-90PC	32P6	
			AT29C010-90TC	32T	
90	50	0.3	AT29C010-90DI	32D6	Industrial (-40° to 85°C)
			AT29C010-90JI	32J	
			AT29C010-90LI	32L	
			AT29C010-90PI	32P6	
120	50	0.1	AT29C010-12DC	32D6	Commercial (0° to 70°C)
			AT29C010-12JC	32J	
			AT29C010-12LC	32L	
			AT29C010-12PC	32P6	
			AT29C010-12TC	32T	
120	50	0.3	AT29C010-12DI	32D6	Industrial (-40° to 85°C)
			AT29C010-12JI	32J	
			AT29C010-12LI	32L	
			AT29C010-12PI	32P6	Military (-55°C to 125°C)
			AT29C010-12DM	32D6	
			AT29C010-12LM	32L	
120	50	0.3	AT29C010-12DM/883	32D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)
			AT29C010-12LM/883	32L	
150	50	0.1	AT29C010-15DC	32D6	Commercial (0° to 70°C)
			AT29C010-15JC	32J	
			AT29C010-15LC	32L	
			AT29C010-15PC	32P6	
			AT29C010-15TC	32T	
150	50	0.3	AT29C010-15DI	32D6	Industrial (-40° to 85°C)
			AT29C010-15JI	32J	
			AT29C010-15LI	32L	
			AT29C010-15PI	32P6	Military (-55°C to 125°C)
			AT29C010-15DM	32D6	
			AT29C010-15LM	32L	
150	50	0.3	AT29C010-15DM/883	32D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)
			AT29C010-15LM/883	32L	
200	50	0.1	AT29C010-20DC	32D6	Commercial (0° to 70°C)
			AT29C010-20JC	32J	
			AT29C010-20LC	32L	
			AT29C010-20PC	32P6	
200	50	0.3	AT29C010-20DI	32D6	Industrial (-40° to 85°C)
			AT29C010-20JI	32J	
			AT29C010-20LI	32L	
			AT29C010-20PI	32P6	
			AT29C010-20DM	32D6	Military (-55°C to 125°C)
AT29C010-20LM	32L				

Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
200	50	0.3	AT29C010-20DM/883 AT29C010-20LM/883	32D6 32L	Military/883C Class B, Fully Compliant (-55°C to 125°C)

Package Type	
32D6	32 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)
32L	32 Pad, Non-Windowed, Ceramic Leadless Chip Carrier (LCC)
32P6	32 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
32T	32 Lead, Thin Small Outline Package (TSOP)





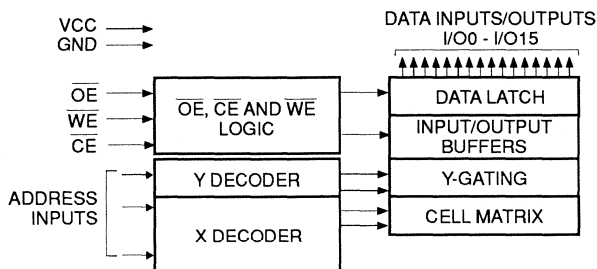
Description (Continued)

AT29C1024 is programmed on a sector basis; 128 words of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 128 words of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a program cycle,

the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7 or I/O15. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29C1024 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

DATA LOAD: Data loads are used to enter the 128 words of a sector to be programmed or the software codes for data protection. A data load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

PROGRAM: The device is reprogrammed on a sector basis. If a word of data within a sector is to be changed, data for the entire sector must be loaded into the device. Any word that is not loaded during the programming of its sector will be erased to read FFh. Once the words of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data word has been loaded into the device, successive words are entered in the same manner: Each new word to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) of the preceding word. If a high to low transition is not detected within 150 μs of the last low to high transition, the load period will end and the internal programming period will start. A7 to A15 specify the sector address. The sector address must be valid during each high to low transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$). A0 to A6 specify the word address within the

sector. The words may be loaded in any order; sequential loading is not required.

SOFTWARE DATA PROTECTION: A software controlled data protection feature is available on the AT29C1024. Once the software protection is enabled a software algorithm must be issued to the device before a program may be performed. The software protection feature may be enabled or disabled by the user; when shipped from Atmel, the software data protection feature is disabled. To enable the software data protection, a series of three program commands to specific addresses with specific data must be performed. After the software data protection is enabled the same three program commands must begin each program cycle in order for the programs to occur. All software program commands must obey the sector program timing specifications. Once set, software data protection will remain active unless the disable command sequence is issued. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

After setting SDP, any attempt to write to the device without the three-word command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc}, a read operation will effectively be a polling operation.

After the software data protection's three-word command code is given, a sector of data is loaded into the device using the sector programming timing specifications.

Device Operation (Continued)

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29C1024 in the following ways: (a) V_{CC} sense— if V_{CC} is below 3.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 5 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identification mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for various Flash densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

\overline{DATA} POLLING: The AT29C1024 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last word loaded will result in the complement of the loaded data on I/O7 and I/O15. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29C1024 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 and I/O14 toggling between one and zero. Once the program cycle has completed, I/O6 and I/O14 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-word software code or high voltage. For details, please contact Atmel.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to $V_{CC} + 0.6$ V
Voltage on \overline{OE} with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C_{IN}	4	6	pF	$V_{IN} = 0$ V
C_{OUT}	8	12	pF	$V_{OUT} = 0$ V

Note: 1. This parameter is characterized and is not 100% tested.



D.C. and A.C. Operating Range

		AT29C1024-70	AT29C1024-90	AT29C1024-12	AT29C1024-15
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
	Mil.			-55°C - 125°C	-55°C - 125°C
V _{CC} Power Supply		5 V ± 10%	5 V ± 10%	5 V ± 10%	5 V ± 10%

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	D _{OUT}
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	D _{IN}
5V Chip Erase	V _{IL}	V _{IH}	V _{IL}	Ai	
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A15 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A15 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_{IH} = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: 25

5. See details under Software Product Identification Entry/Exit.

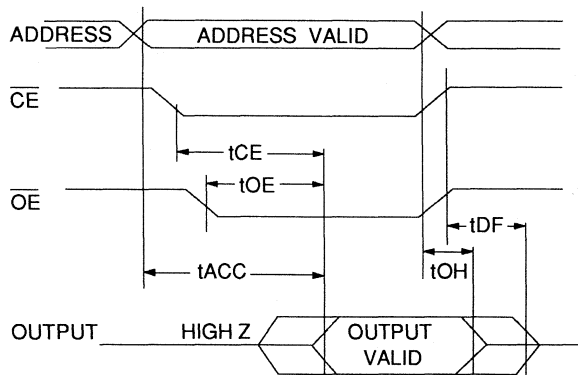
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		10	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		10	μA
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{CE} = V_{CC} - 0.3V$ to V _{CC}	Com.	400	μA
			Ind., Mil.	400	μA
I _{SB2}	V _{CC} Standby Current TTL	$\overline{CE} = 2.0 V$ to V _{CC}		3	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA		100	mA
V _{IL}	Input Low Voltage			0.8	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		.45	V
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	I _{OH} = -100 μA; V _{CC} = 4.5 V	4.2		V

A.C. Read Characteristics

Symbol	Parameter	AT29C1024-70		AT29C1024-90		AT29C1024-12		AT29C1024-15		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		70		90		120		150	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		70		90		120		150	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	35	0	45	0	60	0	70	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	25	0	25	0	30	0	40	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		0		0		ns

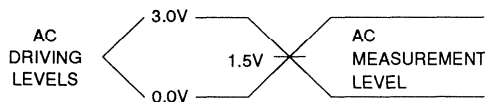
A.C. Read Waveforms



Notes:

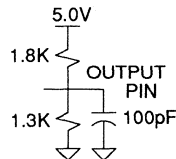
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5pF$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5 \text{ ns}$

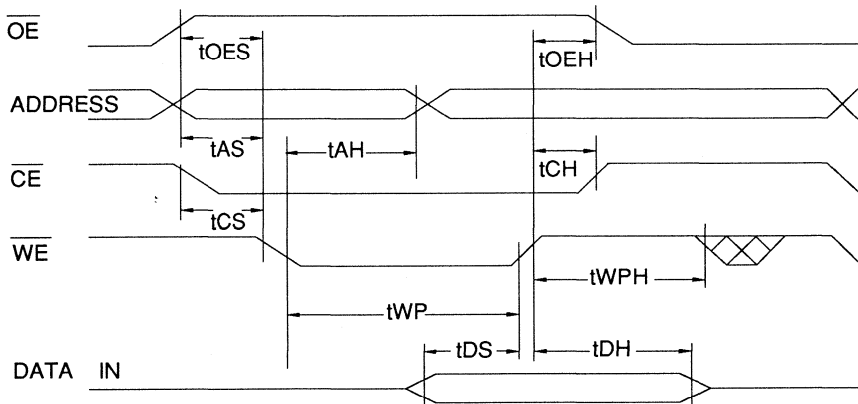
Output Test Load



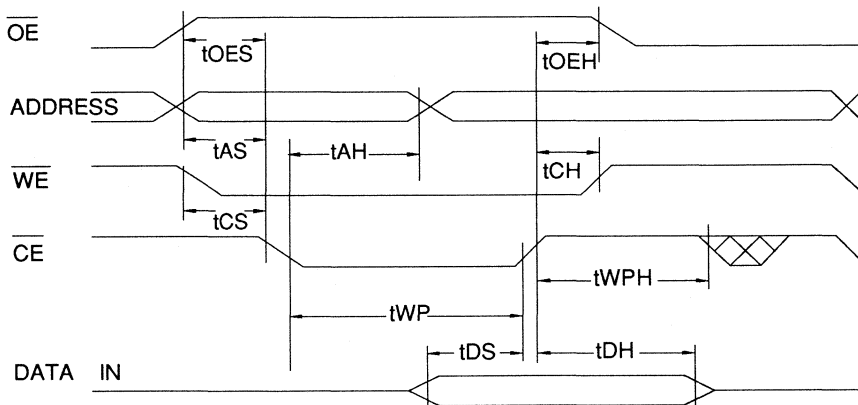
A.C. Word Load Characteristics

Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	0		ns
t_{AH}	Address Hold Time	50		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	70		ns
t_{DS}	Data Set-up Time	50		ns
t_{DH}, t_{OEH}	Data, \overline{OE} Hold Time	0		ns
t_{WPH}	Write Pulse Width High	100		ns

A.C. Word Load Waveforms- \overline{WE} Controlled



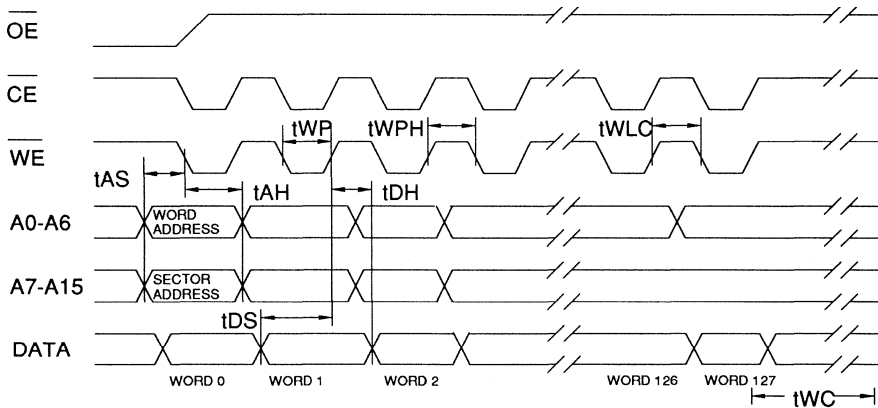
A.C. Word Load Waveforms- \overline{CE} Controlled



Program Cycle Characteristics

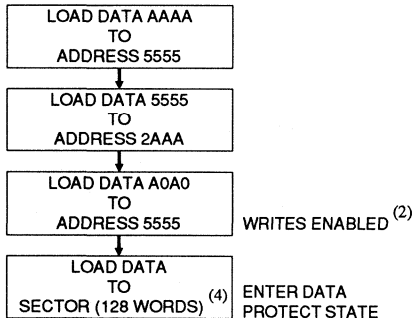
Symbol	Parameter	Min	Max	Units
t _{WC}	Write Cycle Time		10	ms
t _{AS}	Address Set-up Time	0		ns
t _{AH}	Address Hold Time	50		ns
t _{DS}	Data Set-up Time	50		ns
t _{DH}	Data Hold Time	0		ns
t _{WP}	Write Pulse Width	70		ns
t _{WLC}	Word Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	100		ns

Program Cycle Waveforms

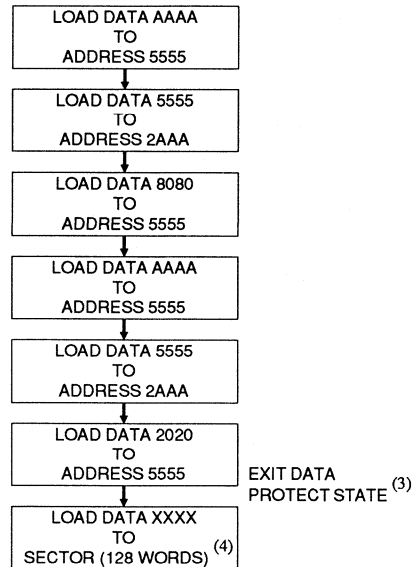


Notes: A7 through A15 must specify the sector address during each high to low transition of **WE** (or **CE**).
OE must be high when **WE** and **CE** are both low.
 All words that are not loaded within the sector being programmed will be erased to FF.

Software Data Protection Enable Algorithm ⁽¹⁾



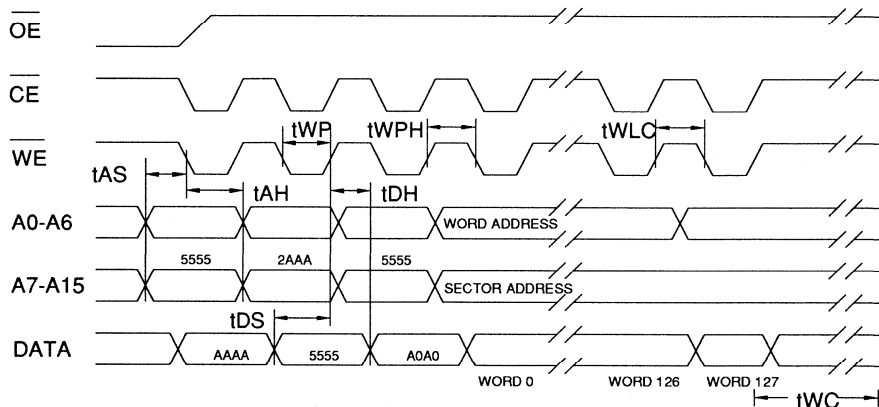
Software Data Protection Disable Algorithm ⁽¹⁾



Notes for software program code:

1. Data Format: I/O15 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Write Protect state will be activated at end of write period even if no other data is loaded.
3. Write Protect state will be deactivated at end of write period even if no other data is loaded.
4. 128 words of data **MUST BE** loaded.

Software Protected Program Cycle Waveform



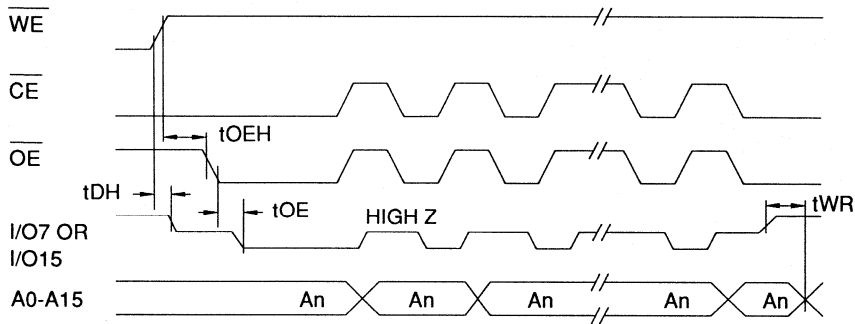
- Notes:
1. A7 through A15 must specify the same page address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
 2. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
 3. All words that are not loaded within the sector being programmed will be erased to FF.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	0			ns
t _{OEH}	\overline{OE} Hold Time	0			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

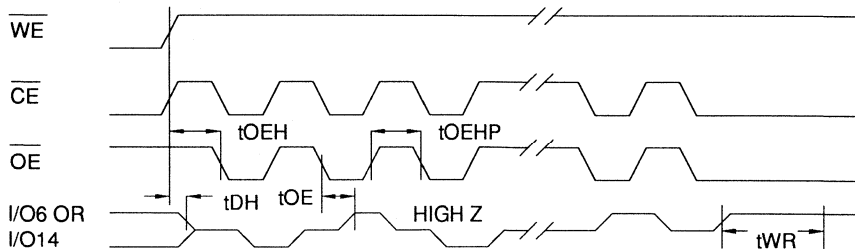


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OEH}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

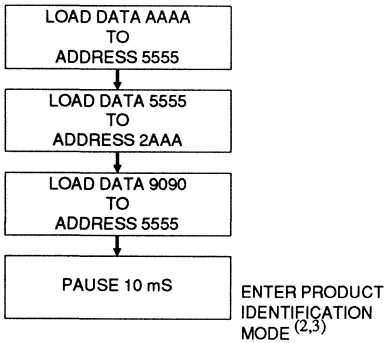
Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms

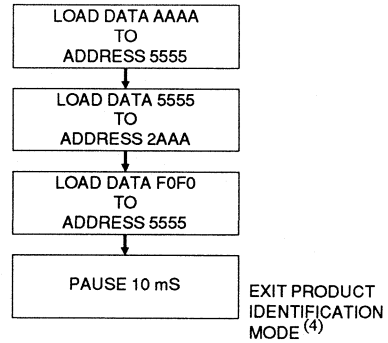


Notes:
 1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
 2. Beginning and ending state of I/O6 and I/O14 may vary.
 3. Any address location may be used but the address should not vary.

Software Product Identification Entry ⁽¹⁾



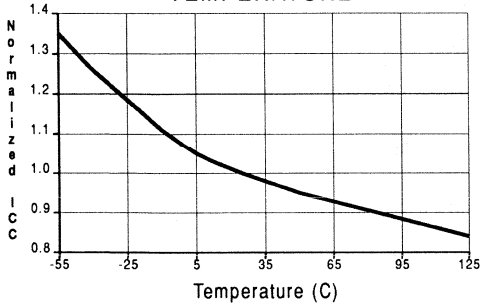
Software Product Identification Exit ⁽¹⁾



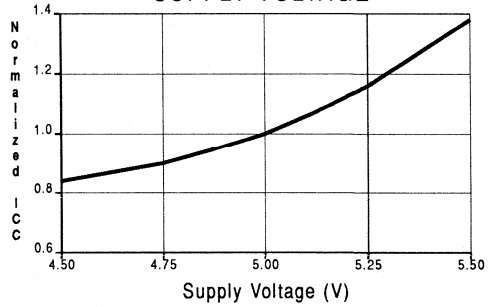
Notes for software product identification:

1. Data Format: I/O15 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A15 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: 25

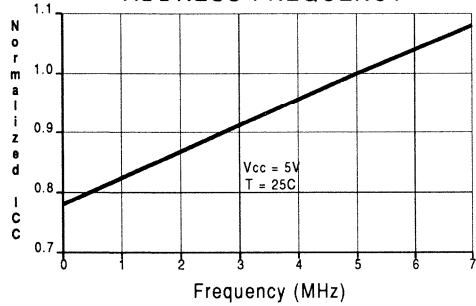
NORMALIZED SUPPLY CURRENT vs. TEMPERATURE



NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE



NORMALIZED SUPPLY CURRENT vs. ADDRESS FREQUENCY





Ordering Information

tACC (ns)	Icc (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
70	50	0.1	AT29C1024-70JC AT29C1024-70LC AT29C1024-70TC	44J 44L 48T	Commercial (0° to 70°C)
70	50	0.3	AT29C1024-70JI AT29C1024-70LI AT29C1024-70TI	44J 44L 48T	Industrial (-40° to 85°C)
90	50	0.1	AT29C1024-90JC AT29C1024-90LC AT29C1024-90TC	44J 44L 48T	Commercial (0° to 70°C)
90	50	0.3	AT29C1024-90JI AT29C1024-90LI AT29C1024-90TI	44J 44L 48T	Industrial (-40° to 85°C)
120	50	0.1	AT29C1024-12JC AT29C1024-12LC AT29C1024-12TC	44J 44L 48T	Commercial (0° to 70°C)
120	50	0.3	AT29C1024-12JI AT29C1024-12LI AT29C1024-12TI	44J 44L 48T	Industrial (-40° to 85°C)
			AT29C1024-12LM	44L	Military (-55°C to 125°C)
150	50	0.1	AT29C1024-15JC AT29C1024-15LC AT29C1024-15TC	44J 44L 48T	Commercial (0° to 70°C)
150	50	0.3	AT29C1024-15JI AT29C1024-15LI AT29C1024-15TI	44J 44L 48T	Industrial (-40° to 85°C)
			AT29C1024-15LM	44L	Military (-55°C to 125°C)

Package Type	
44J	44 Lead, Plastic J-Leaded Chip Carrier (PLCC)
44L	44 Lead, Non-Windowed, Ceramic Leadless Chip Carrier (LCC)
48T	48 Lead, Thin Small Outline Package (TSOP)

Features

- **Fast Read Access Time - 100 ns**
- **Five-Volt-Only Reprogramming**
- **Sector Program Operation**
 - Single Cycle Reprogram (Erase and Program)
 - 1024 Sectors (256 bytes/sector)
 - Internal Address and Data Latches for 256 Bytes
- **Internal Program Control and Timer**
- **Hardware and Software Data Protection**
- **2 - 16KB Boot Blocks with Lockout**
- **Fast Sector Program Cycle Time - 10 ms**
- **DATA Polling for End of Program Detection**
- **Low Power Dissipation**
 - 50 mA Active Current
 - 100 μ A CMOS Standby Current
- **High Reliability CMOS Technology**
 - 1000 Program Cycles per Sector
 - 10-Year Data Retention
- **Single 5 V \pm 10% Supply**
- **CMOS and TTL Compatible Inputs and Outputs**
- **Full Military, Commercial, and Industrial Temperature Ranges**

**2 Megabit
(256K x 8)
5-Volt Only
CMOS Flash
PEROM**

Preliminary

Description

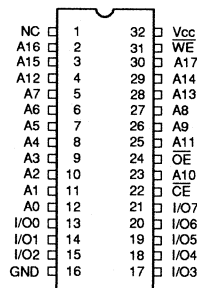
The AT29C020 is a five-volt-only in-system Flash Programmable and Erasable Read Only Memory (PEROM). Its two megabits of memory is organized as 262,144 bytes by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 100 ns with power dissipation of just 275 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than 100 μ A.

continued on next page

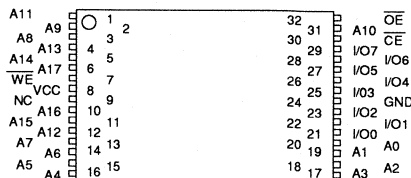
Pin Configurations

Pin Name	Function
A0 - A17	Addresses
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

DIP Top View



TSOP Top View
Type 1

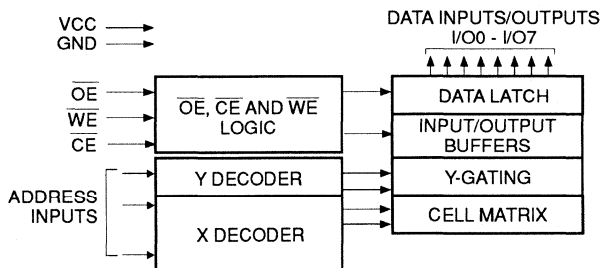


Description (Continued)

To allow for simple in-system reprogrammability, the AT29C020 does not require high input voltages for programming. Five-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT29C020 is performed on a sector basis; 256 bytes of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 256 bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29C020 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

BYTE LOAD: Byte loads are used to enter the 256 bytes of a sector to be programmed or the software codes for data protection. A byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

PROGRAM: The device is reprogrammed on a sector basis. If a byte of data within a sector is to be changed, data for the entire sector must be loaded into the device. Any byte that is not loaded during the programming of its sector will be erased to read FFh. Once the bytes of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) of the preceding byte. If a high to low transition is not detected within 150 μs of the last low to high transition, the load period will end and the internal programming period will start. A8 to A17 specify the sector address. The sector address must be valid during each high to low transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$). A0 to A7 specify the byte address within the sector. The

bytes may be loaded in any order; sequential loading is not required.

SOFTWARE DATA PROTECTION: A software controlled data protection feature is available on the AT29C020. Once the software protection is enabled a software algorithm must be issued to the device before a program may be performed. The software protection feature may be enabled or disabled by the user; when shipped from Atmel, the software data protection feature is disabled. To enable the software data protection, a series of three program commands to specific addresses with specific data must be performed. After the software data protection is enabled the same three program commands must begin each program cycle in order for the programs to occur. All software program commands must obey the sector program timing specifications. Once set, the software data protection feature remains active unless its disable command is issued. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

After setting SDP, any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc}, a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a sector of data is loaded into the device using the sector program timing specifications.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29C020 in the

Device Operation (Continued)

following ways: (a) V_{CC} sense— if V_{CC} is below 3.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 5 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identification mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for 256K to 4-megabit densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

DATA POLLING: The AT29C020 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29C020 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

BOOT BLOCK PROGRAMMING LOCKOUT: The AT29C020 has two designated memory blocks that have a programming lockout feature. This feature prevents programming of data in the designated block once the feature has been enabled. Each of these blocks consists of 16K bytes; the programming lockout feature can be set independently for either block. While the lockout feature does not have to be activated, it can be activated for either or both blocks.

These two 16K memory sections are referred to as *boot blocks*. Secure code which will bring up a system can be contained in a boot block. The AT29C020 blocks are located in the first 16K bytes of memory and the last 16K bytes of memory. The boot block programming lockout feature can therefore support systems that boot from the lower addresses of memory or the higher addresses. Once the programming lockout feature has been activated, the data in that block can no longer be erased or programmed; data in other memory locations can still be changed through the regular programming methods. To activate the lockout feature, a series of seven program commands to specific addresses with specific data must be performed. Please see Boot Block Lockout Feature Enable Algorithm.

If the boot block lockout feature has been activated on either block, the chip erase function will be disabled.

BOOT BLOCK LOCKOUT DETECTION: A software method is available to determine whether programming of either boot block section is locked out. See Software Product Identification Entry and Exit sections. When the device is in the software product identification mode, a read from location 00002H will show if programming the lower address boot block is locked out while reading location 1FFFFH will do so for the upper boot block. If the data is FE, the corresponding block can be programmed; if the data is FF, the program lockout feature has been activated and the corresponding block cannot be programmed. The software product identification exit mode should be used to return to standard operation.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to V_{CC} +0.6 V
Voltage on \overline{OE} with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.

This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. This parameter is characterized and is not 100% tested.

D.C. and A.C. Operating Range

		AT29C020-10	AT29C020-12	AT29C020-15	AT29C020-20
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
	Mil.			-55°C - 125°C	-55°C - 125°C
V _{CC} Power Supply		5 V ± 10%	5 V ± 10%	5 V ± 10%	5 V ± 10%

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	DOUT
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	DIN
5V Chip Erase	V _{IL}	V _{IH}	V _{IL}	Ai	
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A17 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A17 = V _{IL} , A9 = V _{IH} , A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_{IH} = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: DA

5. See details under Software Product Identification Entry/Exit.

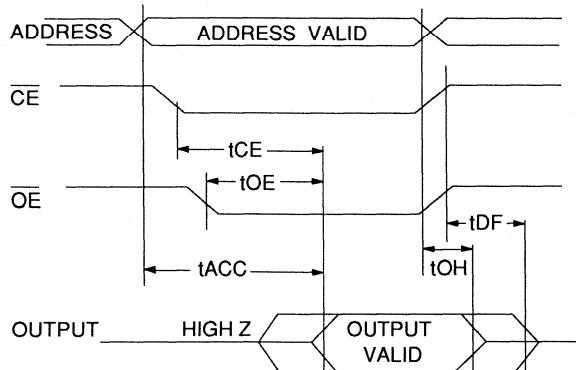
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		10	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		10	μA
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{CE} = V_{CC} - 0.3V$ to V _{CC}	Com.	100	μA
			Ind., Mil.	300	μA
I _{SB2}	V _{CC} Standby Current TTL	$\overline{CE} = 2.0 V$ to V _{CC}		3	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA		50	mA
V _{IL}	Input Low Voltage			0.8	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		.45	V
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	I _{OH} = -100 μA; V _{CC} = 4.5 V	4.2		V

A.C. Read Characteristics

Symbol	Parameter	AT29C020-10		AT29C020-12		AT29C020-15		AT29C020-20		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		100		120		150		200	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		100		120		150		200	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	50	0	50	0	70	0	80	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	25	0	30	0	40	0	50	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		0		0		ns

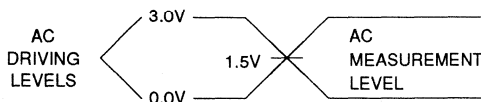
A.C. Read Waveforms



Notes:

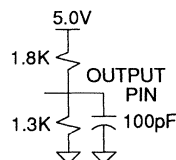
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5\text{pF}$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5\text{ ns}$

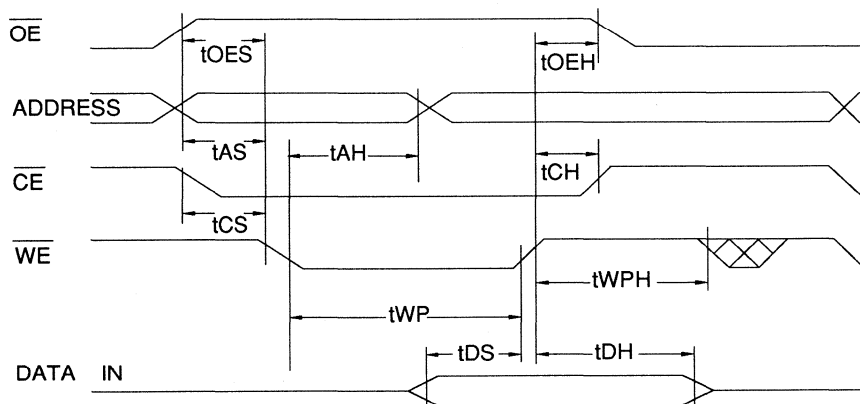
Output Test Load



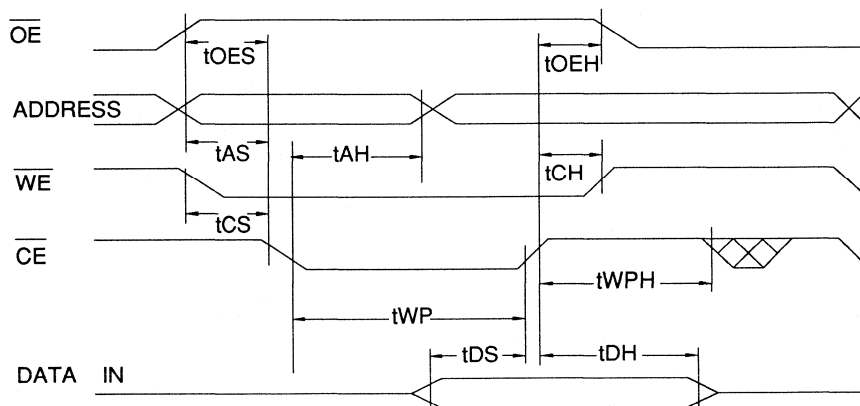
A.C. Byte Load Characteristics

Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	0		ns
t_{AH}	Address Hold Time	50		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	90		ns
t_{DS}	Data Set-up Time	50		ns
t_{DH}, t_{OEH}	Data, \overline{OE} Hold Time	0		ns
t_{WPH}	Write Pulse Width High	100		ns

A.C. Byte Load Waveforms- \overline{WE} Controlled



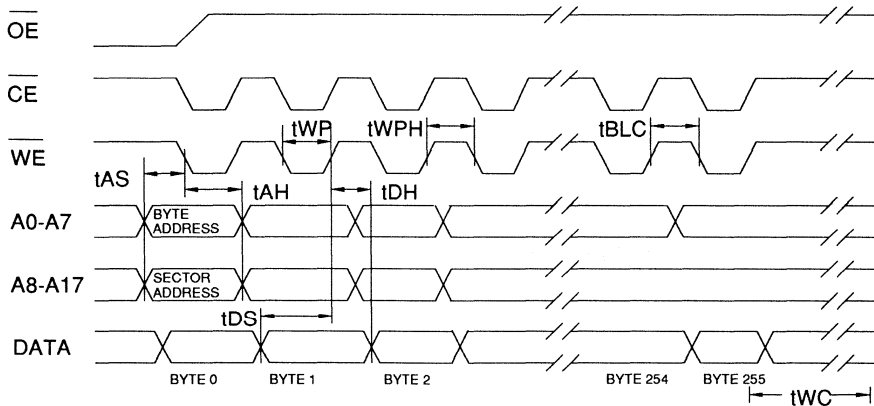
A.C. Byte Load Waveforms- \overline{CE} Controlled



Program Cycle Characteristics

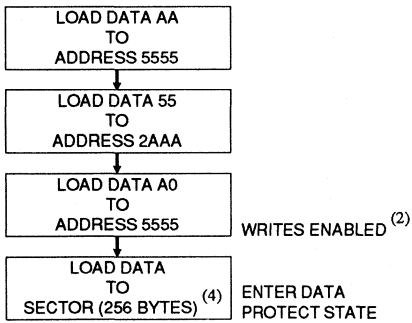
Symbol	Parameter	Min	Max	Units
t _{wc}	Write Cycle Time		10	ms
t _{AS}	Address Set-up Time	0		ns
t _{AH}	Address Hold Time	50		ns
t _{DS}	Data Set-up Time	50		ns
t _{DH}	Data Hold Time	0		ns
t _{WP}	Write Pulse Width	90		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	100		ns

Program Cycle Waveforms

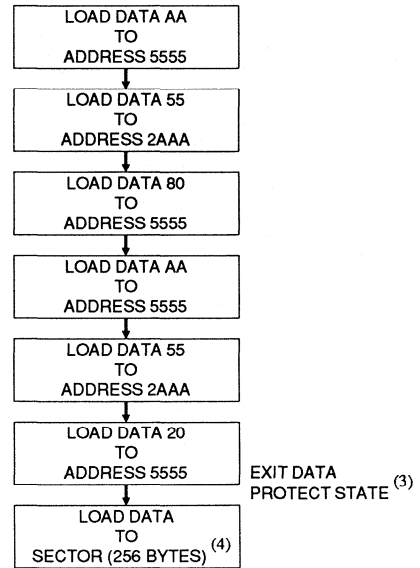


Notes: A8 through A17 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}).
 \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
All bytes that are not loaded within the sector being programmed will be erased to FF.

Software Data Protection Enable Algorithm ⁽¹⁾



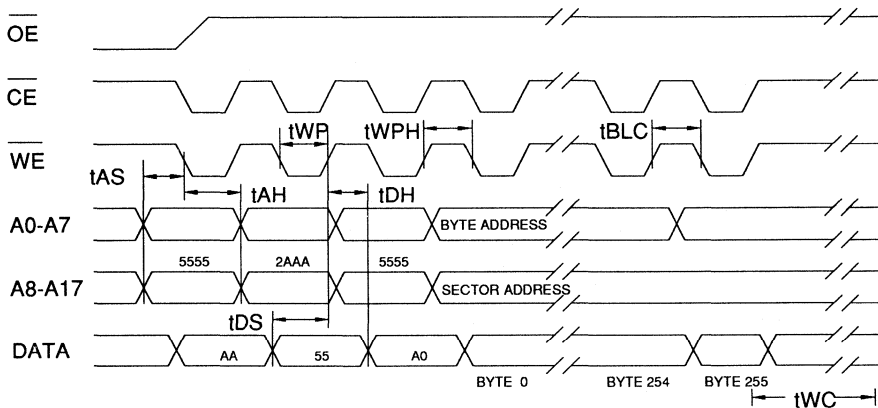
Software Data Protection Disable Algorithm ⁽¹⁾



Notes for software program code:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Data Protect state will be activated at end of program cycle.
3. Data Protect state will be deactivated at end of program period.
4. 256 bytes of data **MUST BE** loaded.

Software Protected Program Cycle Waveform



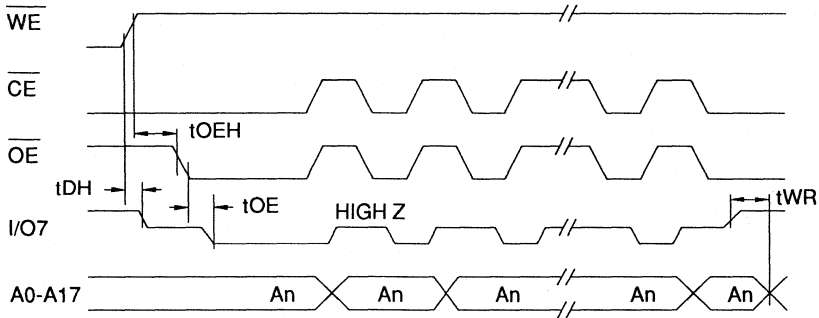
- Notes: 1. A8 through A17 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
2. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
3. All bytes that are not loaded within the sector being programmed will be erased to FF.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE_H}	$\overline{\text{OE}}$ Hold Time	10			ns
t _{OE}	$\overline{\text{OE}}$ to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics

Data Polling Waveforms

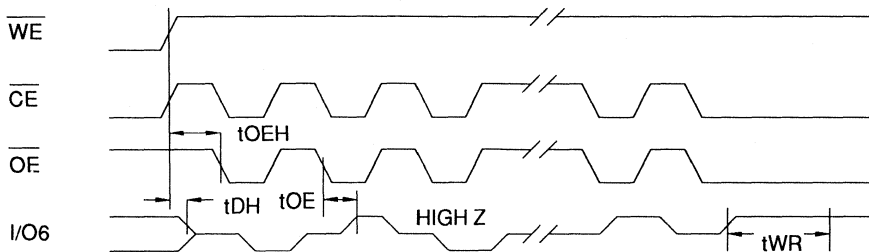


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE_H}	$\overline{\text{OE}}$ Hold Time	10			ns
t _{OE}	$\overline{\text{OE}}$ to Output Delay ⁽²⁾				ns
t _{OEHP}	$\overline{\text{OE}}$ High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

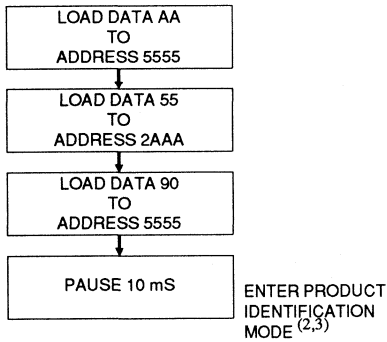
Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics

Toggle Bit Waveforms



Notes:
 1. Toggling either $\overline{\text{OE}}$ or $\overline{\text{CE}}$ or both $\overline{\text{OE}}$ and $\overline{\text{CE}}$ will operate toggle bit.
 2. Beginning and ending state of I/O6 will vary.
 3. Any address location may be used but the address should not vary.

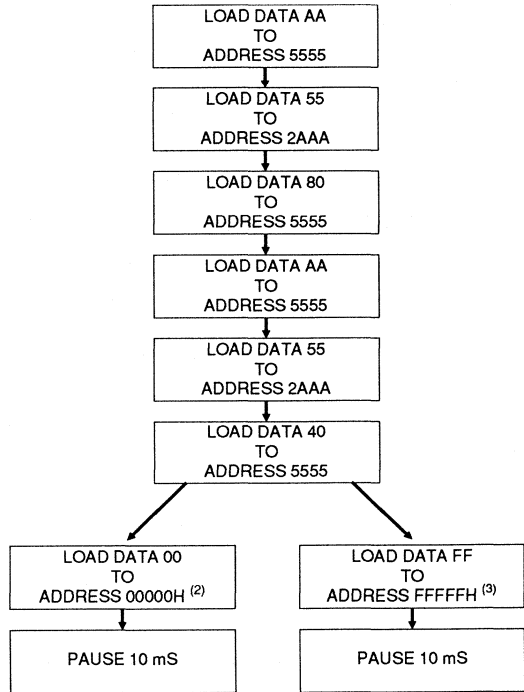
Software Product Identification Entry ⁽¹⁾



Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A17 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: DA

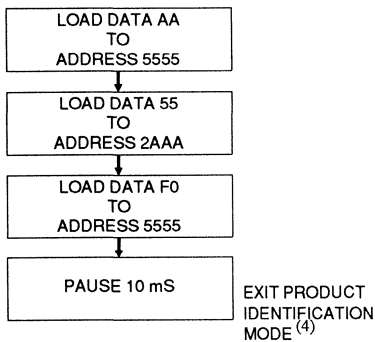
Boot Block Lockout Feature Enable Algorithm ⁽¹⁾



Notes for boot block lockout feature enable:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Lockout feature set on lower address boot block.
3. Lockout feature set on higher address boot block.

Software Product Identification Exit ⁽¹⁾



Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
100	50	0.1	AT29C020-10DC	32D6	Commercial (0° to 70°C)
			AT29C020-10PC	32P6	
			AT29C020-10TC	32T	
100	50	0.3	AT29C020-10DI	32D6	Industrial (-40° to 85°C)
			AT29C020-10PI	32P6	
			AT29C020-10TI	32T	
120	50	0.1	AT29C020-12DC	32D6	Commercial (0° to 70°C)
			AT29C020-12PC	32P6	
			AT29C020-12TC	32T	
120	50	0.3	AT29C020-12DI	32D6	Industrial (-40° to 85°C)
			AT29C020-12PI	32P6	
			AT29C020-12TI	32T	
150	50	0.1	AT29C020-15DC	32D6	Commercial (0° to 70°C)
			AT29C020-15PC	32P6	
			AT29C020-15TC	32T	
150	50	0.3	AT29C020-15DI	32D6	Industrial (-40° to 85°C)
			AT29C020-15PI	32P6	
			AT29C020-15TI	32T	
			AT29C020-15DM	32D6	
			AT29C020-15DM/883	32D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)
200	50	0.1	AT29C020-20DC	32D6	Commercial (0° to 70°C)
			AT29C020-20PC	32P6	
			AT29C020-20TC	32T	
200	50	0.3	AT29C020-20DI	32D6	Industrial (-40° to 85°C)
			AT29C020-20PI	32P6	
			AT29C020-20TI	32T	
			AT29C020-20DM	32D6	
			AT29C020-20DM/883	32D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)

Package Type	
32D6	32 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32P6	32 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
32T	32 Lead, Thin Small Outline Package (TSOP)



Features

- Fast Read Access Time - 120 ns
- Five-Volt-Only Reprogramming
- Sector Program Operation
 - Single Cycle Reprogram (Erase and Program)
 - 1024 Sectors (512 bytes/sector)
 - Internal Address and Data Latches for 512 Bytes
- Internal Program Control and Timer
- Hardware and Software Data Protection
- 2 - 16KB Boot Blocks with Lockout
- Fast Sector Program Cycle Time - 10 ms
- DATA Polling for End of Program Detection
- Low Power Dissipation
 - 50 mA Active Current
 - 100 μ A CMOS Standby Current
- High Reliability CMOS Technology
 - 1000 Program Cycles
 - 10-Year Data Retention
- Single 5 V \pm 10% Supply
- CMOS and TTL Compatible Inputs and Outputs

**4 Megabit
(512K x 8)
5-Volt Only
CMOS Flash
PEROM**

Description

The AT29C040 is a five-volt-only in-system Flash Programmable and Erasable Read Only Memory (PEROM). Its four megabit of memory is organized as 524,288 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 120 ns with power dissipation of just 275 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than 100 μ A. The programming algorithm is identical to other devices in Atmel's five-volt-only Flash PEROM family.

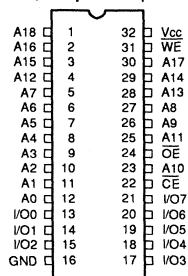
To allow for simple in-system reprogrammability, the AT29C040 does not require high input voltages for programming. Five-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the

continued on next page

Pin Configurations

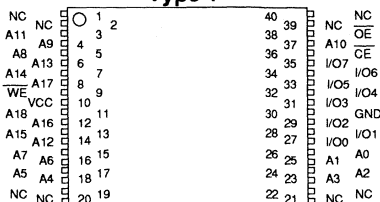
Pin Name	Function
A0 - A18	Addresses
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

DIP, Flatpack Top View



TSOP Top View

Type 1



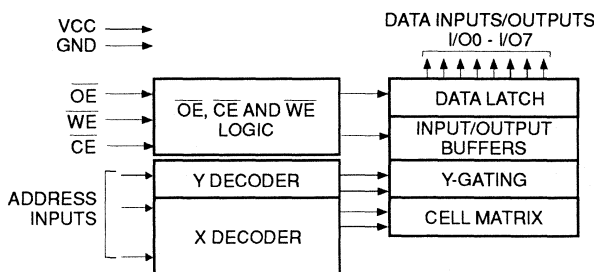
Description (Continued)

AT29C040 is performed on a sector basis; 512 bytes of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 512 bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a program cycle,

the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29C040 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

BYTE LOAD: Byte loads are used to enter the 512 bytes of a sector to be programmed or the software codes for data protection. A byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

PROGRAM: The device is reprogrammed on a sector basis. If a byte of data within a sector is to be changed, data for the entire sector must be loaded into the device. Any byte that is not loaded during the programming of its sector will be erased to read FFh. Once the bytes of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) of the preceding byte. If a high to low transition is not detected within 150 μs of the last low to high transition, the load period will end and the internal programming period will start. A9 to A18 specify the sector address. The sector address must be valid during each high to low transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$). A0 to A8 specify the byte address within the sector. The bytes may be loaded in any order; sequential loading is not required.

SOFTWARE DATA PROTECTION: A software controlled data protection feature is available on the AT29C040. Once the

software protection is enabled a software algorithm must be issued to the device before a program may be performed. The software protection feature may be enabled or disabled by the user; when shipped from Atmel, the software data protection feature is disabled. To enable the software data protection, a series of three program commands to specific addresses with specific data must be performed. After the software data protection is enabled the same three program commands must begin each program cycle in order for the programs to occur. All software program commands must obey the sector program timing specifications. Once set, the software data protection feature remains active unless its disable command is issued. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

After setting SDP, any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc}, a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$. The 512 bytes of data must be loaded into each sector by the same procedure as outlined in the program section under device operation.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29C040 in the following ways: (a) V_{CC} sense— if V_{CC} is below 3.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device

continued on next page

Device Operation (Continued)

will automatically time out 5 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identification mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for 256K to 4-megabit densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

\overline{DATA} POLLING: The AT29C040 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29C040 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

BOOT BLOCK PROGRAMMING LOCKOUT: The AT29C040 has two designated memory blocks that have a programming lockout feature. This feature prevents programming of data in the designated block once the feature has been enabled. Each of these blocks consists of 16K bytes; the programming lockout feature can be set independently for either block. While the lockout feature does not have to be activated, it can be activated for either or both blocks.

These two 16K memory sections are referred to as *boot blocks*. Secure code which will bring up a system can be contained in a boot block. The AT29C040 blocks are located in the first 16K bytes of memory and the last 16K bytes of memory. The boot block programming lockout feature can therefore support systems that boot from the lower addresses of memory or the higher addresses. Once the programming lockout feature has been activated, the data in that block can no longer be erased or programmed; data in other memory locations can still be changed through the regular programming methods. To activate the lockout feature, a series of seven program commands to specific addresses with specific data must be performed. Please see Boot Block Lockout Feature Enable Algorithm.

If the boot block lockout feature has been activated on either block, the chip erase function will be disabled.

BOOT BLOCK LOCKOUT DETECTION: A software method is available to determine whether programming of either boot block section is locked out. See Software Product Identification Entry and Exit sections. When the device is in the software product identification mode, a read from location 00002H will show if programming the lower address boot block is locked out while reading location 1FFFFH will do so for the upper boot block. If the data is FE, the corresponding block can be programmed; if the data is FF, the program lockout feature has been activated and the corresponding block cannot be programmed. The software product identification exit mode should be used to return to standard operation.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to $V_{CC} + 0.6 V$
Voltage on \overline{OE} with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. This parameter is characterized and is not 100% tested.

D.C. and A.C. Operating Range

		AT29C040-12	AT29C040-15	AT29C040-20
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
	Mil.		-55°C - 125°C	-55°C - 125°C
V _{CC} Power Supply		5 V ± 10%	5 V ± 10%	5 V ± 10%

Operating Modes

Mode	CE	OE	WE	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	DOUT
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	DIN
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A18 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A18 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_{IH} = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: 5B

5. See details under Software Product Identification Entry/Exit.

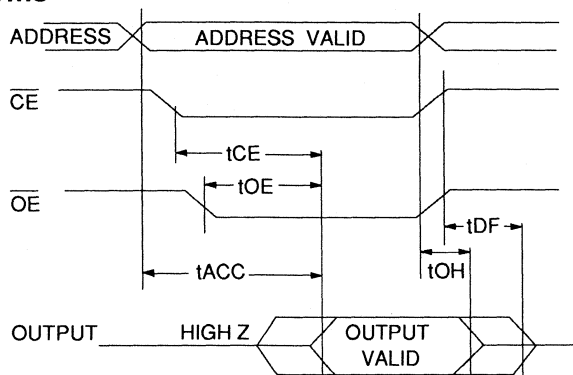
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		10	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		10	μA
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{\text{CE}} = V_{CC} - 0.3V$ to V _{CC}	Com.	100	μA
			Ind., Mil.	300	μA
I _{SB2}	V _{CC} Standby Current TTL	$\overline{\text{CE}} = 2.0V$ to V _{CC}		3	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA		50	mA
V _{IL}	Input Low Voltage			0.8	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		.45	V
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	I _{OH} = -100 μA; V _{CC} = 4.5 V	4.2		V

A.C. Read Characteristics

Symbol	Parameter	AT29C040-12		AT29C040-15		AT29C040-20		Units
		Min	Max	Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		120		150		200	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		120		150		200	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	50	0	70	0	80	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	30	0	40	0	50	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		0		ns

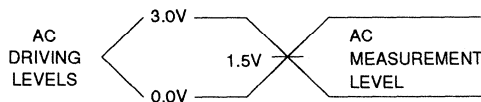
A.C. Read Waveforms



Notes:

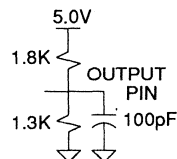
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5pF$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5$ ns

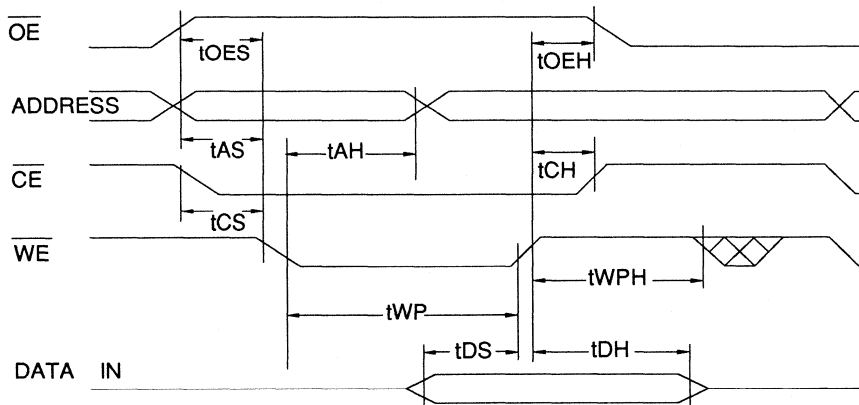
Output Test Load



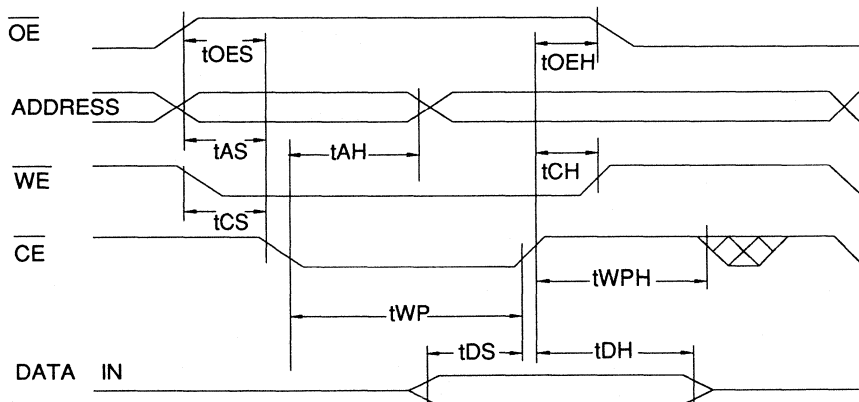
A.C. Byte Load Characteristics

Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	10		ns
t_{AH}	Address Hold Time	50		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	90		ns
t_{DS}	Data Set-up Time	50		ns
t_{DH}, t_{OEH}	Data, \overline{OE} Hold Time	10		ns
t_{WPH}	Write Pulse Width High	100		ns

A.C. Byte Load Waveforms- \overline{WE} Controlled



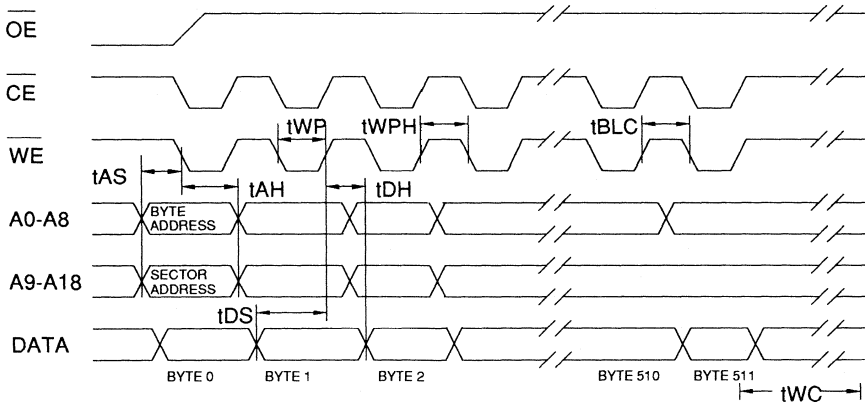
A.C. Byte Load Waveforms- \overline{CE} Controlled



Program Cycle Characteristics

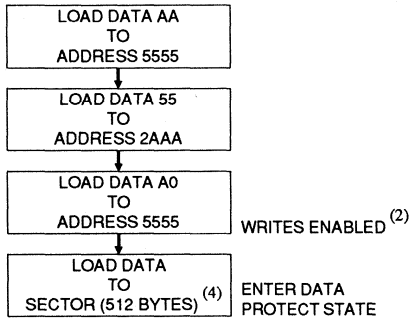
Symbol	Parameter	Min	Max	Units
t _{WC}	Write Cycle Time		10	ms
t _{AS}	Address Set-up Time	10		ns
t _{AH}	Address Hold Time	50		ns
t _{DS}	Data Set-up Time	50		ns
t _{DH}	Data Hold Time	10		ns
t _{WP}	Write Pulse Width	90		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	100		ns

Program Cycle Waveforms

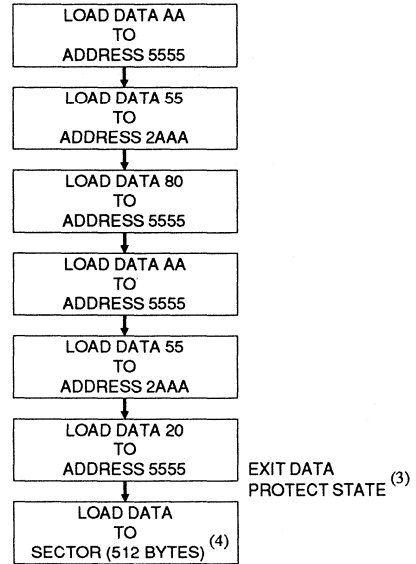


Notes: A9 through A18 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}).
 \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
All bytes that are not loaded within the sector being programmed will be erased to FF.

Software Data Protection Enable Algorithm ⁽¹⁾



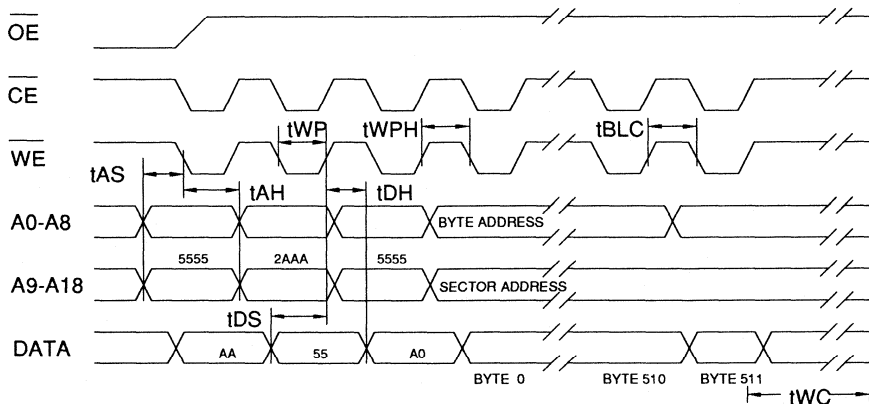
Software Data Protection Disable Algorithm ⁽¹⁾



Notes for software program code:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Data Protect state will be activated at end of program cycle.
3. Data Protect state will be deactivated at end of program period.
4. 512 bytes of data **MUST BE** loaded.

Software Protected Program Cycle Waveform



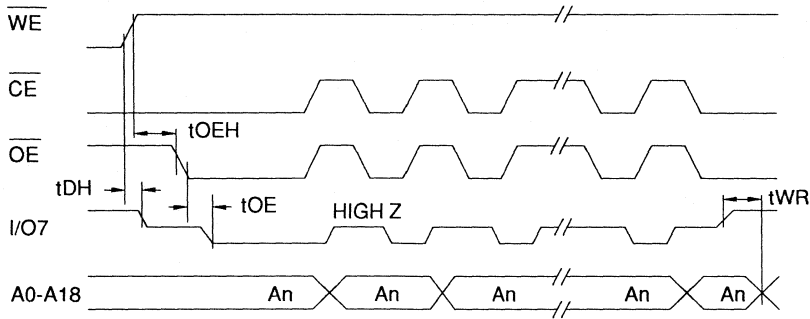
- Notes:
1. A9 through A18 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
 2. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
 3. All bytes that are not loaded within the sector being programmed will be erased to FF.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE\overline{H}}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

- Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

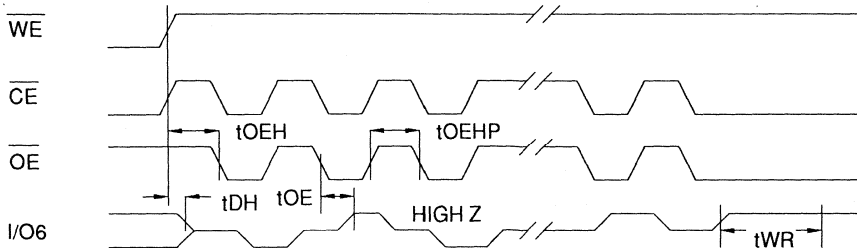


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE\overline{H}}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

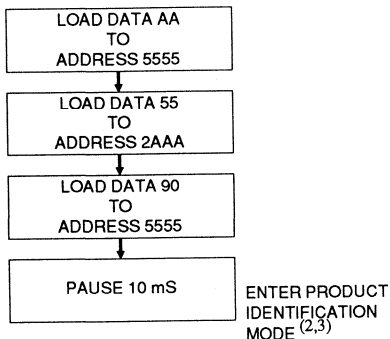
- Notes: 1. These parameters are characterized and not 100% tested.
 2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms



- Notes: 1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
 The t_{OEHP} specification must be met by the toggling input(s).
 2. Beginning and ending state of I/O6 will vary.
 3. Any address location may be used but the address should not vary.

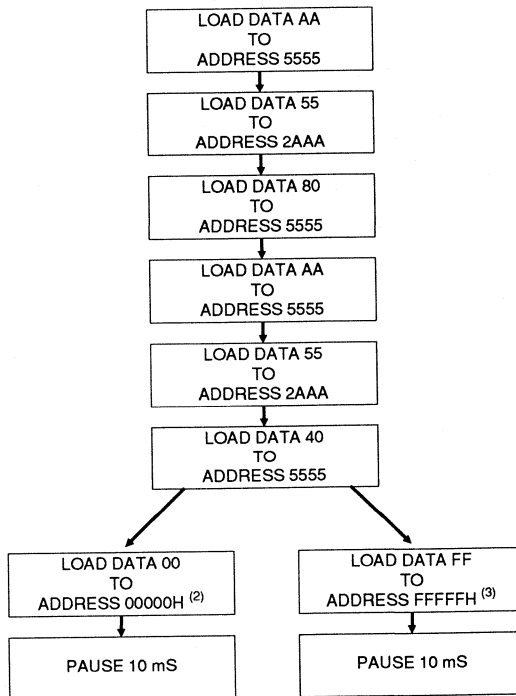
Software Product Identification Entry ⁽¹⁾



Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A18 = V_{IL}.
Manufacture Code is read for A0 = V_{II};
Device Code is read for A0 = V_{III}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: 5B

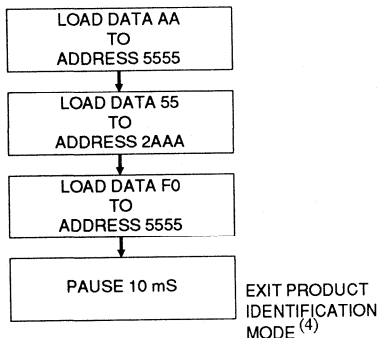
Boot Block Lockout Feature Enable Algorithm ⁽¹⁾



Notes for boot block lockout feature enable:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Lockout feature set on lower address boot block.
3. Lockout feature set on higher address boot block.

Software Product Identification Exit ⁽¹⁾



Ordering Information

tACC (ns)	Icc (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
120	50	0.1	AT29C040-12DC AT29C040-12PC AT29C040-12TC	32D6 32P6 40T	Commercial (0° to 70°C)
120	50	0.3	AT29C040-12DI AT29C040-12PI	32D6 32P6	Industrial (-40° to 85°C)
150	50	0.1	AT29C040-15DC AT29C040-15PC AT29C040-15TC	32D6 32P6 40T	Commercial (0° to 70°C)
150	50	0.3	AT29C040-15DI AT29C040-15FI AT29C040-15PI	32D6 32F 32P6	Industrial (-40° to 85°C)
			AT29C040-15DM AT29C040-15FM	32D6 32F	Military (-55°C to 125°C)
200	50	0.1	AT29C040-20DC AT29C040-20PC	32D6 32P6	Commercial (0° to 70°C)
200	50	0.3	AT29C040-20DI AT29C040-20FI AT29C040-20PI	32D6 32F 32P6	Industrial (-40° to 85°C)
			AT29C040-20DM AT29C040-20FM	32D6 32F	Military (-55°C to 125°C)

Package Type	
32D6	32 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32F	32 Lead, Non-Windowed, Ceramic Bottom-Brazed Flat Package (Flatpack)
32P6	32 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
40T	40 Lead, Thin Small Outline Package (TSOP)



Features

- Single 3.3 V ± 10% Supply
- Three-Volt-Only Read and Write Operation
- Software Protected Programming
- Low Power Dissipation
 - 15 mA Active Current
 - 20 μA CMOS Standby Current
- Fast Read Access Time - 200 ns
- Sector Program Operation
 - Single Cycle Reprogram (Erase and Program)
 - 512 Sectors (64 bytes/sector)
 - Internal Address and Data Latches for 64 Bytes
- Fast Sector Program Cycle Time - 20 ms Max.
- Internal Program Control and Timer
- DATA Polling for End of Program Detection
- High Reliability CMOS Technology
 - 1000 Program Cycles per Sector
 - 10-Year Data Retention
- CMOS and TTL Compatible Inputs and Outputs
- Commercial and Industrial Temperature Ranges

**256K (32K x 8)
3-Volt Only
CMOS Flash
PEROM**

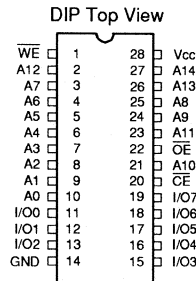
Description

The AT29LV256 is a three-volt-only in-system Flash Programmable Erasable Read Only Memory (PEROM). Its 256K of memory is organized as 32,768 words by 8 bits. Manufactured with Amel's advanced nonvolatile CMOS technology, the device offers access times to 200 ns with power dissipation of just 54 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than 20 μA.

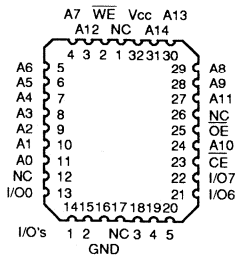
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Pin Configurations

Pin Name	Function
A0 - A14	Addresses
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

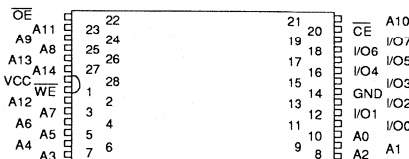


PLCC, LCC Top View



Note: PLCC package pins 1 and 17 are DON'T CONNECT.

TSOP Top View
Type 1



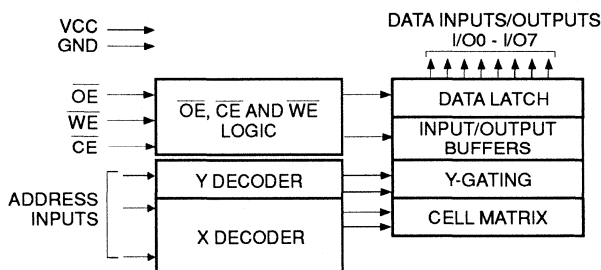
Description (Continued)

To allow for simple in-system reprogrammability, the AT29LV256 does not require high input voltages for programming. Three-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT29LV256 is performed on a sector basis; 64 bytes of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 64 bytes of data are captured at microprocessor speed and internally

latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29LV256 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

SOFTWARE DATA PROTECTION PROGRAMMING: The AT29LV256 has 512 individual sectors, each 64 bytes. Using the software data protection feature, byte loads are used to enter the 64 bytes of a sector to be programmed. The AT29LV256 can only be programmed or reprogrammed using the software data protection feature. The device is programmed on a sector basis. If a byte of data within the sector is to be changed, data for the entire 64-byte sector must be loaded into the device. The AT29LV256 automatically does a sector erase prior to loading the data into the sector. An erase command is not required.

Software data protection protects the device from inadvertent programming. A series of three program commands to specific addresses with specific data must be presented to the device before programming may occur. The same three program commands must begin each program operation. All software program commands must obey the sector program timing specifica-

tions. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

Any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wrc} , a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

The 64 bytes of data must be loaded into each sector. Any byte that is not loaded during the programming of its sector will be erased to read FFh. Once the bytes of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high tran-

continued on next page

Device Operation (Continued)

sition of \overline{WE} (or \overline{CE}) of the preceding byte. If a high to low transition is not detected within 150 μ s of the last low to high transition, the load period will end and the internal programming period will start. A6 to A14 specify the sector address. The sector address must be valid during each high to low transition of \overline{WE} (or \overline{CE}). A0 to A5 specify the byte address within the sector. The bytes may be loaded in any order; sequential loading is not required.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29LV256 in the following ways: (a) V_{CC} sense— if V_{CC} is below 1.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 10 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

INPUT LEVELS: While operating with a 3.3 V \pm 10% power supply, the address inputs and control inputs (\overline{OE} , \overline{CE} and \overline{WE}) may be driven from 0 to 5.5 V without adversely affecting the operation of the device. The I/O lines can only be driven from 0 to 3.6 volts.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In

addition, users may wish to use the software product identification mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for 256K to 4-megabit densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

DATA POLLING: The AT29LV256 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29LV256 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to V_{CC} +0.6 V
Voltage on A9 (including N.C. Pins) with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. These parameters are characterized and not 100% tested.



D.C. and A.C. Operating Range

		AT29LV256-20	AT29LV256-25
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C
Vcc Power Supply		3.3 V ± 0.3 V	3.3 V ± 0.3 V

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	DOUT
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	DIN
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A14 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A14 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_{IH} = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: BC.

5. See details under Software Product Identification Entry/Exit.

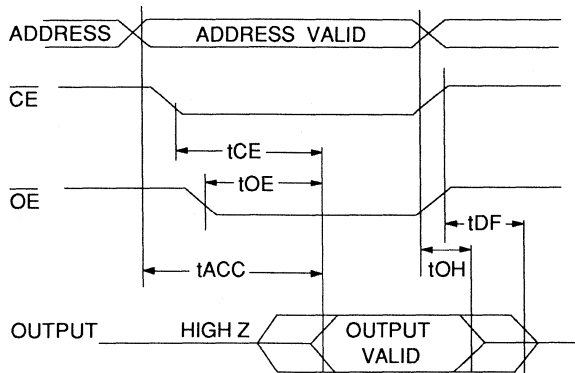
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		1	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		1	μA
I _{SB1}	Vcc Standby Current CMOS	$\overline{CE} = V_{CC} - 0.3 \text{ V to } V_{CC}$	Com.	20	μA
			Ind.	50	μA
I _{SB2}	Vcc Standby Current TTL	$\overline{CE} = 2.0 \text{ V to } V_{CC}$		1	mA
I _{CC}	Vcc Active Current	f = 5 MHz; I _{OUT} = 0 mA; V _{CC} = 3.6 V		15	mA
V _{IL}	Input Low Voltage			0.6	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 1.6 mA; V _{CC} = 3.0 V		.45	V
V _{OH}	Output High Voltage	I _{OH} = -100 μA; V _{CC} = 3.0 V	2.4		V

A.C. Read Characteristics

Symbol	Parameter	AT29LV256-20		AT29LV256-25		Units
		Min	Max	Min	Max	
t _{ACC}	Address to Output Delay		200		250	ns
t _{CE} ⁽¹⁾	\overline{CE} to Output Delay		200		250	ns
t _{OE} ⁽²⁾	\overline{OE} to Output Delay	0	100	0	120	ns
t _{DF} ^(3,4)	\overline{CE} or \overline{OE} to Output Float	0	50	0	60	ns
t _{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		ns

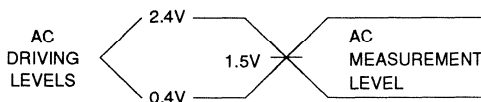
A.C. Read Waveforms



Notes:

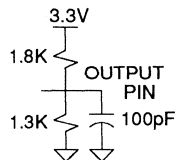
1. \overline{CE} may be delayed up to t_{ACC} - t_{CE} after the address transition without impact on t_{ACC}.
2. \overline{OE} may be delayed up to t_{CE} - t_{OE} after the falling edge of \overline{CE} without impact on t_{CE} or by t_{ACC} - t_{OE} after an address change without impact on t_{ACC}.
3. t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first (C_L = 5 pF).
4. This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



t_R, t_F < 5 ns

Output Test Load

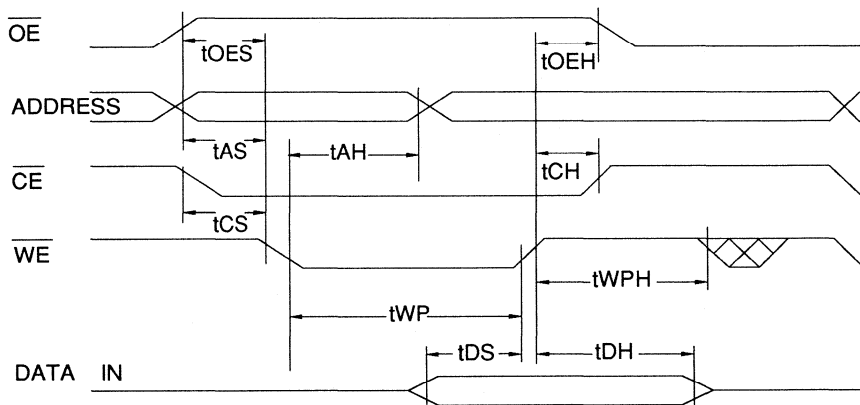


A.C. Byte Load Characteristics

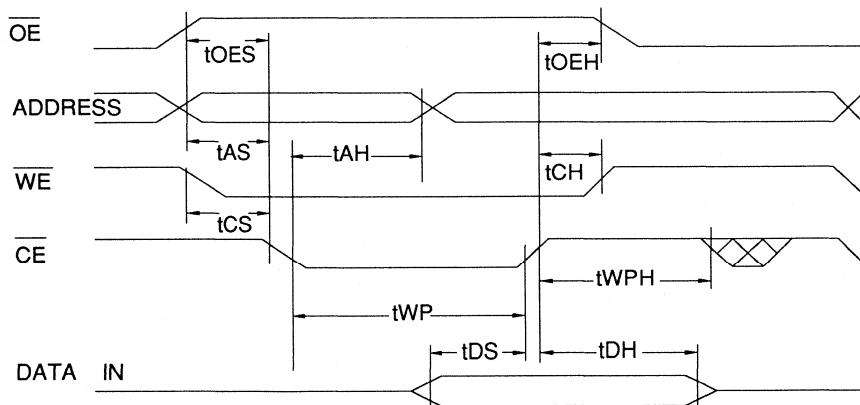
Symbol	Parameter	Min	Max	Units
tAS, tOES	Address, $\overline{\text{OE}}$ Set-up Time	10		ns
tAH	Address Hold Time	100		ns
tCS	Chip Select Set-up Time	0		ns
tCH	Chip Select Hold Time	0		ns
tWP	Write Pulse Width ($\overline{\text{WE}}$ or $\overline{\text{CE}}$)	200		ns
tDS	Data Set-up Time	100		ns
tDH, tOEH	Data, $\overline{\text{OE}}$ Hold Time	10		ns
tWPH	Write Pulse Width High	200		ns

A.C. Byte Load Waveforms ^(1,2)

$\overline{\text{WE}}$ Controlled



$\overline{\text{CE}}$ Controlled



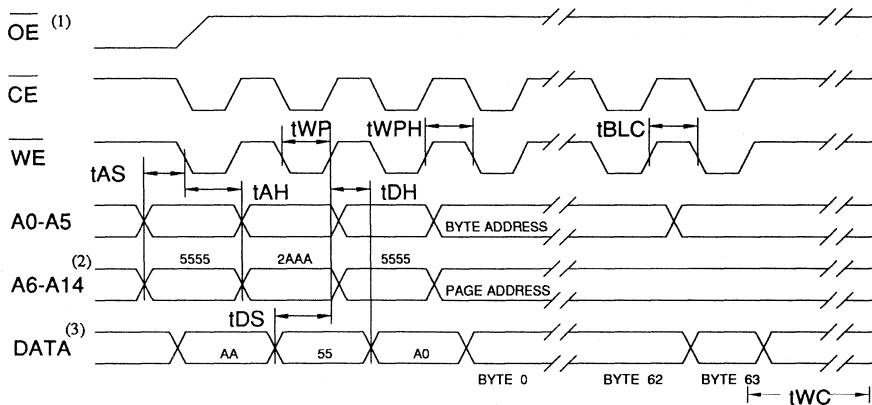
Notes:

1. The software data protection commands must be applied prior to byte loads.
2. A complete sector (64 bytes) should be loaded using these waveforms as shown in the Software Protected Byte Load waveforms (see previous page).

Program Cycle Characteristics

Symbol	Parameter	Min	Max	Units
t _{WC}	Write Cycle Time		20	ms
t _{AS}	Address Set-up Time	10		ns
t _{AH}	Address Hold Time	100		ns
t _{DS}	Data Set-up Time	100		ns
t _{DH}	Data Hold Time	10		ns
t _{WP}	Write Pulse Width	200		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	200		ns

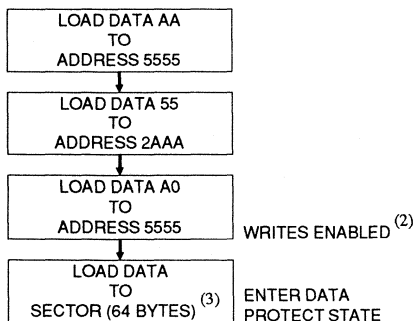
Software Protected Program Waveform



Notes:

1. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
2. A6 through A14 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
3. All bytes that are not loaded within the sector being programmed will be erased to FF.

Programming Algorithm ⁽¹⁾



Notes for software program code:

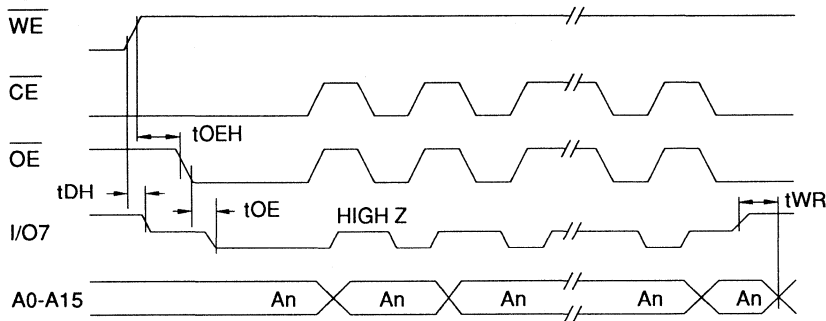
1. Data Format: I/O7-I/O0 (Hex); Address Format: A14-A0 (Hex).
2. Data Protect state will be re-activated at end of program cycle.
3. 64 bytes of data **MUST BE** loaded.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE}	$\overline{\text{OE}}$ Hold Time	10			ns
t _{OE}	$\overline{\text{OE}}$ to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

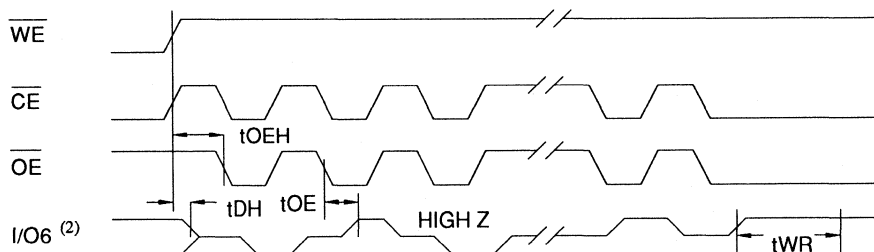


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE}	$\overline{\text{OE}}$ Hold Time	10			ns
t _{OE}	$\overline{\text{OE}}$ to Output Delay ⁽²⁾				ns
t _{OEHP}	$\overline{\text{OE}}$ High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms^(1,3)

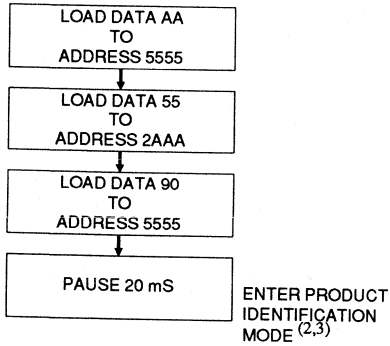


Notes:

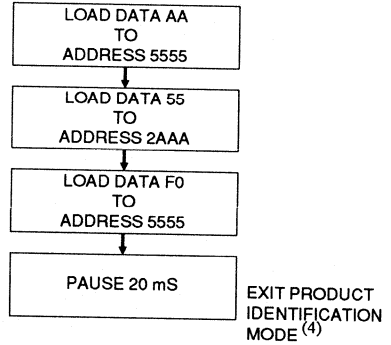
1. Toggling either $\overline{\text{OE}}$ or $\overline{\text{CE}}$ or both $\overline{\text{OE}}$ and $\overline{\text{CE}}$ will operate toggle bit.

2. Beginning and ending state of I/O6 will vary.
3. Any address location may be used but the address should not vary.

Software Product Identification Entry ⁽¹⁾



Software Product Identification Exit ⁽¹⁾



Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A14 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: BC



Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
200	15	0.02	AT29LV256-20DC AT29LV256-20JC AT29LV256-20PC AT29LV256-20TC	28D6 32J 28P6 28T	Commercial (0° to 70°C)
	15	0.05	AT29LV256-20DI AT29LV256-20JI AT29LV256-20PI	28D6 32J 28P6	Industrial (-40° to 85°C)
250	15	0.02	AT29LV256-25DC AT29LV256-25JC AT29LV256-25PC AT29LV256-25TC	28D6 32J 28P6 28T	Commercial (0° to 70°C)
	15	0.05	AT29LV256-25DI AT29LV256-25JI AT29LV256-25PI	28D6 32J 28P6	Industrial (-40° to 85°C)

Package Type	
28D6	28 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)
28P6	28 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
28T	28 Lead, Thin Small Outline Package (TSOP)

Features

- Single 3.3 V ± 10% Supply
- Three-Volt-Only Read and Write Operation
- Software Protected Programming
- Low Power Dissipation
 - 15 mA Active Current
 - 20 μA CMOS Standby Current
- Fast Read Access Time - 200 ns
- Sector Program Operation
 - Single Cycle Reprogram (Erase and Program)
 - 512 Sectors (128 bytes/sector)
 - Internal Address and Data Latches for 128 Bytes
- Fast Sector Program Cycle Time - 20 ms Max.
- Internal Program Control and Timer
- DATA Polling for End of Program Detection
- High Reliability CMOS Technology
 - 1000 Program Cycles per Sector
 - 10-Year Data Retention
- CMOS and TTL Compatible Inputs and Outputs
- Commercial and Industrial Temperature Ranges

**512K (64K x 8)
3-Volt Only
CMOS Flash
PEROM**

Description

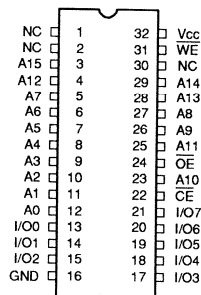
The AT29LV512 is a three-volt-only in-system Flash Programmable Erasable Read Only Memory (PEROM). Its 512K of memory is organized as 65,536 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 200 ns with power dissipation of just 54 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than 20 μA.

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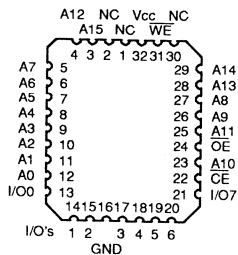
Pin Configurations

Pin Name	Function
A0 - A15	Addresses
CE	Chip Enable
OE	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

DIP Top View

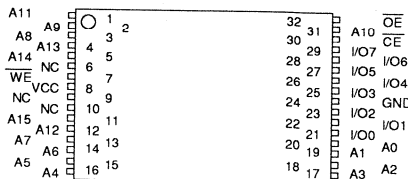


PLCC, LCC Top View



Note: PLCC package pin 30 is a DON'T CONNECT.

TSOP Top View
Type 1



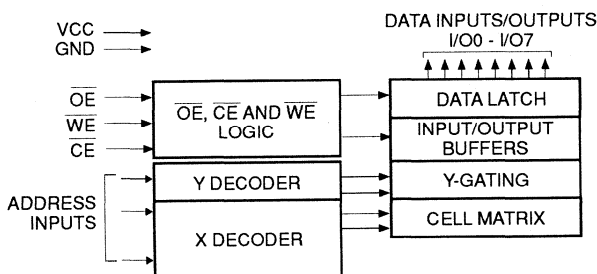
Description (Continued)

To allow for simple in-system reprogrammability, the AT29LV512 does not require high input voltages for programming. Three-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT29LV512 is performed on a sector basis; 128 bytes of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 128 bytes of data are captured at microprocessor speed and internally

latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29LV512 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

SOFTWARE DATA PROTECTION PROGRAMMING: The AT29LV512 has 512 individual sectors, each 128 bytes. Using the software data protection feature, byte loads are used to enter the 128 bytes of a sector to be programmed. The AT29LV512 can only be programmed or reprogrammed using the software data protection feature. The device is programmed on a sector basis. If a byte of data within the sector is to be changed, data for the entire 128-byte sector must be loaded into the device. The AT29LV512 automatically does a sector erase prior to loading the data into the sector. An erase command is not required.

Software data protection protects the device from inadvertent programming. A series of three program commands to specific addresses with specific data must be presented to the device before programming may occur. After writing the three-byte command sequence (and after t_{wc}), the entire device is protected. The same three program commands must begin each program operation. All software program commands must obey the sector program timing specifications. Power transitions will not

reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

Any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc} , a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

The 128 bytes of data must be loaded into each sector. Any byte that is not loaded during the programming of its sector will be erased to read FFh. Once the bytes of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) of the preceding byte. If a high to low transition is not detected within 150 μs of the last low to high

continued on next page

Device Operation (Continued)

transition, the load period will end and the internal programming period will start. A7 to A15 specify the sector address. The sector address must be valid during each high to low transition of \overline{WE} (or \overline{CE}). A0 to A6 specify the byte address within the sector. The bytes may be loaded in any order; sequential loading is not required.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29LV512 in the following ways: (a) V_{CC} sense— if V_{CC} is below 1.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 10 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

INPUT LEVELS: While operating with a 3.3 V $\pm 10\%$ power supply, the address inputs and control inputs (\overline{OE} , \overline{CE} and \overline{WE}) may be driven from 0 to 5.5 V without adversely affecting the operation of the device. The I/O lines can only be driven from 0 to 3.6 volts.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identifica-

tion mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for 256K to 4-megabit densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

DATA POLLING: The AT29LV512 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29LV512 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to $V_{CC} + 0.6$ V
Voltage on A9 (including N.C. Pins) with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. These parameters are characterized and not 100% tested.



D.C. and A.C. Operating Range

		AT29LV512-20	AT29LV512-25
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C
V _{CC} Power Supply		3.3 V ± 0.3 V	3.3 V ± 0.3 V

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	D _{OUT}
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	D _{IN}
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A15 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A15 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_{IH} = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: 3D.

5. See details under Software Product Identification Entry/Exit.

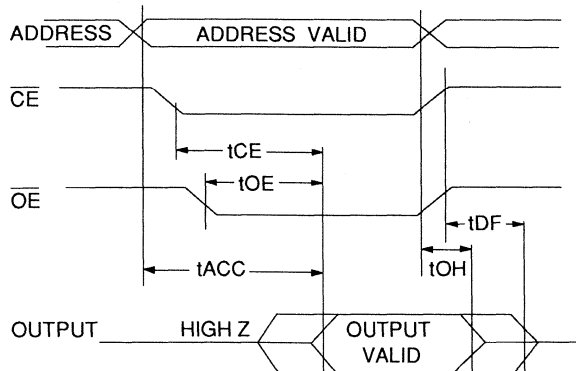
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		1	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		1	μA
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{CE} = V_{CC} - 0.3 \text{ V to } V_{CC}$	Com.	20	μA
			Ind.	50	μA
I _{SB2}	V _{CC} Standby Current TTL	$\overline{CE} = 2.0 \text{ V to } V_{CC}$		1	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA; V _{CC} = 3.6 V		15	mA
V _{IL}	Input Low Voltage			0.6	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 1.6 mA; V _{CC} = 3.0 V		.45	V
V _{OH}	Output High Voltage	I _{OH} = -100 μA; V _{CC} = 3.0 V	2.4		V

A.C. Read Characteristics

Symbol	Parameter	AT29LV512-20		AT29LV512-25		Units
		Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		200		250	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		200		250	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	100	0	120	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	50	0	60	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		ns

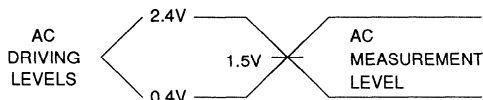
A.C. Read Waveforms



Notes:

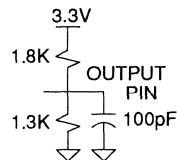
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5$ pF).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5$ ns

Output Test Load

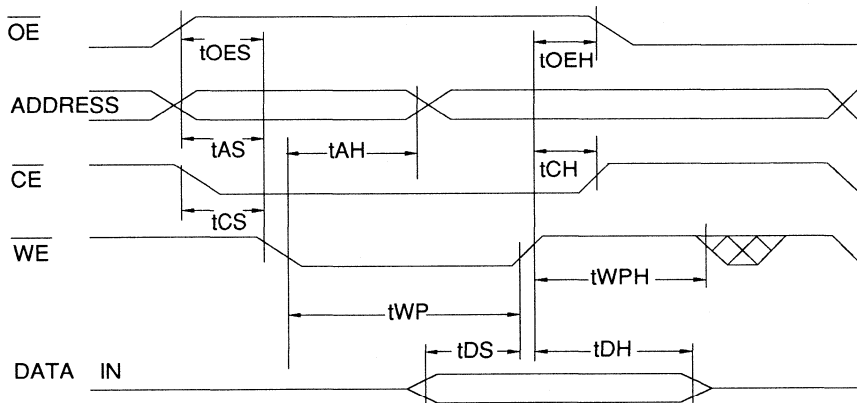


A.C. Byte Load Characteristics

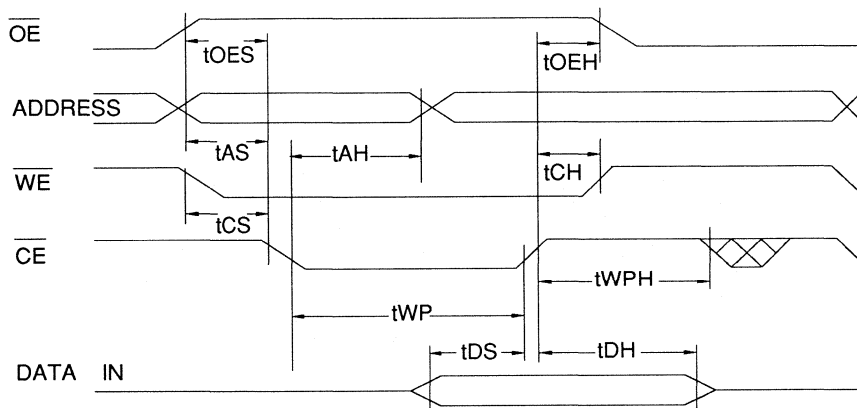
Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	10		ns
t_{AH}	Address Hold Time	100		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	200		ns
t_{DS}	Data Set-up Time	100		ns
t_{DH}, t_{OEH}	Data, \overline{OE} Hold Time	10		ns
t_{WPH}	Write Pulse Width High	200		ns

A.C. Byte Load Waveforms ^(1,2)

\overline{WE} Controlled



\overline{CE} Controlled



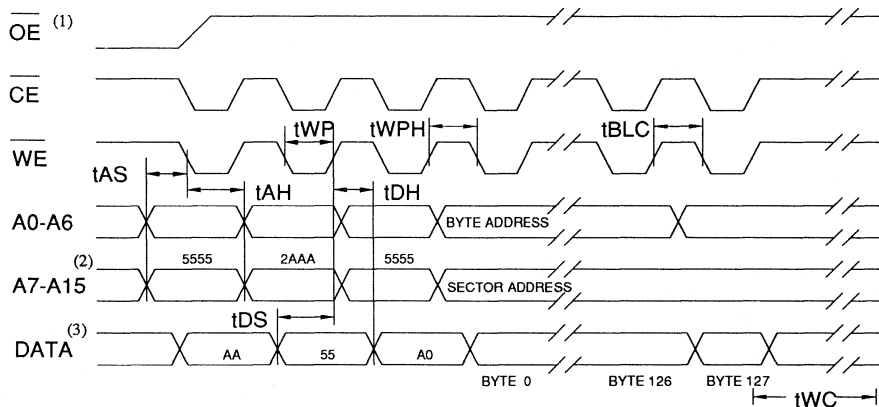
Notes:

1. The software data protection commands must be applied prior to byte loads.
2. A complete sector (128 bytes) should be loaded using these waveforms as shown in the Software Protected Byte Load waveforms (see previous page).

Program Cycle Characteristics

Symbol	Parameter	Min	Max	Units
t _{WC}	Write Cycle Time		20	ms
t _{AS}	Address Set-up Time	10		ns
t _{AH}	Address Hold Time	100		ns
t _{DS}	Data Set-up Time	100		ns
t _{DH}	Data Hold Time	10		ns
t _{WP}	Write Pulse Width	200		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	200		ns

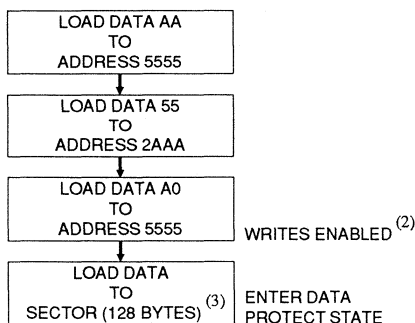
Software Protected Program Waveform



Notes:

1. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
2. A7 through A15 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
3. All bytes that are not loaded within the sector being programmed will be erased to FF.

Programming Algorithm ⁽¹⁾



Notes for software program code:

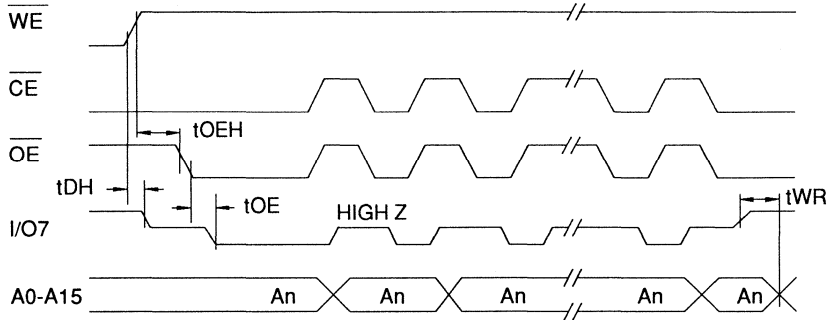
1. Data Format: I/O7-I/O0 (Hex); Address Format: A14-A0 (Hex).
2. Data Protect state will be re-activated at end of program cycle.
3. 128 bytes of data **MUST BE** loaded.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OEH}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

- Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

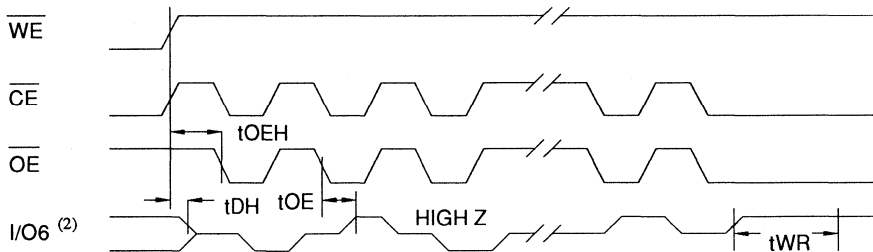


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OEH}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

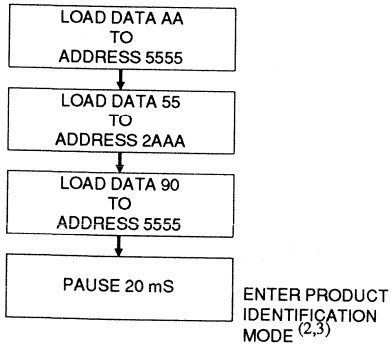
- Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms^(1,3)

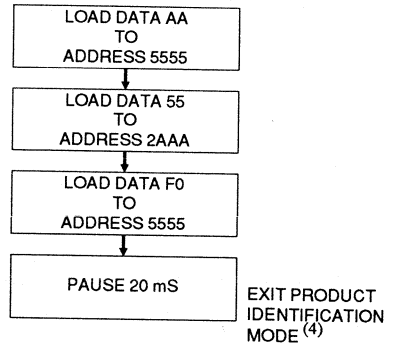


- Notes: 1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
2. Beginning and ending state of I/O6 will vary.
3. Any address location may be used but the address should not vary.

Software Product Identification Entry ⁽¹⁾



Software Product Identification Exit ⁽¹⁾



Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A15 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: 3D



Ordering Information

tACC (ns)	Icc (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
200	15	0.02	AT29LV512-20DC AT29LV512-20JC AT29LV512-20PC	32D6 32J 32P6	Commercial (0° to 70°C)
	15	0.05	AT29LV512-20DI AT29LV512-20JI AT29LV512-20PI AT29LV512-20TI	32D6 32J 32P6 32T	Industrial (-40° to 85°C)
250	15	0.02	AT29LV512-25DC AT29LV512-25JC AT29LV512-25PC	32D6 32J 32P6	Commercial (0° to 70°C)
	15	0.05	AT29LV512-25DI AT29LV512-25JI AT29LV512-25PI AT29LV512-25TI	32D6 32J 32P6 32T	Industrial (-40° to 85°C)

Package Type

32D6	32 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)
32P6	32 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
32T	32 Lead, Thin Small Outline Package (TSOP)

Features

- Single 3.3 V \pm 10% Supply
- Three-Volt-Only Read and Write Operation
- Software Protected Programming
- Low Power Dissipation
 - 15 mA Active Current
 - 20 μ A CMOS Standby Current
- Fast Read Access Time - 200 ns
- Sector Program Operation
 - Single Cycle Reprogram (Erase and Program)
 - 1024 Sectors (128 bytes/sector)
 - Internal Address and Data Latches for 128 Bytes
- Fast Sector Program Cycle Time - 20 ms Max.
- Internal Program Control and Timer
- DATA Polling for End of Program Detection
- High Reliability CMOS Technology
 - 1000 Program Cycles per Sector
 - 10-Year Data Retention
- CMOS and TTL Compatible Inputs and Outputs
- Commercial and Industrial Temperature Ranges

**1 Megabit
(128K x 8)
3-Volt Only
CMOS Flash
PEROM**

Description

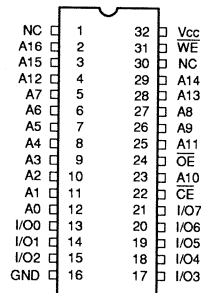
The AT29LV010 is a three-volt-only in-system Flash Programmable Erasable Read Only Memory (PEROM). Its one megabit of memory is organized as 131,072 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 200 ns with power dissipation of just 54 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than 20 μ A.

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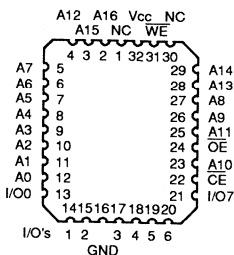
Pin Configurations

Pin Name	Function
A0 - A16	Addresses
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

DIP Top View

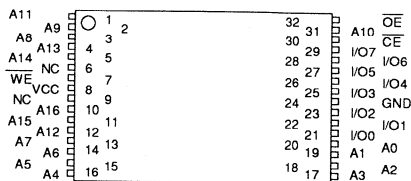


PLCC, LCC Top View



Note: PLCC package pin 30 is a DON'T CONNECT.

TSOP Top View
Type 1



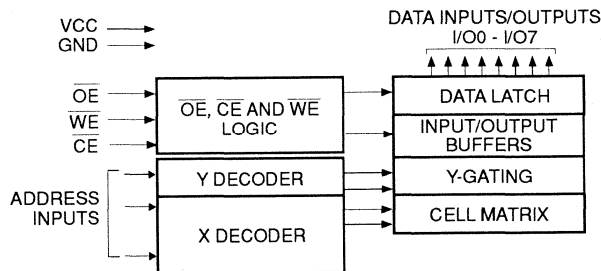
Description (Continued)

To allow for simple in-system reprogrammability, the AT29LV010 does not require high input voltages for programming. Three-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT29LV010 is performed on a sector basis; 128 bytes of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 128 bytes of data are captured at microprocessor speed and internally

latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29LV010 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

SOFTWARE DATA PROTECTION PROGRAMMING: The AT29LV010 has 1024 individual sectors, each 128 bytes. Using the software data protection feature, byte loads are used to enter the 128 bytes of a sector to be programmed. The AT29LV010 can only be programmed or reprogrammed using the software data protection feature. The device is programmed on a sector basis. If a byte of data within the sector is to be changed, data for the entire 128-byte sector must be loaded into the device. The AT29LV010 automatically does a sector erase prior to loading the data into the sector. An erase command is not required.

Software data protection protects the device from inadvertent programming. A series of three program commands to specific addresses with specific data must be presented to the device before programming may occur. The same three program commands must begin each program operation. All software program commands must obey the sector program timing specifications. Power transitions will not reset the software data protec-

tion feature, however the software feature will guard against inadvertent program cycles during power transitions.

Any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wrc} , a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

The 128 bytes of data must be loaded into each sector. Any byte that is not loaded during the programming of its sector will be erased to read FFh. Once the bytes of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) of the preceding byte. If a high to low transition is not detected within 150 μs of the last low to high transition, the load period will end and the internal program-

continued on next page

Device Operation (Continued)

ming period will start. A7 to A16 specify the sector address. The sector address must be valid during each high to low transition of \overline{WE} (or \overline{CE}). A0 to A6 specify the byte address within the sector. The bytes may be loaded in any order; sequential loading is not required.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29LV010 in the following ways: (a) V_{CC} sense— if V_{CC} is below 1.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 10 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

INPUT LEVELS: While operating with a 3.3 V $\pm 10\%$ power supply, the address inputs and control inputs (\overline{OE} , \overline{CE} and \overline{WE}) may be driven from 0 to 5.5 V without adversely affecting the operation of the device. The I/O lines can only be driven from 0 to 3.6 volts.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identifica-

tion mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for 256K to 4-megabit densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

DATA POLLING: The AT29LV010 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29LV010 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to $V_{CC} + 0.6 V$
Voltage on A9 (including N.C. Pins) with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. These parameters are characterized and not 100% tested.



D.C. and A.C. Operating Range

		AT29LV010-20	AT29LV010-25
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C
V _{CC} Power Supply		3.3 V ± 0.3 V	3.3 V ± 0.3 V

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	AI	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	D _{OUT}
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	D _{IN}
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A16 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A16 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_H = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: 35.

5. See details under Software Product Identification Entry/Exit.

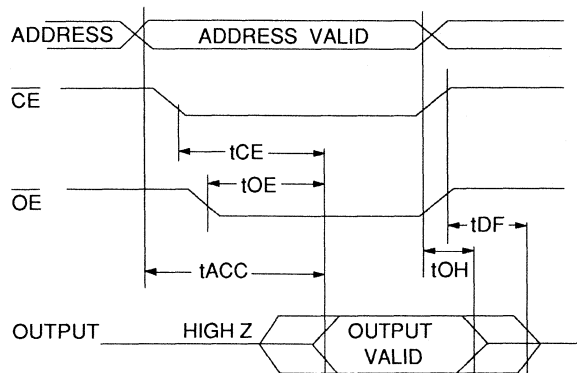
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		1	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		1	μA
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{CE} = V_{CC} - 0.3 \text{ V to } V_{CC}$	Com.	20	μA
			Ind.	50	μA
I _{SB2}	V _{CC} Standby Current TTL	$\overline{CE} = 2.0 \text{ V to } V_{CC}$		1	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA; V _{CC} = 3.6 V		15	mA
V _{IL}	Input Low Voltage			0.6	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 1.6 mA; V _{CC} = 3.0 V		.45	V
V _{OH}	Output High Voltage	I _{OH} = -100 μA; V _{CC} = 3.0 V	2.4		V

A.C. Read Characteristics

Symbol	Parameter	AT29LV010-20		AT29LV010-25		Units
		Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		200		250	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		200		250	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	100	0	120	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	50	0	60	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		ns

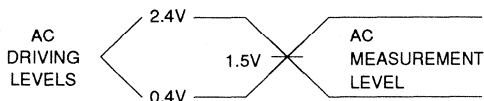
A.C. Read Waveforms



Notes:

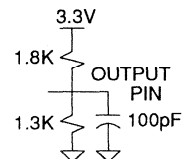
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5\text{pF}$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_r, t_f < 5 \text{ ns}$

Output Test Load

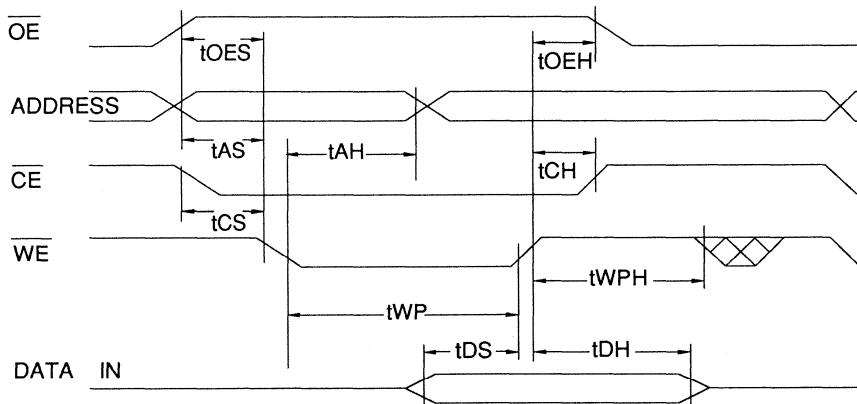


A.C. Byte Load Characteristics

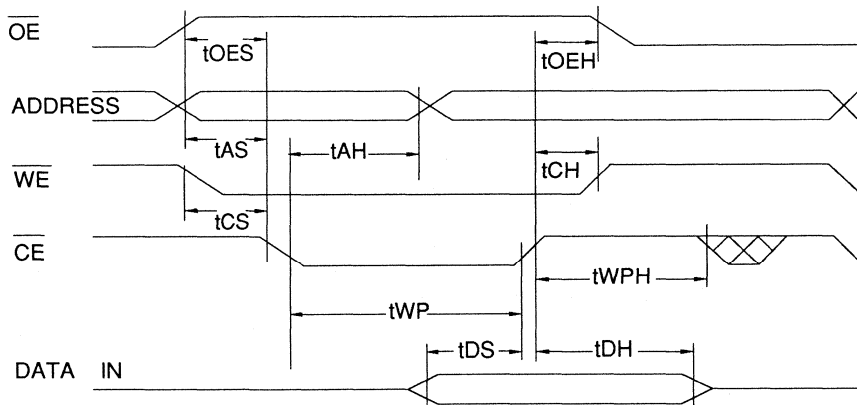
Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	10		ns
t_{AH}	Address Hold Time	100		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	200		ns
t_{DS}	Data Set-up Time	100		ns
t_{DH}, t_{OEH}	Data, \overline{OE} Hold Time	10		ns
t_{WPH}	Write Pulse Width High	200		ns

A.C. Byte Load Waveforms ^(1,2)

WE Controlled



\overline{CE} Controlled



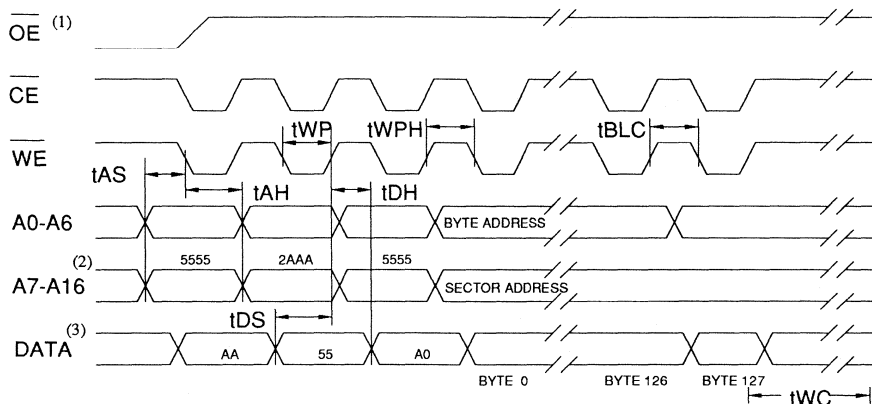
Notes:

1. The software data protection commands must be applied prior to byte loads.
2. A complete sector (128 bytes) should be loaded using these waveforms as shown in the Software Protected Byte Load waveforms (see previous page).

Program Cycle Characteristics

Symbol	Parameter	Min	Max	Units
t _{WC}	Write Cycle Time		20	ms
t _{AS}	Address Set-up Time	10		ns
t _{AH}	Address Hold Time	100		ns
t _{DS}	Data Set-up Time	100		ns
t _{DH}	Data Hold Time	10		ns
t _{WP}	Write Pulse Width	200		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	200		ns

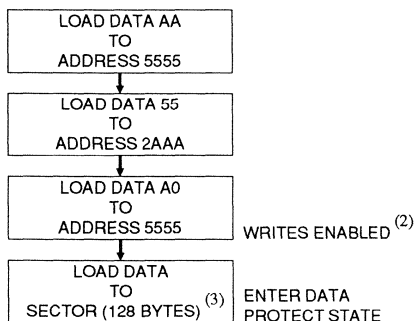
Software Protected Program Waveform



Notes:

1. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
2. A7 through A16 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
3. All bytes that are not loaded within the sector being programmed will be erased to FF.

Programming Algorithm ⁽¹⁾



Notes for software program code:

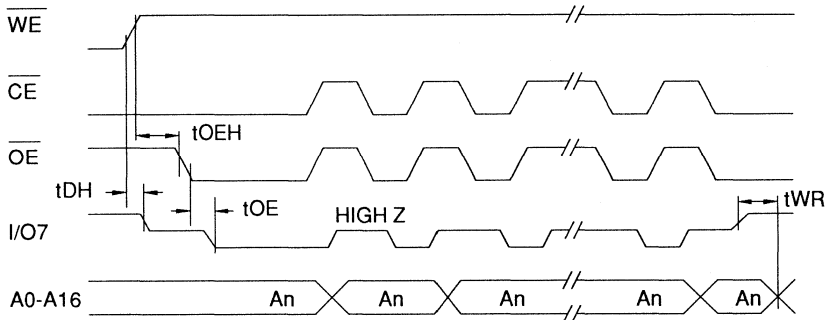
1. Data Format: I/O7-I/O0 (Hex); Address Format: A14-A0 (Hex).
2. Data Protect state will be re-activated at end of program cycle.
3. 128 bytes of data MUST BE loaded.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE\overline{H}}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

- Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

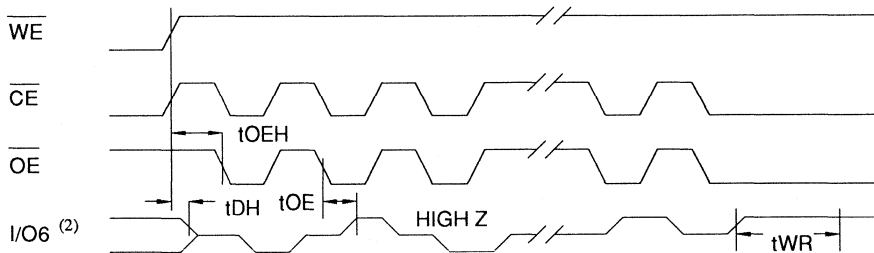


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE\overline{H}}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

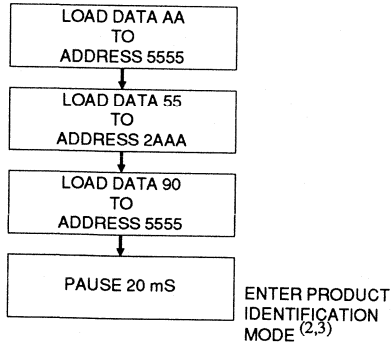
- Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms^(1,3)

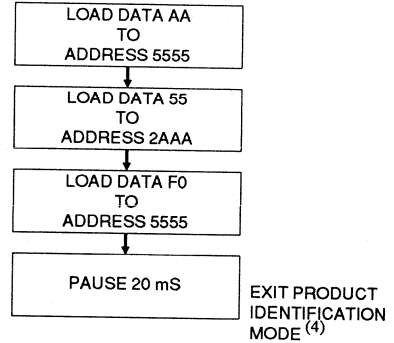


- Notes:
1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
2. Beginning and ending state of I/O6 will vary.
3. Any address location may be used but the address should not vary.

Software Product Identification Entry ⁽¹⁾



Software Product Identification Exit ⁽¹⁾



Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A16 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: 35



Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
200	15	0.02	AT29LV010-20DC AT29LV010-20JC AT29LV010-20PC AT29LV010-20TC	32D6 32J 32P6 32T	Commercial (0° to 70°C)
	15	0.05	AT29LV010-20DI AT29LV010-20JI AT29LV010-20PI	32D6 32J 32P6	Industrial (-40° to 85°C)
250	15	0.02	AT29LV010-25DC AT29LV010-25JC AT29LV010-25PC AT29LV010-25TC	32D6 32J 32P6 32T	Commercial (0° to 70°C)
	15	0.05	AT29LV010-25DI AT29LV010-25JI AT29LV010-25PI	32D6 32J 32P6	Industrial (-40° to 85°C)

Package Type	
32D6	32 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)
32P6	32 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
32T	32 Lead, Thin Small Outline Package (TSOP)

Features

- Single 3.3 V ± 10% Supply
- Three-Volt-Only Read and Write Operation
- Software Protected Programming
- Fast Read Access Time - 250 ns
- Low Power Dissipation
 - 15 mA Active Current
 - 50 µA CMOS Standby Current
- Sector Program Operation
 - Single Cycle Reprogram (Erase and Program)
 - 512 Sectors (128 words/sector)
 - Internal Address and Data Latches for 128 Words
- Fast Sector Program Cycle Time - 20 ms
- Internal Program Control and Timer
- DATA Polling for End of Program Detection
- High Reliability CMOS Technology
 - 1000 Program Cycles per Sector
 - 10-Year Data Retention
- CMOS and TTL Compatible Inputs and Outputs
- Commercial and Industrial Temperature Ranges

**1 Megabit
(64K x 16)
3-Volt Only
CMOS Flash
PEROM**

Description

The AT29LV1024 is a three-volt-only in-system Flash Programmable and Erasable Read Only Memory (PEROM). Its one megabit of memory is organized as 65,536 words by 16 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 200 ns with power dissipation of just 54 mW. When the device is deselected, the CMOS standby current is less than 50 µA.

To allow for simple in-system reprogrammability, the AT29LV1024 does not require high input voltages for programming. Three-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming

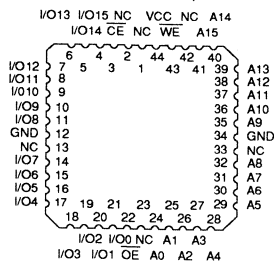
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Preliminary

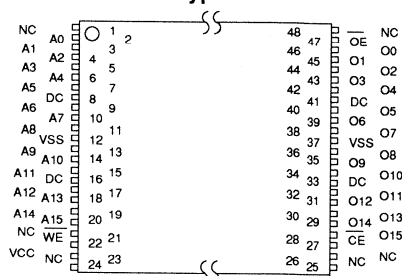
Pin Configurations

Pin Name	Function
A0 - A15	Addresses
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
I/O0 - I/O15	Data Inputs/Outputs
NC	No Connect

PLCC and LCC Top View



TSOP Top View
Type 1



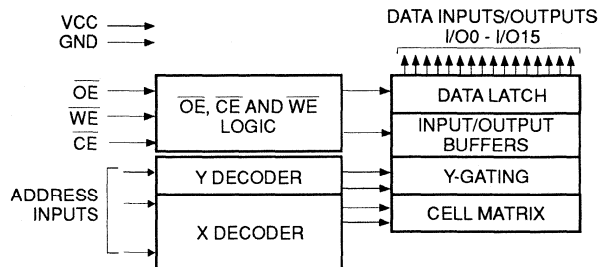
Description (Continued)

the AT29LV1024 is performed on a sector basis; 128 words of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 128 words of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a program cycle,

the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7 or I/O15. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29LV1024 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

SOFTWARE DATA PROTECTION PROGRAMMING: The AT29LV1024 has 512 individual sectors, each 128 words. Using the software data protection feature, word loads are used to enter the 128 words of a sector to be programmed. The AT29LV1024 can only be programmed or reprogrammed using the software data protection feature. The device is programmed on a sector basis. If a word of data within the sector is to be changed, data for the entire 128-word sector must be loaded into the device. The AT29LV1024 automatically does a sector erase prior to loading the data into the sector. An erase command is not required.

Software data protection protects the device from inadvertent programming. A series of three program commands to specific addresses with specific data must be presented to the device before programming may occur. The same three program commands must begin each program operation. All software program commands must obey the sector program timing specifications. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

Any attempt to write to the device without the three-word command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wrc} , a read operation will effectively be a polling operation.

After the software data protection's three-word command code is given, a word load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

The 128 words of data must be loaded into each sector. Any word that is not loaded during the programming of its sector will be erased to read FFFFh. Once the words of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data word has been loaded into the device, successive words are entered in the same manner. Each new word to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) of the preceding word. If a high to low transition is not detected within 150 μs of the last low to high transition, the load period will end and the internal programming period will start. A7 to A15 specify the sector address. The sector address must be valid during each high to low transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$). A0 to A6 specify the word address within the sector. The words may be loaded in any order; sequential loading is not required.

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Device Operation (Continued)

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29LV1024 in the following ways: (a) V_{CC} sense— if V_{CC} is below 1.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 10 ms (typical) before programming. (c) Program inhibit— holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits program cycles. (d) Noise filter— pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identification mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for various Flash densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

\overline{DATA} POLLING: The AT29LV1024 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last word loaded will result in the complement of the loaded data on I/O7 and I/O15. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29LV1024 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 and I/O14 toggling between one and zero. Once the program cycle has completed, I/O6 and I/O14 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-word software code or high voltage. For details, please contact Atmel.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to $V_{CC} + 0.6$ V
Voltage on \overline{OE} with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C_{IN}	4	6	pF	$V_{IN} = 0$ V
C_{OUT}	8	12	pF	$V_{OUT} = 0$ V

Note: 1. This parameter is characterized and is not 100% tested.



D.C. and A.C. Operating Range

		AT29LV1024-20	AT29LV1024-25
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C
	Mil.		-55°C - 125°C
Vcc Power Supply		3.3 V ± 0.3 V	3.3 V ± 0.3 V

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	AI	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	DOUT
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	DIN
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A15 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A15 = V _{IL} , A9 = V _{IH} , ⁽³⁾ A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_H = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: 26

5. See details under Software Product Identification Entry/Exit.

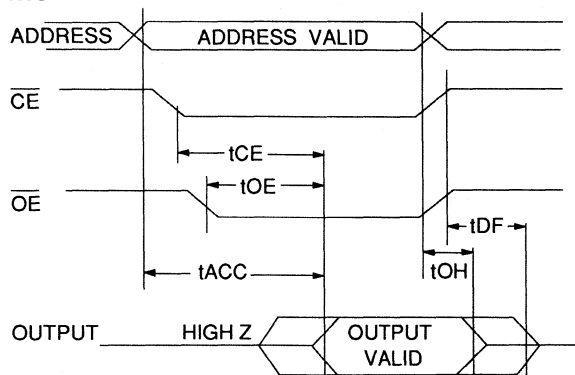
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		1	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		1	μA
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{CE} = V_{CC} - 0.3V$ to V _{CC}	Com.	50	μA
			Ind., Mil.	100	μA
I _{SB2}	V _{CC} Standby Current TTL	$\overline{CE} = 2.0 V$ to V _{CC}		1	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA		15	mA
V _{IL}	Input Low Voltage			0.6	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		.45	V
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	I _{OH} = -100 μA; V _{CC} = 4.5 V	4.2		V

A.C. Read Characteristics

Symbol	Parameter	AT29LV1024-20		AT29LV1024-25		Units
		Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		200		250	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		200		250	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	100	0	120	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	50	0	60	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		ns

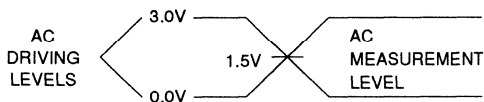
A.C. Read Waveforms



Notes:

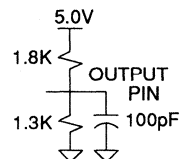
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5pF$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5 \text{ ns}$

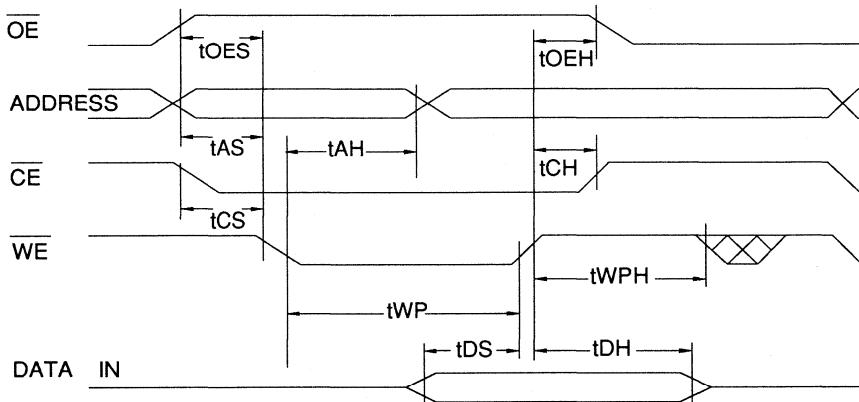
Output Test Load



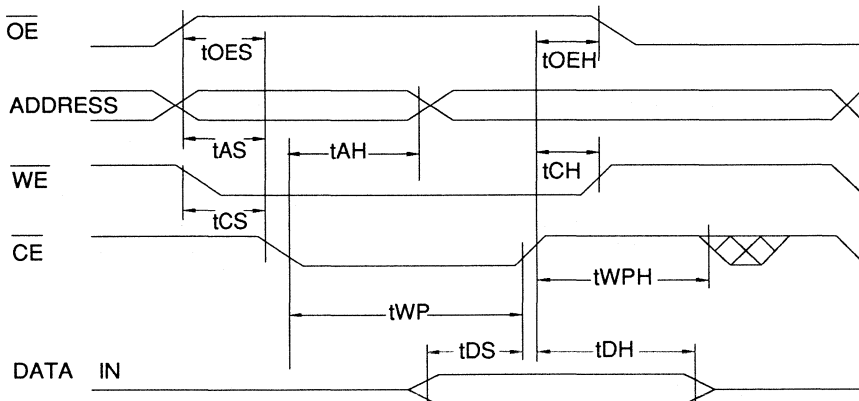
A.C. Word Load Characteristics

Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	0		ns
t_{AH}	Address Hold Time	100		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	200		ns
t_{DS}	Data Set-up Time	100		ns
t_{DH}, t_{OEH}	Data, \overline{OE} Hold Time	0		ns
t_{WPH}	Write Pulse Width High	200		ns

A.C. Word Load Waveforms- \overline{WE} Controlled



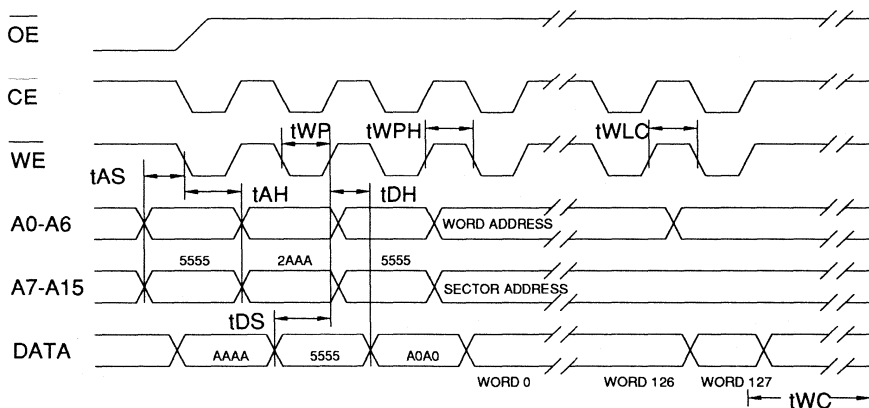
A.C. Word Load Waveforms- \overline{CE} Controlled



Program Cycle Characteristics

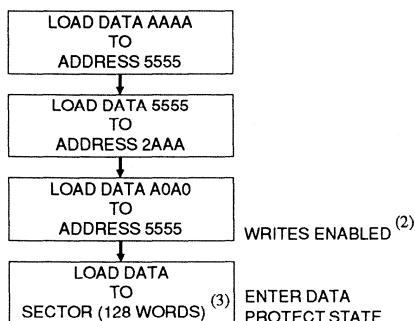
Symbol	Parameter	Min	Max	Units
tWC	Write Cycle Time		20	ms
tAS	Address Set-up Time	0		ns
tAH	Address Hold Time	100		ns
tDS	Data Set-up Time	100		ns
tDH	Data Hold Time	0		ns
tWP	Write Pulse Width	200		ns
tWLC	Word Load Cycle Time		150	μs
tWPH	Write Pulse Width High	200		ns

Software Protected Program Waveform



- Notes:
1. A7 through A15 must specify the same page address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
 2. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
 3. All words that are not loaded within the sector being programmed will be erased to FF.

Programming Algorithm ⁽¹⁾



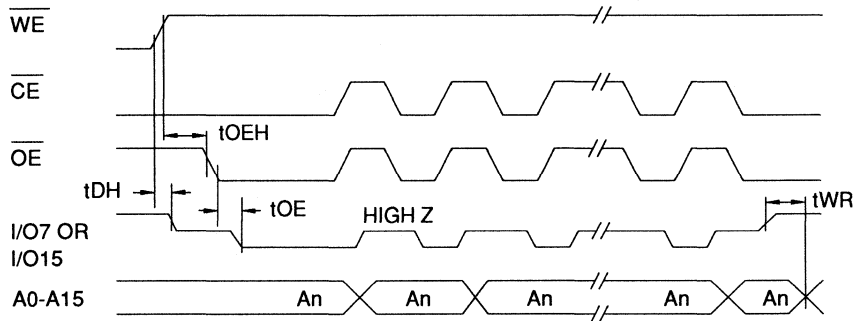
- Notes for software program code:
1. Data Format: I/O7-I/O0 (Hex); Address Format: A14-A0 (Hex).
 2. Data Protect state will be re-activated at end of program cycle.
 3. 128 words of data **MUST BE** loaded.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	0			ns
t _{OEH}	\overline{OE} Hold Time	0			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

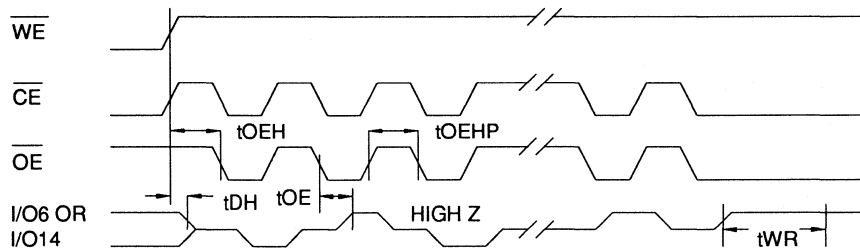


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OEH}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

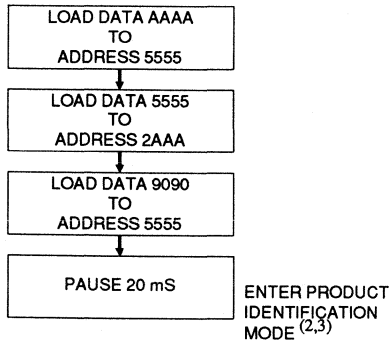
Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms

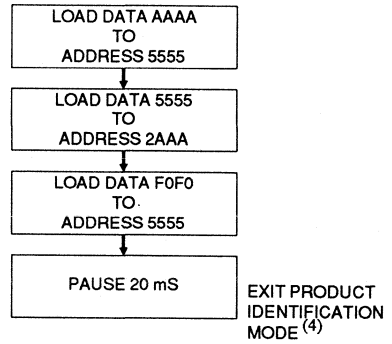


Notes:
1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
2. Beginning and ending state of I/O6 and I/O14 may vary.
3. Any address location may be used but the address should not vary.

Software Product Identification Entry ⁽¹⁾



Software Product Identification Exit ⁽¹⁾



Notes for software product identification:

1. Data Format: I/O15 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A15 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: 26



Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
200	15	0.05	AT29LV1024-20JC	44J	Commercial (0° to 70°C)
			AT29LV1024-20LC	44L	
			AT29LV1024-20TC	48T	
200	15	0.10	AT29LV1024-20JI	44J	Industrial (-40° to 85°C)
			AT29LV1024-20LI	44L	
			AT29LV1024-20TI	48T	
250	15	0.05	AT29LV1024-25JC	44J	Commercial (0° to 70°C)
			AT29LV1024-25LC	44L	
			AT29LV1024-25TC	48T	
250	15	0.10	AT29LV1024-25JI	44J	Industrial (-40° to 85°C)
			AT29LV1024-25LI	44L	
			AT29LV1024-25TI	48T	

Package Type	
44J	44 Lead, Plastic J-Leaded Chip Carrier (PLCC)
44L	44 Lead, Non-Windowed, Ceramic Leadless Chip Carrier (LCC)
48T	48 Lead, Thin Small Outline Package (TSOP)

Features

- Single 3.3 V \pm 10% Supply
- Three-Volt-Only Read and Write Operation
- Software Protected Programming
- Fast Read Access Time - 250 ns
- Low Power Dissipation
 - 15 mA Active Current
 - 20 μ A CMOS Standby Current
- Sector Program Operation
 - Single Cycle Reprogram (Erase and Program)
 - 1024 Sectors (256 bytes/sector)
 - Internal Address and Data Latches for 256 Bytes
- 2 - 16KB Boot Blocks with Lockout
- Fast Sector Program Cycle Time - 20 ms
- Internal Program Control and Timer
- DATA Polling for End of Program Detection
- High Reliability CMOS Technology
 - 1000 Program Cycles per Sector
 - 10-Year Data Retention
- CMOS and TTL Compatible Inputs and Outputs
- Commercial and Industrial Temperature Ranges

**2 Megabit
(256K x 8)
3-Volt Only
CMOS Flash
PEROM**

Preliminary

Description

The AT29LV020 is a three-volt-only in-system Flash Programmable and Erasable Read Only Memory (PEROM). Its two megabit of memory is organized as 262,144 bytes by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 250 ns with power dissipation of just 54 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than 20 μ A.

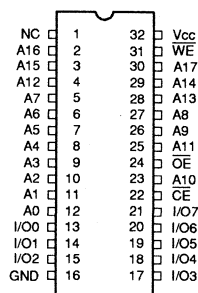
To allow for simple in-system reprogrammability, the AT29LV020 does not require high input voltages for programming. Five-volt-only commands determine the operation of the device.

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Pin Configurations

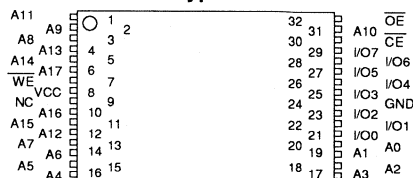
Pin Name	Function
A0 - A17	Addresses
CE	Chip Enable
OE	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

DIP Top View



TSOP Top View

Type 1



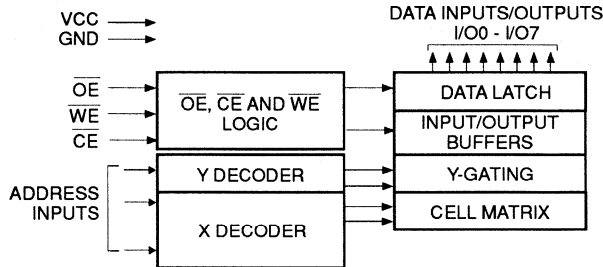
Description (Continued)

Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT29LV020 is performed on a sector basis; 256 bytes of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 256 bytes of data are captured at microprocessor speed and internally latched, freeing the address and data bus for other operations.

Following the initiation of a program cycle, the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29LV020 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

SOFTWARE DATA PROTECTION PROGRAMMING: The AT29LV020 has 1024 individual sectors, each 256 bytes. Using the software data protection feature, byte loads are used to enter the 256 bytes of a sector to be programmed. The AT29LV020 can only be programmed or reprogrammed using the software data protection feature. The device is programmed on a sector basis. If a byte of data within the sector is to be changed, data for the entire 256-byte sector must be loaded into the device. The AT29LV020 automatically does a sector erase prior to loading the data into the sector. An erase command is not required.

Software data protection protects the device from inadvertent programming. A series of three program commands to specific addresses with specific data must be presented to the device before programming may occur. The same three program commands must begin each program operation. All software program commands must obey the sector program timing specifications. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

Any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc}, a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

The 256 bytes of data must be loaded into each sector. Any byte that is not loaded during the programming of its sector will be erased to read FFh. Once the bytes of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$). If a high to low transition is not detected within 150 μs of the last low to high transition, the load period will end and the internal programming period will start. A8 to A17 specify the sector address. The sector address must be valid during each high to low transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$). A0 to A7 specify the byte address within the sector. The bytes may be loaded in any order; sequential loading is not required.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29LV020 in the following ways: (a) V_{CC} sense— if V_{CC} is below 1.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 10 ms (typical) before programming. (c) Program inhibit— holding any one of $\overline{\text{OE}}$ low, $\overline{\text{CE}}$

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Device Operation (Continued)

high or \overline{WE} high inhibits program cycles. (d) Noise filter—pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

INPUT LEVELS: While operating with a 3.3 V $\pm 10\%$ power supply, the address inputs and control inputs (\overline{OE} , \overline{CE} and \overline{WE}) may be driven from 0 to 5.5 V without adversely affecting the operation of the device. The I/O lines can be driven from 0 to 3.6 volts.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identification mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for 256K to 4-megabit densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

\overline{DATA} POLLING: The AT29LV020 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29LV020 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

BOOT BLOCK PROGRAMMING LOCKOUT: The AT29LV020 has two designated memory blocks that have a programming lockout feature. This feature prevents programming of data in the designated block once the feature has been enabled. Each of these blocks consists of 16K bytes; the programming lockout feature can be set independently for either block. While the lockout feature does not have to be activated, it can be activated for either or both blocks.

These two 16K memory sections are referred to as *boot blocks*. Secure code which will bring up a system can be contained in a boot block. The AT29LV020 blocks are located in the first 16K bytes of memory and the last 16K bytes of memory. The boot block programming lockout feature can therefore support systems that boot from the lower addresses of memory or the higher addresses. Once the programming lockout feature has been activated, the data in that block can no longer be erased or programmed; data in other memory locations can still be changed through the regular programming methods. To activate the lockout feature, a series of seven program commands to specific addresses with specific data must be performed. Please see Boot Block Lockout Feature Enable Algorithm.

If the boot block lockout feature has been activated on either block, the chip erase function will be disabled.

BOOT BLOCK LOCKOUT DETECTION: A software method is available to determine whether programming of either boot block section is locked out. See Software Product Identification Entry and Exit sections. When the device is in the software product identification mode, a read from location 00002H will show if programming the lower address boot block is locked out while reading location 1FFFFH will do so for the upper boot block. If the data is FE, the corresponding block can be programmed; if the data is FF, the program lockout feature has been activated and the corresponding block cannot be programmed. The software product identification exit mode should be used to return to standard operation.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to $V_{CC} + 0.6$ V
Voltage on A9 (including N.C. Pins) with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. These parameters are characterized and not 100% tested.

D.C. and A.C. Operating Range

		AT29LV020-20	AT29LV020-25
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C
V _{CC} Power Supply		3.3 V ± 0.3 V	3.3 V ± 0.3 V

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	DOUT
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	DIN
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A17 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A17 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_{IH} = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: BA.

5. See details under Software Product Identification Entry/Exit.

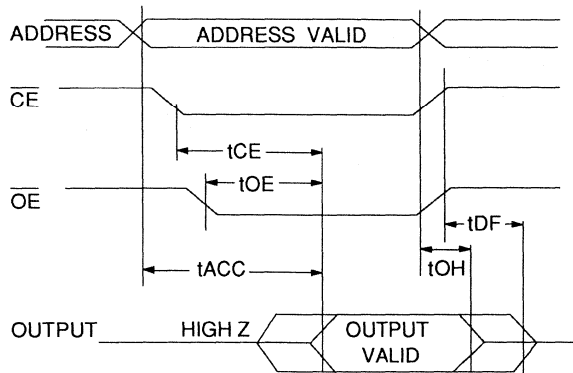
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		1	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		1	μA
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{CE} = V_{CC} - 0.3 \text{ V to } V_{CC}$	Com.	20	μA
			Ind.	50	μA
I _{SB2}	V _{CC} Standby Current TTL	$\overline{CE} = 2.0 \text{ V to } V_{CC}$		1	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA; V _{CC} = 3.6 V		15	mA
V _{IL}	Input Low Voltage			0.6	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 1.6 mA; V _{CC} = 3.0 V		.45	V
V _{OH}	Output High Voltage	I _{OH} = -100 μA; V _{CC} = 3.0 V	2.4		V

A.C. Read Characteristics

Symbol	Parameter	AT29LV020-20		AT29LV020-25		Units
		Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		200		250	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		200		250	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	100	0	120	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	50	0	60	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		ns

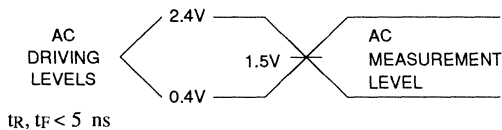
A.C. Read Waveforms



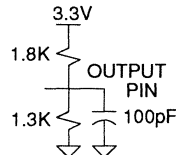
Notes:

- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5\text{pF}$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



Output Test Load

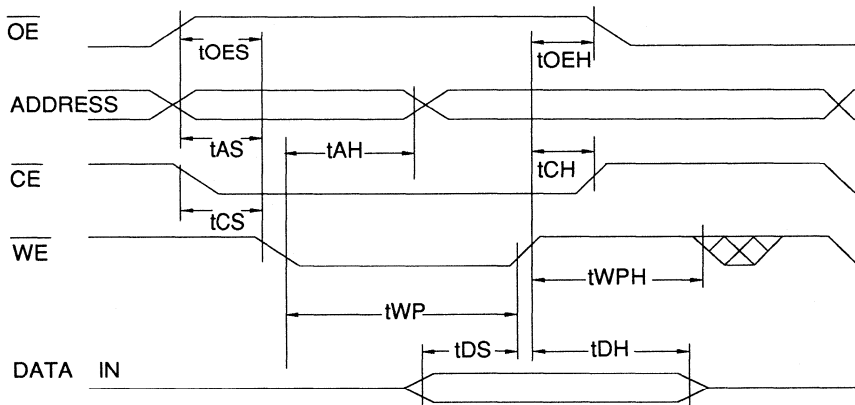


A.C. Byte Load Characteristics

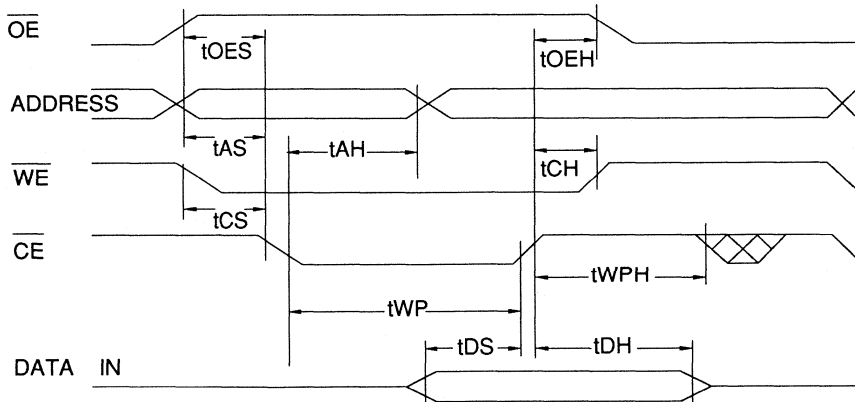
Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, \overline{OE} Set-up Time	10		ns
t_{AH}	Address Hold Time	100		ns
t_{CS}	Chip Select Set-up Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width (\overline{WE} or \overline{CE})	200		ns
t_{DS}	Data Set-up Time	100		ns
$t_{DH}, t_{OE\overline{H}}$	Data, \overline{OE} Hold Time	10		ns
t_{WPH}	Write Pulse Width High	200		ns

A.C. Byte Load Waveforms^(1,2)

\overline{WE} Controlled



\overline{CE} Controlled



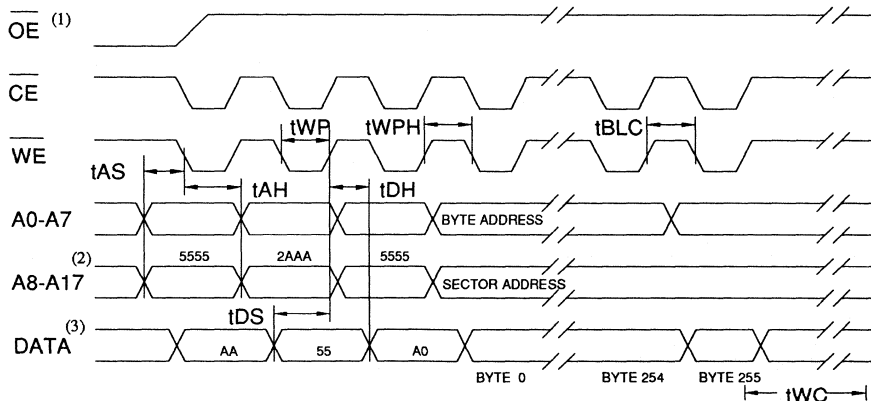
Notes:

1. The software data protection commands must be applied prior to byte loads.
2. A complete sector (256 bytes) should be loaded using these waveforms as shown in the Software Protected Byte Load waveforms (see previous page).

Program Cycle Characteristics

Symbol	Parameter	Min	Max	Units
tWC	Write Cycle Time		20	ms
tAS	Address Set-up Time	10		ns
tAH	Address Hold Time	100		ns
tDS	Data Set-up Time	100		ns
tDH	Data Hold Time	10		ns
tWP	Write Pulse Width	200		ns
tBLC	Byte Load Cycle Time		150	μs
tWPH	Write Pulse Width High	200		ns

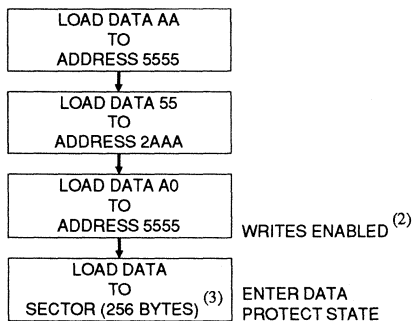
Software Protected Program Waveform



Notes:

1. OE must be high when WE and CE are both low.
2. A8 through A17 must specify the sector address during each high to low transition of WE (or CE) after the software code has been entered.
3. All bytes that are not loaded within the sector being programmed will be erased to FF.

Programming Algorithm ⁽¹⁾



Notes for software program code:

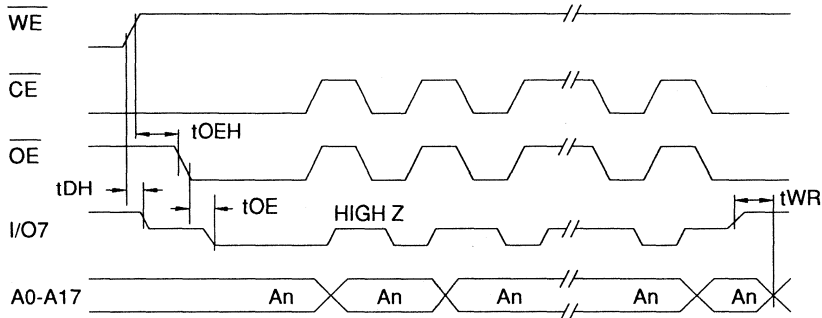
1. Data Format: I/O7-I/O0 (Hex); Address Format: A14-A0 (Hex).
2. Data Protect state will be re-activated at end of program cycle.
3. 256 bytes of data MUST BE loaded.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OEH}	$\overline{\text{OE}}$ Hold Time	10			ns
t _{OE}	$\overline{\text{OE}}$ to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

- Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

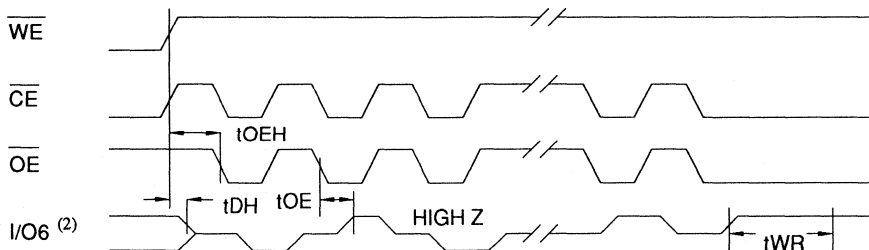


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OEH}	$\overline{\text{OE}}$ Hold Time	10			ns
t _{OE}	$\overline{\text{OE}}$ to Output Delay ⁽²⁾				ns
t _{OEHP}	$\overline{\text{OE}}$ High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

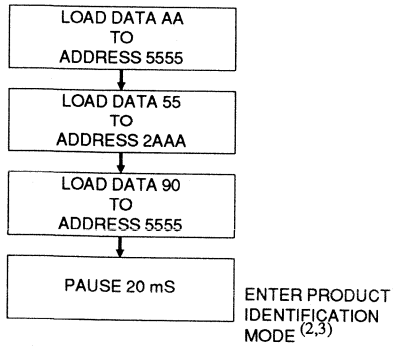
- Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms^(1,3)



- Notes: 1. Toggling either $\overline{\text{OE}}$ or $\overline{\text{CE}}$ or both $\overline{\text{OE}}$ and $\overline{\text{CE}}$ will operate toggle bit.
2. Beginning and ending state of I/O6 will vary.
3. Any address location may be used but the address should not vary.

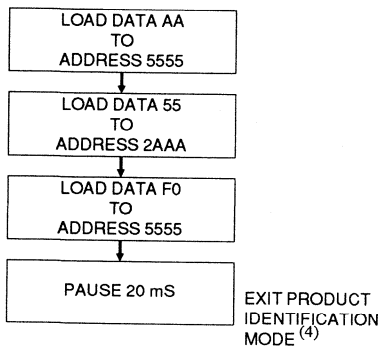
Software Product Identification Entry ⁽¹⁾



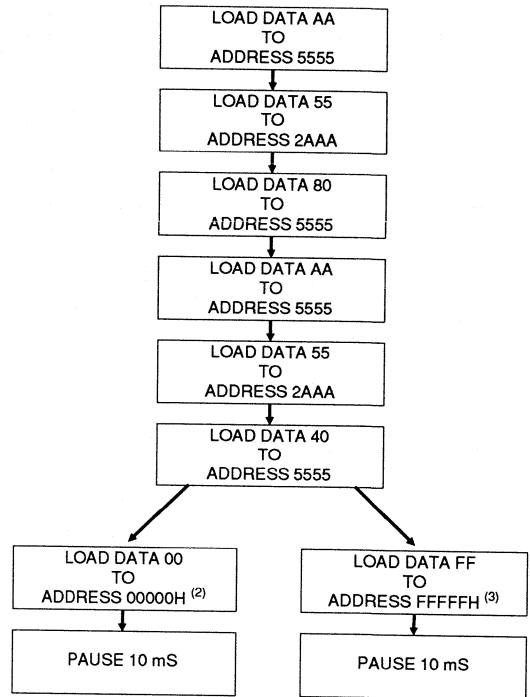
Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A17 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: BA

Software Product Identification Exit ⁽¹⁾



Boot Block Lockout Feature Enable Algorithm ⁽¹⁾



Notes for boot block lockout feature enable:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Lockout feature set on lower address boot block.
3. Lockout feature set on higher address boot block.



Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
200	15	0.02	AT29LV020-20DC AT29LV020-20PC AT29LV020-20TC	32D6 32P6 32T	Commercial (0° to 70°C)
	15	0.05	AT29LV020-20DI AT29LV020-20PI	32D6 32P6	Industrial (-40° to 85°C)
250	15	0.02	AT29LV020-25DC AT29LV020-25PC AT29LV020-25TC	32D6 32P6 32T	Commercial (0° to 70°C)
	15	0.05	AT29LV020-25DI AT29LV020-25PI	32D6 32P6	Industrial (-40° to 85°C)

Package Type

32D6	32 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32P6	32 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
32T	32 Lead, Thin Small Outline Package (TSOP)

Features

- Single 3.3 V ± 10% Supply
- Three-Volt-Only Read and Write Operation
- Software Protected Programming
- Fast Read Access Time - 250 ns
- Low Power Dissipation
 - 15 mA Active Current
 - 20 µA CMOS Standby Current
- Sector Program Operation
 - Single Cycle Reprogram (Erase and Program)
 - 1024 Sectors (512 bytes/sector)
 - Internal Address and Data Latches for 512 Bytes
- 2 - 16 KB Boot Blocks with Lockout
- Fast Sector Program Cycle Time - 20 ms Max.
- Internal Program Control and Timer
- DATA Polling for End of Program Detection
- High Reliability CMOS Technology
 - 1000 Program Cycles per Sector
 - 10-Year Data Retention
- CMOS and TTL Compatible Inputs and Outputs
- Commercial and Industrial Temperature Ranges

**4 Megabit
(512K x 8)
3-Volt Only
CMOS Flash
PEROM**

Preliminary

Description

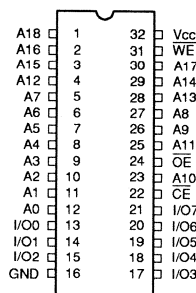
The AT29LV040 is a three-volt-only in-system Flash Programmable and Erasable Read Only Memory (PEROM). Its four megabit of memory is organized as 524,288 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 250 ns with power dissipation of just 54 mW over the commercial temperature range. When the device is deselected, the CMOS standby current is less than 20 µA. The programming algorithm is identical to Atmel's 256K, 512K, and 1-megabit Flash PEROMs.

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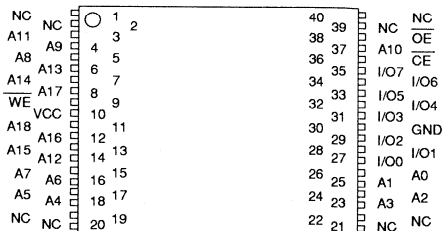
Pin Configurations

Pin Name	Function
A0 - A18	Addresses
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect

DIP Top View



TSOP Top View
Type 1



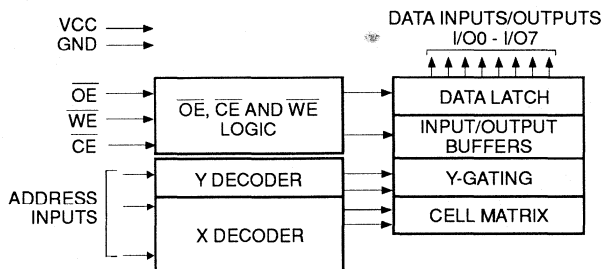
Description (Continued)

To allow for simple in-system reprogrammability, the AT29LV040 does not require high input voltages for programming. Three-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from an EPROM. Reprogramming the AT29LV040 is performed on a sector basis; 512 bytes of data are loaded into the device and then simultaneously programmed.

During a reprogram cycle, the address locations and 512 bytes of data are captured at microprocessor speed and internally

latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the sector and then program the latched data using an internal control timer. The end of a program cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a program cycle has been detected, a new access for a read or program can begin.

Block Diagram



Device Operation

READ: The AT29LV040 is accessed like an EPROM. When $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are low and $\overline{\text{WE}}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever $\overline{\text{CE}}$ or $\overline{\text{OE}}$ is high. This dual-line control gives designers flexibility in preventing bus contention.

SOFTWARE DATA PROTECTION PROGRAMMING: The AT29LV040 has 1024 individual sectors, each 512 bytes. Using the software data protection feature, byte loads are used to enter the 512 bytes of a sector to be programmed. The AT29LV040 can only be programmed or reprogrammed using the software data protection feature. The device is programmed on a sector basis. If a byte of data within the sector is to be changed, data for the entire 512-byte sector must be loaded into the device. The AT29LV040 automatically does a sector erase prior to loading the data into the sector. An erase command is not required.

Software data protection protects the device from inadvertent programming. A series of three program commands to specific addresses with specific data must be presented to the device before programming may occur. The same three program commands must begin each program operation. All software program commands must obey the sector program timing specifications. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

Any attempt to write to the device without the three-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{wc}, a read operation will effectively be a polling operation.

After the software data protection's three-byte command code is given, a byte load is performed by applying a low pulse on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ input with $\overline{\text{CE}}$ or $\overline{\text{WE}}$ low (respectively) and $\overline{\text{OE}}$ high. The address is latched on the falling edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$, whichever occurs last. The data is latched by the first rising edge of $\overline{\text{CE}}$ or $\overline{\text{WE}}$.

The 512 bytes of data must be loaded into each sector. Any byte that is not loaded during the programming of its sector will be erased to read FFh. Once the bytes of a sector are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) of the preceding byte. If a high to low transition is not detected within 150 μs of the last low to high transition, the load period will end and the internal programming period will start. A9 to A18 specify the sector address. The sector address must be valid during each high to low transition of $\overline{\text{WE}}$ (or $\overline{\text{CE}}$). A0 to A8 specify the byte address within the sector. The bytes may be loaded in any order; sequential loading is not required.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29LV040 in the following ways: (a) V_{CC} sense— if V_{CC} is below 1.8 V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 10 ms (typical) before programming. (c) Program inhibit— holding any one of $\overline{\text{OE}}$ low, $\overline{\text{CE}}$

continued on next page

Device Operation (Continued)

high or \overline{WE} high inhibits program cycles. (d) Noise filter—pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a program cycle.

INPUT LEVELS: While operating with a $3.3\text{ V} \pm 10\%$ power supply, the address inputs and control inputs (\overline{OE} , \overline{CE} and \overline{WE}) may be driven from 0 to 5.5 V without adversely affecting the operation of the device. The I/O lines can only be driven from 0 to 3.6 volts.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer as Atmel. It may be accessed by hardware or software operation. The hardware operation mode can be used by an external programmer to identify the correct programming algorithm for the Atmel product. In addition, users may wish to use the software product identification mode to identify the part (i.e. using the device code), and have the system software use the appropriate sector size for program operations. In this manner, the user can have a common board design for 256K to 4-megabit densities and, with each density's sector size in a memory map, have the system software apply the appropriate sector size.

For details, see Operating Modes (for hardware operation) or Software Product Identification. The manufacturer and device code is the same for both modes.

\overline{DATA} POLLING: The AT29LV040 features \overline{DATA} polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. \overline{DATA} polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to \overline{DATA} polling the AT29LV040 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODES: The entire device may be erased by either using a six-byte software code or high voltage. For details, please contact Atmel.

BOOT BLOCK PROGRAMMING LOCKOUT: The AT29LV040 has two designated memory blocks that have a programming lockout feature. This feature prevents programming of data in the designated block once the feature has been enabled. Each of these blocks consists of 16K bytes; the programming lockout feature can be set independently for either block. While the lockout feature does not have to be activated, it can be activated for either or both blocks.

These two 16K memory sections are referred to as *boot blocks*. Secure code which will bring up a system can be contained in a boot block. The AT29LV040 blocks are located in the first 16K bytes of memory and the last 16K bytes of memory. The boot block programming lockout feature can therefore support systems that boot from the lower addresses of memory or the higher addresses. Once the programming lockout feature has been activated, the data in that block can no longer be erased or programmed; data in other memory locations can still be changed through the regular programming methods. To activate the lockout feature, a series of seven program commands to specific addresses with specific data must be performed. Please see Boot Block Lockout Feature Enable Algorithm.

If the boot block lockout feature has been activated on either block, the chip erase function will be disabled.

BOOT BLOCK LOCKOUT DETECTION: A software method is available to determine whether programming of either boot block section is locked out. See Software Product Identification Entry and Exit sections. When the device is in the software product identification mode, a read from location 00002H will show if programming the lower address boot block is locked out while reading location 1FFFFH will do so for the upper boot block. If the data is FE, the corresponding block can be programmed; if the data is FF, the program lockout feature has been activated and the corresponding block cannot be programmed. The software product identification exit mode should be used to return to standard operation.

Absolute Maximum Ratings*

Temperature Under Bias.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
All Input Voltages (including N.C. Pins) with Respect to Ground	-0.6 V to +6.25 V
All Output Voltages with Respect to Ground	-0.6 V to $V_{CC} + 0.6\text{ V}$
Voltage on A9 (including N.C. Pins) with Respect to Ground	-0.6 V to +13.5 V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Pin Capacitance (f = 1 MHz, T = 25°C) ⁽¹⁾

	Typ	Max	Units	Conditions
C _{IN}	4	6	pF	V _{IN} = 0 V
C _{OUT}	8	12	pF	V _{OUT} = 0 V

Note: 1. These parameters are characterized and not 100% tested.

D.C. and A.C. Operating Range

		AT29LV040-20	AT29LV040-25
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C
V _{CC} Power Supply		3.3 V ± 0.3 V	3.3 V ± 0.3 V

Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	Ai	I/O
Read	V _{IL}	V _{IL}	V _{IH}	Ai	D _{OUT}
Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	D _{IN}
Standby/Write Inhibit	V _{IH}	X ⁽¹⁾	X	X	High Z
Program Inhibit	X	X	V _{IH}		
Program Inhibit	X	V _{IL}	X		
Output Disable	X	V _{IH}	X		High Z
Product Identification					
Hardware	V _{IL}	V _{IL}	V _{IH}	A1-A18 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IL}	Manufacturer Code ⁽⁴⁾
				A1-A18 = V _{IL} , A9 = V _{IH} ⁽³⁾ , A0 = V _{IH}	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _I	Manufacturer Code ⁽⁴⁾
				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to A.C. Programming Waveforms.

3. V_H = 12.0 V ± 0.5 V.

4. Manufacturer Code: 1F, Device Code: 3B.

5. See details under Software Product Identification Entry/Exit.

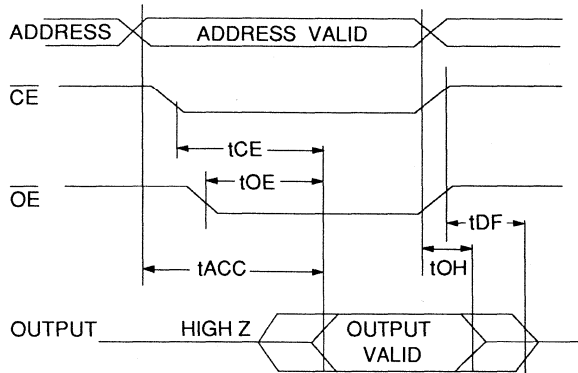
D.C. Characteristics

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	V _{IN} = 0 V to V _{CC}		1	μA
I _{LO}	Output Leakage Current	V _{I/O} = 0 V to V _{CC}		1	μA
I _{SB1}	V _{CC} Standby Current CMOS	\overline{CE} = V _{CC} - 0.3 V to V _{CC}	Com.	20	μA
			Ind.	50	μA
I _{SB2}	V _{CC} Standby Current TTL	\overline{CE} = 2.0 V to V _{CC}		1	mA
I _{CC}	V _{CC} Active Current	f = 5 MHz; I _{OUT} = 0 mA; V _{CC} = 3.6 V		15	mA
V _{IL}	Input Low Voltage			0.6	V
V _{IH}	Input High Voltage		2.0		V
V _{OL}	Output Low Voltage	I _{OL} = 1.6 mA; V _{CC} = 3.0 V		.45	V
V _{OH}	Output High Voltage	I _{OH} = -100 μA; V _{CC} = 3.0 V	2.4		V

A.C. Read Characteristics

Symbol	Parameter	AT29LV040-20		AT29LV040-25		Units
		Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		200		250	ns
$t_{CE}^{(1)}$	\overline{CE} to Output Delay		200		250	ns
$t_{OE}^{(2)}$	\overline{OE} to Output Delay	0	100	0	120	ns
$t_{DF}^{(3,4)}$	\overline{CE} or \overline{OE} to Output Float	0	50	0	60	ns
t_{OH}	Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	0		0		ns

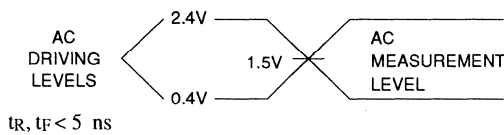
A.C. Read Waveforms



Notes:

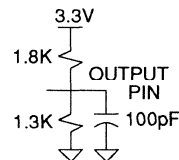
- \overline{CE} may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC} .
- \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first ($C_L = 5\text{pF}$).
- This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



$t_R, t_F < 5 \text{ ns}$

Output Test Load

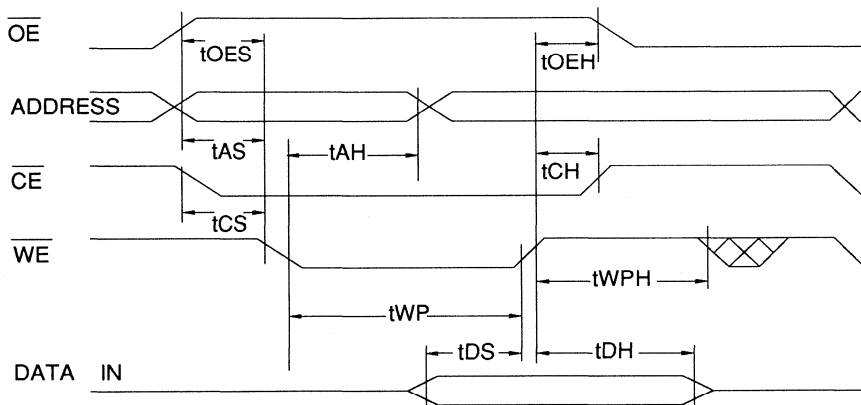


A.C. Byte Load Characteristics

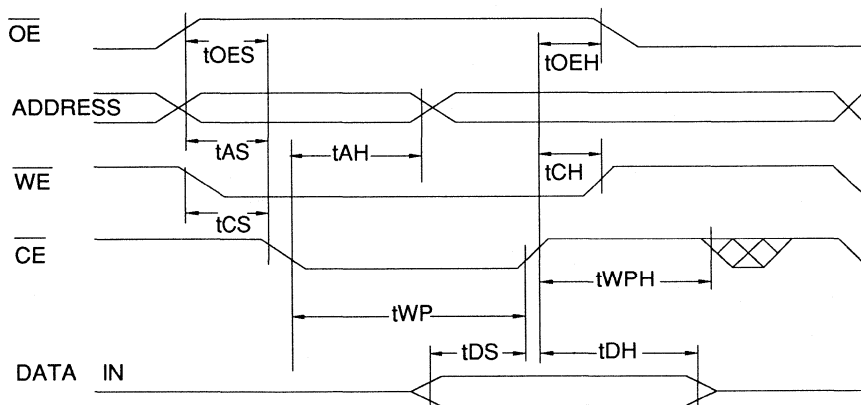
Symbol	Parameter	Min	Max	Units
tAS, tOES	Address, \overline{OE} Set-up Time	10		ns
tAH	Address Hold Time	100		ns
tCS	Chip Select Set-up Time	0		ns
tCH	Chip Select Hold Time	0		ns
tWP	Write Pulse Width (\overline{WE} or \overline{CE})	200		ns
tDS	Data Set-up Time	100		ns
tDH, tOEH	Data, \overline{OE} Hold Time	10		ns
tWPH	Write Pulse Width High	200		ns

A.C. Byte Load Waveforms ^(1,2)

\overline{WE} Controlled



\overline{CE} Controlled



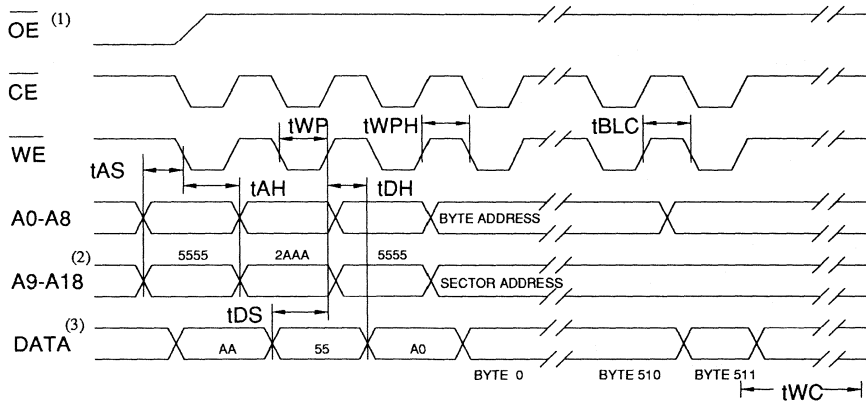
Notes:

1. The three byte address and data commands shown on the previous page must be applied prior to byte loads.
2. A complete sector (512 bytes) should be loaded using these waveforms as shown in the Byte Load waveforms (see previous page).

Program Cycle Characteristics

Symbol	Parameter	Min	Max	Units
t _{WC}	Write Cycle Time		20	ms
t _{AS}	Address Set-up Time	10		ns
t _{AH}	Address Hold Time	100		ns
t _{DS}	Data Set-up Time	100		ns
t _{DH}	Data Hold Time	10		ns
t _{WP}	Write Pulse Width	200		ns
t _{BLC}	Byte Load Cycle Time		150	μs
t _{WPH}	Write Pulse Width High	200		ns

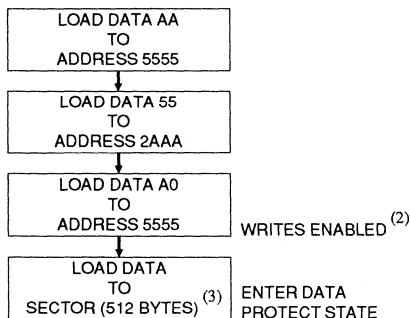
Software Protected Program Waveform



Notes:

- \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
- A9 through A18 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
- All bytes that are not loaded within the sector being programmed will be erased to FF.

Programming Algorithm ⁽¹⁾



Notes for software program code:

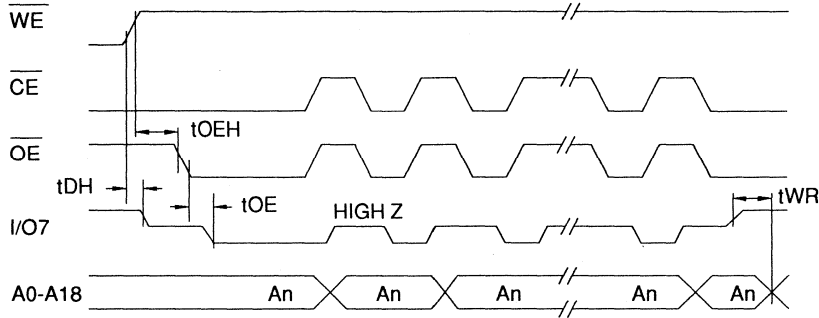
- Data Format: I/O7-I/O0 (Hex); Address Format: A14-A0 (Hex).
- Data Protect state will be re-activated at end of program cycle.
- 512 bytes of data **MUST BE** loaded.

Data Polling Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE_H}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{WR}	Write Recovery Time	0			ns

- Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Data Polling Waveforms

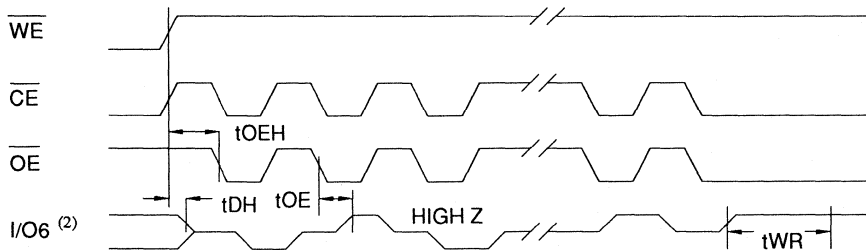


Toggle Bit Characteristics⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Units
t _{DH}	Data Hold Time	10			ns
t _{OE_H}	\overline{OE} Hold Time	10			ns
t _{OE}	\overline{OE} to Output Delay ⁽²⁾				ns
t _{OEHP}	\overline{OE} High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

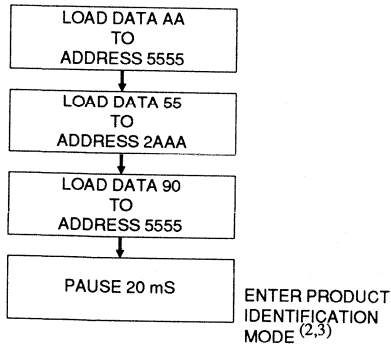
- Notes: 1. These parameters are characterized and not 100% tested.
2. See t_{OE} spec in A.C. Read Characteristics.

Toggle Bit Waveforms^(1,3)



- Notes:
1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
2. Beginning and ending state of I/O6 will vary.
3. Any address location may be used but the address should not vary.

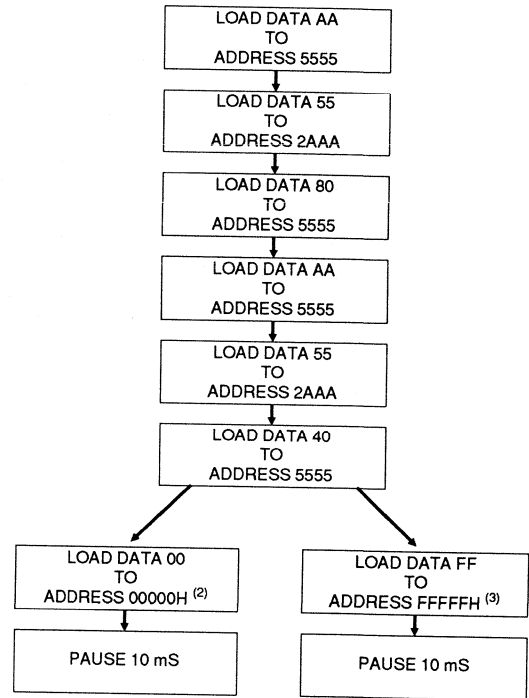
Software Product Identification Entry ⁽¹⁾



Notes for software product identification:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. A1 - A18 = V_{IL}.
Manufacture Code is read for A0 = V_{IL};
Device Code is read for A0 = V_{IH}.
3. The device does not remain in identification mode if powered down.
4. The device returns to standard operation mode.
5. Manufacturer Code: 1F
Device Code: 3B

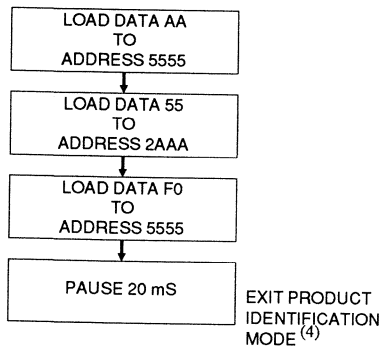
Boot Block Lockout Feature Enable Algorithm ⁽¹⁾



Notes for boot block lockout feature enable:

1. Data Format: I/O7 - I/O0 (Hex);
Address Format: A14 - A0 (Hex).
2. Lockout feature set on lower address boot block.
3. Lockout feature set on higher address boot block.

Software Product Identification Exit ⁽¹⁾





Ordering Information

t _{ACC} (ns)	I _{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
200	15	0.02	AT29LV040-20DC AT29LV040-20PC AT29LV040-20TC	32D6 32P6 40T	Commercial (0° to 70°C)
	15	0.05	AT29LV040-20DI AT29LV040-20PI	32D6 32P6	Industrial (-40° to 85°C)
250	15	0.02	AT29LV040-25DC AT29LV040-25PC AT29LV040-25TC	32D6 32P6 40T	Commercial (0° to 70°C)
	15	0.05	AT29LV040-25DI AT29LV040-25PI	32D6 32P6	Industrial (-40° to 85°C)

Package Type	
32D6	32 Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline Package (Cerdip)
32P6	32 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
40T	40 Lead, Thin Small Outline Package (TSOP)

Atmel Flash PEROMs

Introduction

As the industry recognizes the benefits of field reprogrammability for systems, the need for a cost effective, easy to update non-volatile memory arises. To fill this role, Flash memory devices have shown great promise to become the memory of choice. But, as with the early days of EPROM and EEPROM devices, there is much confusion about what features and voltages the ideal Flash memory device should contain. The ideal Flash device provides the designer the cleanest hardware implementation, requiring the fewest number of external components. In addition the device should provide the software designer with the highest level of flexibility, yet very simple and straightforward commands for programming. Atmel has developed the Flash PEROM with these ideas in mind.

Atmel Flash PEROMs (programmable erasable read-only memories) are implemented on an advanced sub-micron process using a highly efficient memory cell to store each bit of data. Unlike first generation Flash memories, Fowler-Nordheim tunneling is used in both the erasing and programming of the memory cell. This programming method requires only nanoamps of high voltage (15 V to 20 V) programming current, allowing

the use of an on-chip charge pump to generate the necessary programming voltages. The low programming current also permits sector programming. Typical first generation Flash devices are made with EPROM cell structures which use hot electron injection for programming. Hot electron injection typically requires several milliamps of high voltage programming current. This current requirement is why multiple external voltages are required for programming and why only one byte at a time can be programmed for first generation Flash devices.

Flash PEROM Device Features

The Atmel family of Flash PEROM devices consists of five capacities ranging from 256K to 4 megabit. All devices are single voltage, either 3-volt-only or 5-volt-only, and can be programmed using the same deterministic (i.e., fixed maximum time) programming algorithm.

The Atmel Flash PEROM devices are all designed as large memory arrays broken up into small individually reprogrammable sectors. For example, the AT29C010 (128K x 8) is divided into 1024 sectors of 128 bytes. Table 1 describes this organization for each Flash PEROM device:

Table 1. Atmel Flash PEROM Devices

Devices		Memory Size	Number of Sectors	Sector Size (bytes)	Manufacturer ID	Device ID	
5 V	3 V					5 V	3 V
AT29C256/7	AT29LV256/7	32K x 8	512	64	1F	DC	BC
AT29C512	AT29LV512	64K x 8	512	128	1F	5D	3D
AT29C010	AT29LV010	128K x 8	1024	128	1F	D5	35
AT29C1024	AT29LV1024	64K x 16	512	128 ⁽¹⁾	1F	25	26
AT29C020	AT29LV020	256K x 8	1024	256	1F	DA	BA
AT29C040	AT29LV040	512K x 8	1024	512	1F	5B	3B

Note: 1. 128 Words.

Flash Programmable Erasable ROM

Application Note

Key features are implemented on a Flash PEROM memory to improve system performance and simplify hardware and software development, as described below:

Small Sectors

Atmel Flash PEROMs are organized into small sectors for reprogramming. Unlike first generation devices that require erasing large blocks of memory before reprogramming (at least several thousand bytes to as much as the entire chip capacity), Atmel's sector organization allows for fast and easy data updates. Each sector's contents may be altered independently by simply loading new data into the on-chip sector buffer, at full bus speed, then waiting 10 to 20 msec while the chip's built-in sequencer programs the contents of the newly loaded buffer into the array. No pre-erase is required. When only a small portion of the total memory must be altered, the small sector approach saves considerable time. It also eliminates the need for large system buffer memory space to hold unchanging information that would have to be copied out of a large area of the Flash component and rewritten back into it after the small portion is updated. These differences can be very significant: Write time for the Atmel Flash PEROM is always 10 msec per sector (20 msec for 3-volt write), while write time for large-sectored or whole chip Flash devices is variable and can extend to several minutes. The several-hundred-byte Flash PEROM sector typically requires no additional buffering, while the large sector devices require tens to hundreds of Kbytes of system memory or extra hardware memory to contain not-to-be-changed memory contents during the mandatory pre-erase activity.

Data Protection

The Atmel Flash PEROM memory has both hardware and software data protection on-chip to prevent the contents of memory from being inadvertently altered. The following five mechanisms exist on each Flash PEROM:

- 1. Noise Filter:** All control line inputs have filtering circuitry to eliminate any noise spikes less than 15 nsec in duration.
- 2. VCC sense:** If VCC falls below 3.8 volts, (typical), programming will be inhibited. For LV (low voltage) devices VCC sense is typically 1.8 volts.
- 3. Power on Delay:** When VCC rises above the VCC sense level a 5-msec timer is started which will inhibit programming until it has completed its time-out, allowing all system power transients to settle and initialization routines to proceed without disturbing the Flash PEROM contents.
- 4. Three-Line Control:** To initiate a write cycle all three control lines must be in the correct state. If OE is not high, or CE is not low, or if WE is not low a write cycle will be inhibited.
- 5. Software Data Protection (SDP):** This protection mechanism is the only one that may be optionally activated or disabled under software control. When it is activated, the Flash PEROM requires a specific 3-byte temporary unlock write sequence prior to each sector load cycle to enable programming. If a sector load cycle is executed without the 3-byte write sequence, no information will be altered

and the device will lock out all activity, (reads and writes), for 10 msec. Activation is accomplished by the first occurrence of the specific 3-byte temporary unlock write sequence. Thereafter, all sector writes must be preceded by the same 3-byte write sequence. SDP can be explicitly disabled by a specific 6-byte write sequence.

Product ID

Built into every Flash PEROM is the ability to interrogate the device to determine the manufacturer and device type. Simply write the proper 3-byte code into the device, wait the write cycle time (twc), and read from locations 0000H and 0001H. No special voltages are required. Reading from location 0000H will access the manufacturer code. All Atmel devices read 1F. Reading from location 0001H will access the device ID code. See Table 1 for the device ID codes for each Flash device. Note that device ID codes are different for the standard 5-volt parts and for the 3-volt (LV) devices. Product ID information can also be accessed by applying a 12-volt signal to pin A9. This is available to maintain compatibility with high voltage Flash or EPROMs when used with external programming hardware.

Data Polling

Maximum programming time for a Flash PEROM is specified as 10 msec, (20 msec for LV devices). Typically, this programming time is only 5 to 7 msec, (10 to 15 msec for LV devices). To take advantage of this typical programming time and to speed up the overall programming process, a data polling feature is available in the Flash PEROM device. To utilize this feature, the user must read from the final address written following a sector write. During programming, Bit 7 will be inverted from the state in which it was written. When a read produces true data on all outputs, the programming process is complete. The device is then ready for the next operation.

Toggle Bit

An alternate method of indicating when programming is complete is to use the toggle bit. Programming completion is indicated by monitoring Bit 6 of any byte location. On successive reads from a fixed location, Bit 6 will toggle logic states during programming. When Bit 6 does not change on successive reads, the device has completed programming.

Flash PEROM Programming Description

Atmel Flash PEROMs are designed to allow all devices to be programmed using the same deterministic algorithm. As shown in the accompanying flow charts, Figure 1 through Figure 4, the user simply has to interrogate the device ID code and set the sector size. This operation need only be done once if the sector size variable is saved. The sector size variable can be hard-set in software and the device ID interrogation eliminated if only one density device will ever be used.

Following sector size determination, a sector load cycle can be initiated. The following will describe programming the 3 V Flash and the 5 V Flash using software data protection. Programming begins with a 3-byte sequence to temporarily unlock the software data protection, followed by loading the sector of data to the device. This sequence of activity is shown in Figure 5. If a complete sector of data is not loaded, the byte locations

within the sector that were not loaded will be cleared to FF during programming. All addresses must be within the same physical sector or errors may occur. It is not necessary to load the sector buffer in any address order. A random addressing sequence is perfectly acceptable, with each byte accompanied by its address within the sector. During the sector load cycle, a maximum time of 150 μ sec (t_{BLC}) is allowed between successive byte loads. If this byte load time is exceeded, the device will begin programming mode prematurely.

t_{BLC} time after loading the sector, the Flash PEROM device will enter its programming mode. While programming, the device will ignore any further write commands and any attempt to read will output only $\overline{\text{Data Poll}}$ and toggle bit data.

Before entering into a polling loop, it is good practice to start a programming cycle watchdog timer. This will prevent your software from being caught in an endless loop if something goes wrong with programming the device.

The polling loop should consist of two operations. The first is to check status of the watchdog timer, and the second to check

$\overline{\text{Data Poll}}$ data. The watchdog timer should never time-out in normal programming. If a time-out does occur, check the hardware and software for possible problems. To check $\overline{\text{Data Poll}}$, simply read the device at the address of the last byte programmed in the sector. The data should be compared against the data that was written. When the data matches, the programming is complete.

Before going on to another operation, it is recommended to verify that the sector was properly programmed.

Summary

Programming the Atmel Flash PEROM is a simple process, akin to loading an SRAM. Facilities in the device minimize the software and system overhead and architectural and circuit features simplify the interface and speed performance, while improving system integrity. The programming procedures described above will insure that devices will always be properly programmed, and require only about one-tenth of the typical software, buffer memory and performance overhead of first generation Flash components.

Figure 1. Software Product Identification Entry

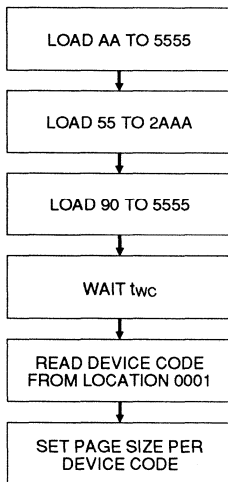


Figure 2. Software Product Identification Exit

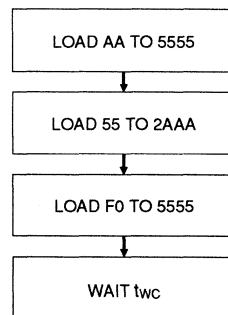


Figure 3. Page Loop

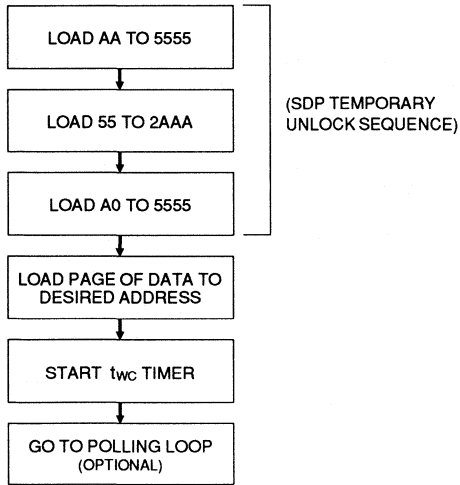


Figure 4. Polling Loop

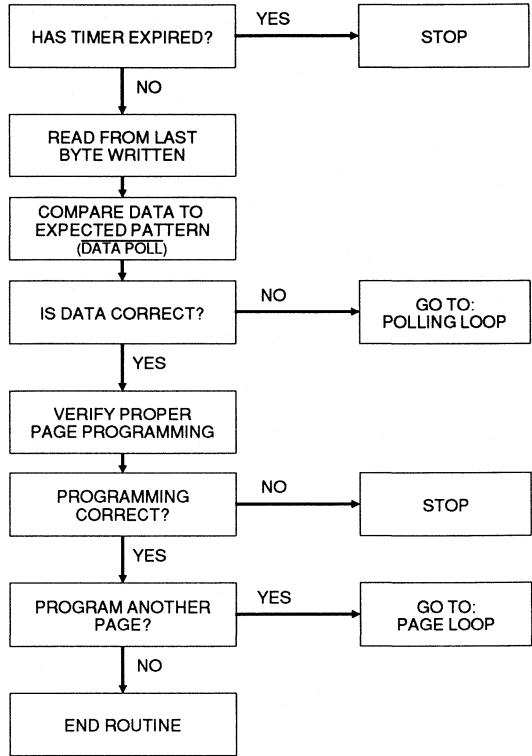
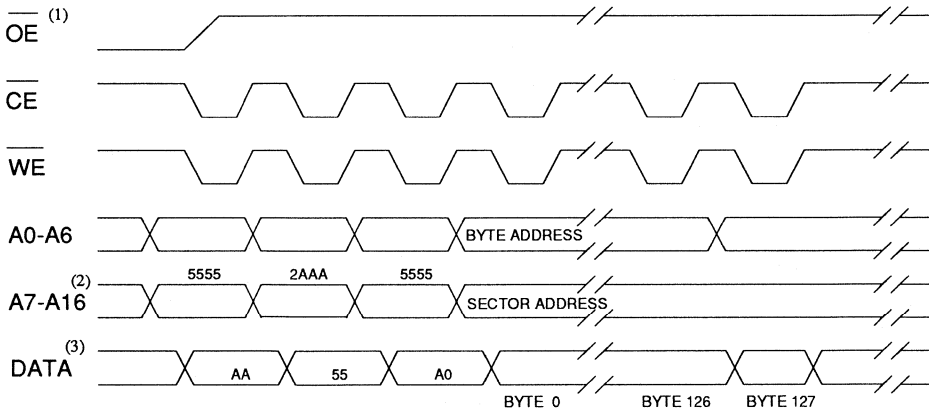


Figure 5. Timing Sequence for Protected Sector Write (AT29C010 1-Mbit Example)



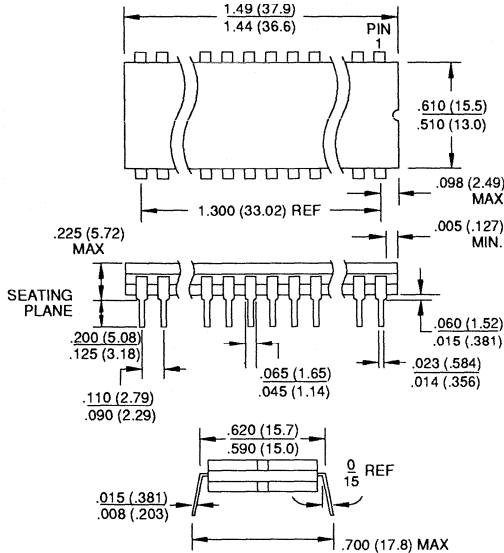
Notes:

1. OE must be high when \overline{WE} and \overline{CE} are both low.
2. A7 through A16 must specify the sector address during each high to low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.

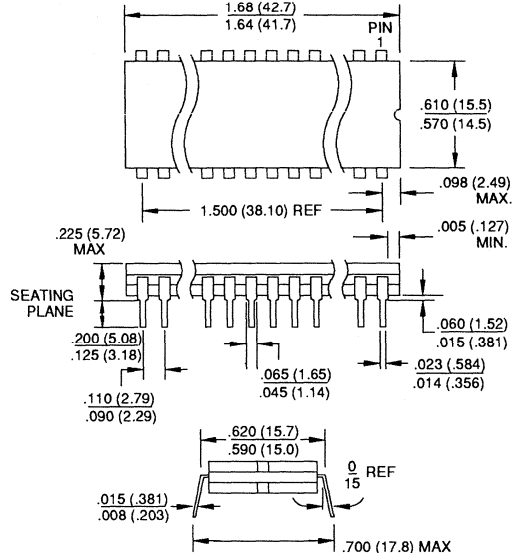
3. All bytes that are not loaded within the sector being programmed will be erased to FF.

Packaging Information

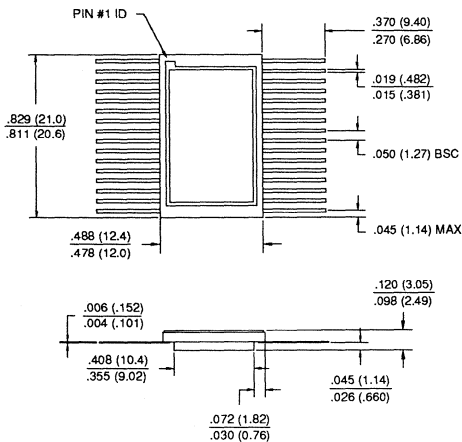
28D6, 28 Lead, 0.600" Wide, Non-Windowed,
Ceramic Dual Inline Package (Cerdip)
Dimensions in Inches and (Millimeters)
MIL-STD-1835 D-10 CONFIG 1



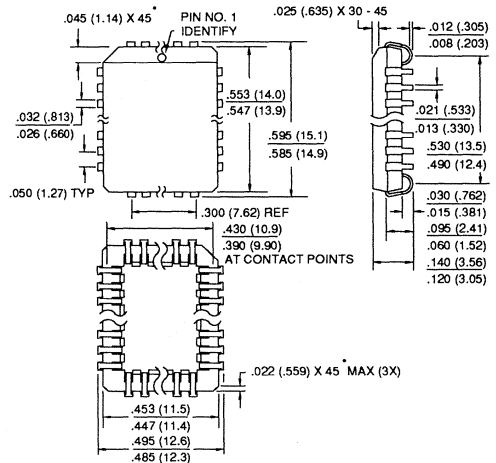
32D6, 32 Lead, 0.600" Wide, Non-Windowed,
Ceramic Dual Inline Package (Cerdip)
Dimensions in Inches and (Millimeters)
MIL-STD-1835 CONFIG A



32F, 32 Lead, Non-Windowed,
Ceramic Bottom Brazed Flat Package (Flatpack)
Dimensions in Inches and (Millimeters)
MIL-STD-1835 F-18 CONFIG B
JEDEC OUTLINE MO-115

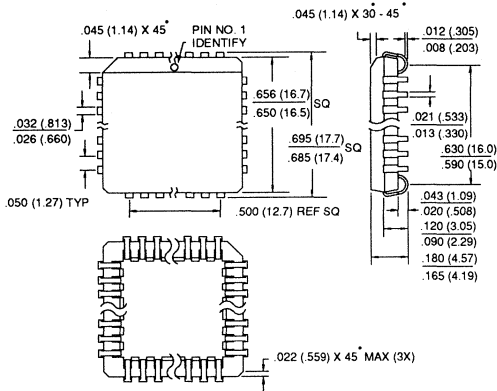


32J, 32 Lead, Plastic J-Leaded Chip Carrier (PLCC)
Dimensions in Inches and (Millimeters)
JEDEC OUTLINE MO-52 AC

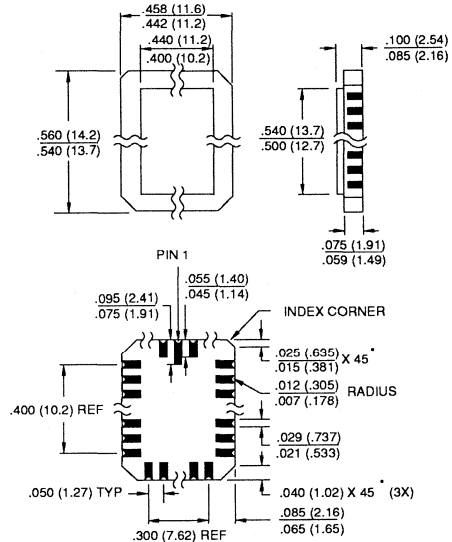


Packaging Information

44J, 44 Lead, Plastic J-Leaded Chip Carrier (PLCC)
 Dimensions in Inches and (Millimeters)
 JEDEC OUTLINE MO-47 AC

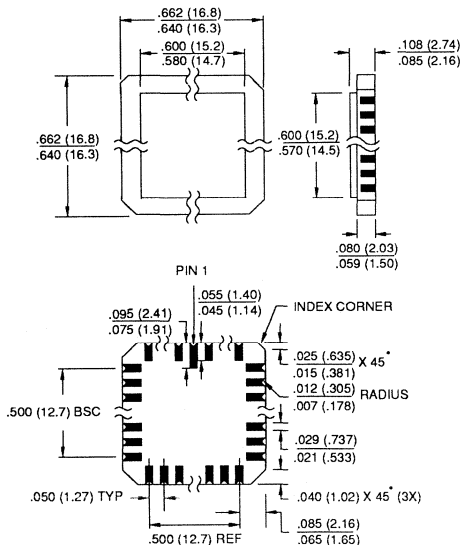


32L, 32 Pad, Non-Windowed, Ceramic Leadless Chip Carrier (LCC)
 Dimensions in Inches and (Millimeters)*



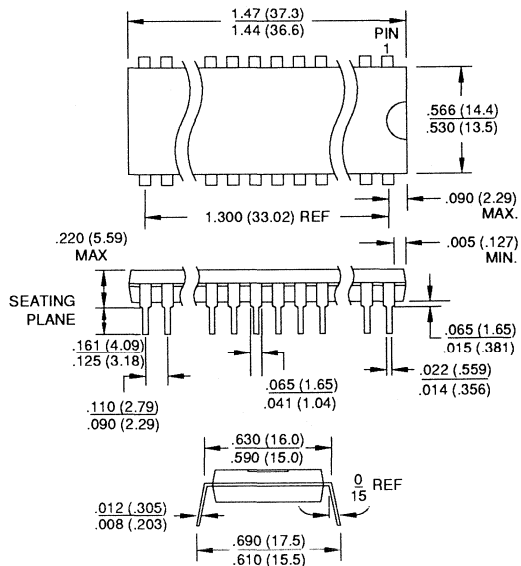
*Ceramic lid standard unless specified.

44L, 44 Pad, Non-Windowed, Ceramic Leadless Chip Carrier (LCC)
 Dimensions in Inches and (Millimeters)*



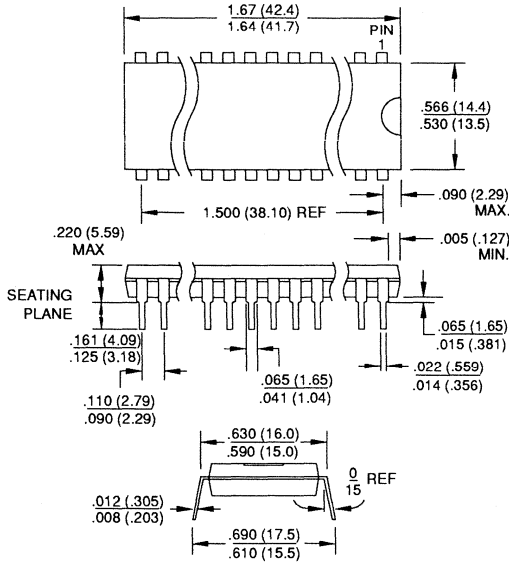
*Ceramic lid standard unless specified.

28P6, 28 Lead, 0.600" Wide, Plastic Dual In-Line Package (PDIP)
 Dimensions in Inches and (Millimeters)

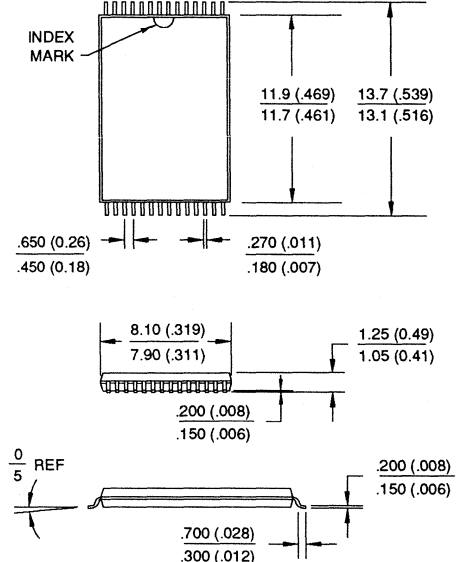


Packaging Information

**32P6, 32 Lead, 0.600" Wide,
Plastic Dual In Line Package (PDIP)
Dimensions in Inches and (Millimeters)**

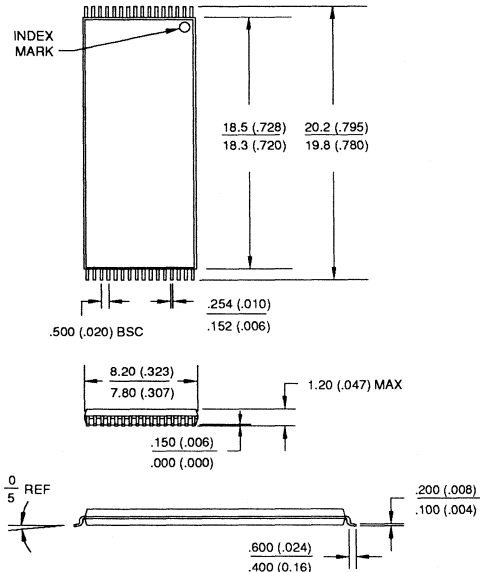


**28T, 28 Lead, Plastic Thin Small Outline Package (TSOP)
Dimensions in Millimeters and (Inches)***



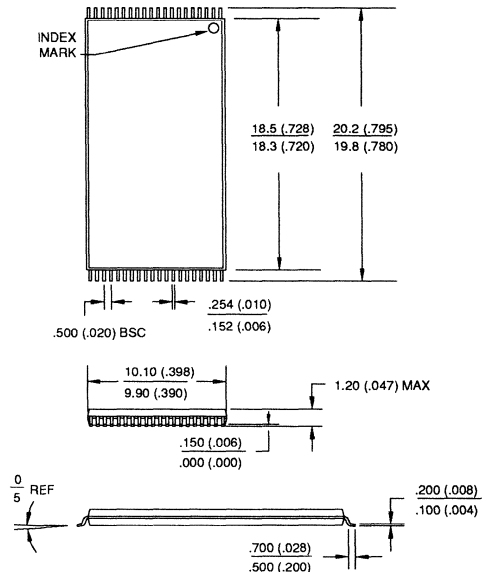
*Controlling dimension: millimeters

**32T, 32 Lead, Plastic Thin Small Outline Package (TSOP)
Dimensions in Millimeters and (Inches)***



*Controlling dimension: millimeters

**40T, 40 Lead, Plastic Thin Small Outline Package (TSOP)
Dimensions in Millimeters and (Inches)***

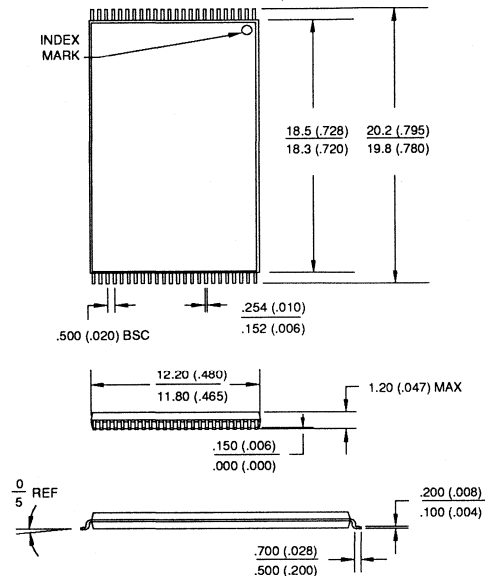


*Controlling dimension: millimeters

Packaging Information

48T, 48 Lead, Plastic Thin Small Outline Package (TSOP)

Dimensions in Millimeters and (Inches)*



*Controlling dimension: millimeters